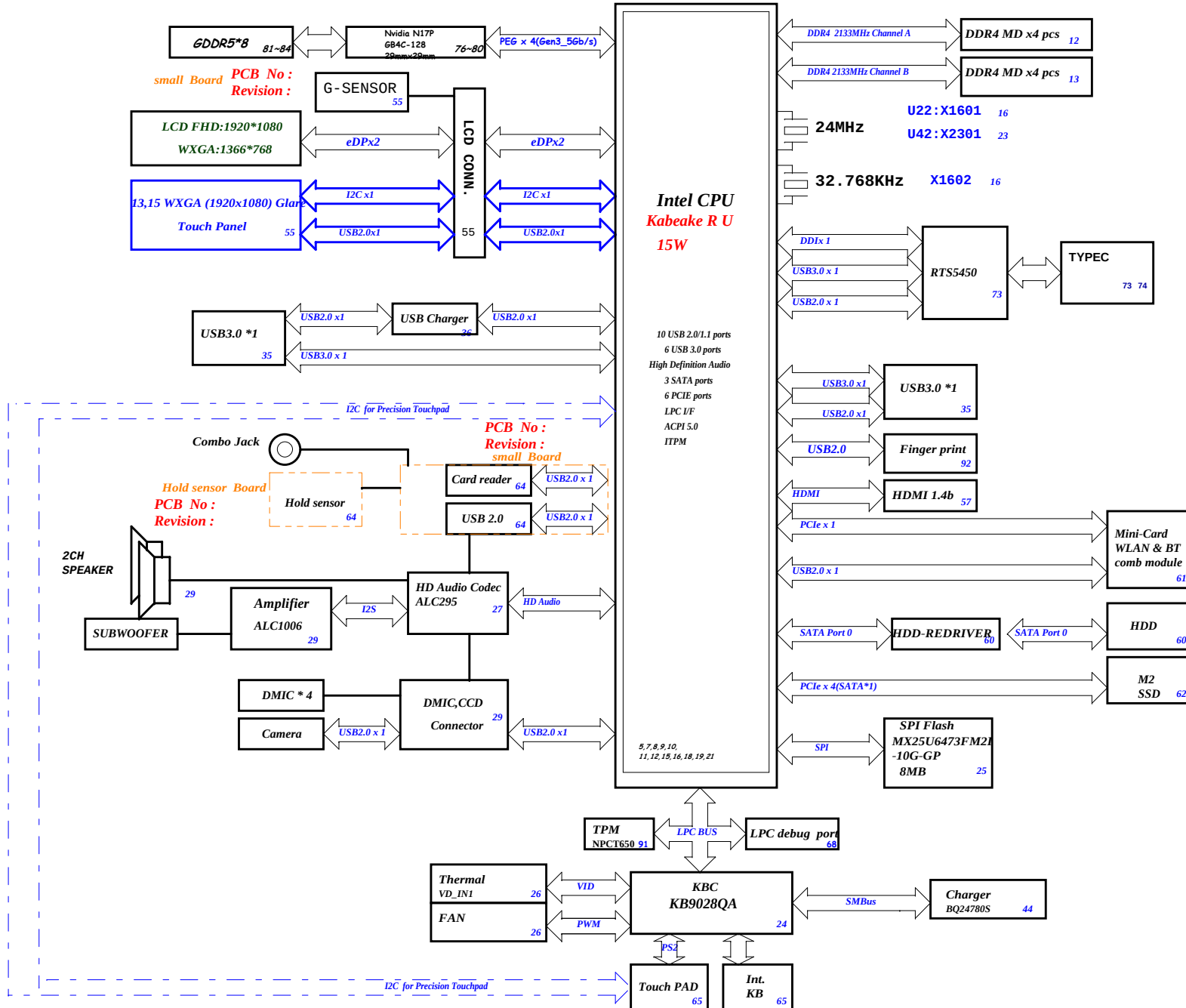


***16932 Buzz_KBL
Schematics Document***

***DY : None Installed
UMA: UMA only installed
DIS: DISCRTE OPTIMUS installed***

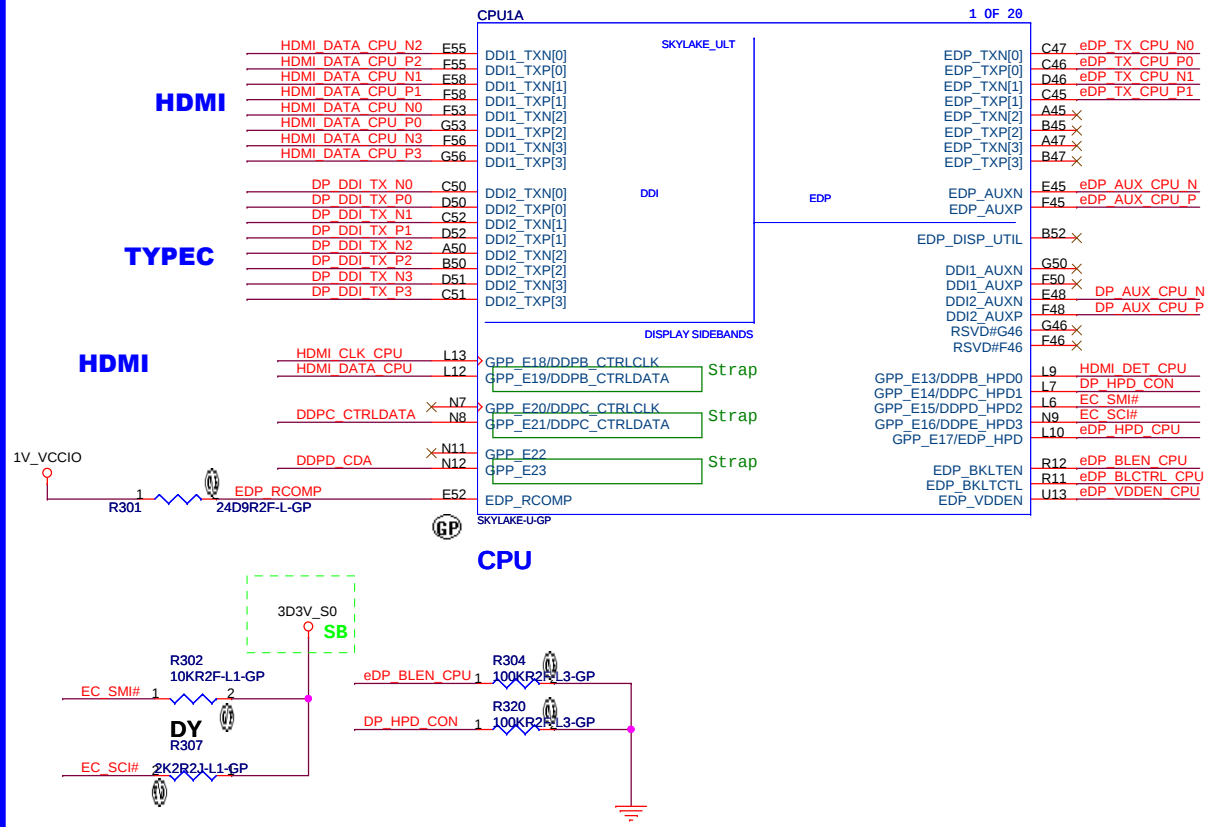
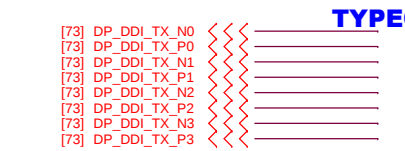
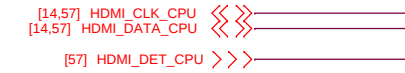
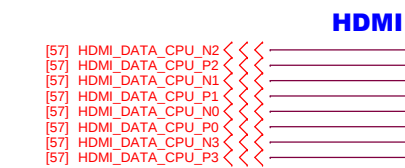
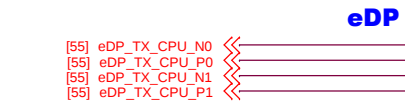
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Project Code:4PD0CR010001
PCB No : 16932
Revision : 2



GPU DC/DC				CHARGER			
RT8813DGQW-GP		85		BQ24780S		44	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
5V_S0		1V_VGACORE_S0		AD_5T*		19V_DCBATOUT	
GPU DC/DC				SYSTEM DC/DC			
RT8816AGQW-GP		85		RT6228CGQUF-GP		45	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
5V_S5		1V_VGACORE1_S0		19V_DCBATOUT		3D3V_AUX_S5 5V_S5	
GPU DC/DC				SYSTEM DC/DC			
RT8816AGQW-GP		86		RT6226BGQUF-GP		45	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
5V_S5		1D35V_VGA_S0		19V_DCBATOUT		3D3V_S5	
GPU DC/DC				CPU DC/DC			
SY8003ADFC-GP		86		RT3602		46-47	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
3D3V_S5		1D8V_AON_S0		19V_DCBATOUT		1V_CPU_CORE	
GPU DC/DC				CPU DC/DC			
APE8939GN3-GP		86		AOZ5049		48	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
1D8V_AON_S0		1D8V_VGA_S0		19V_DCBATOUT		1V_VCC6T	
GPU DC/DC				CPU DC/DC			
APE8939GN3-GP		86		RT9610B		50	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
1D0V_S5		1V_1D05V_VGA_S0		5V_S5		1V_VCCSA	
GPU DC/DC				CPU DC/DC			
RT8068A		88		G5388K11U-GP		51	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
3D3V_S5		1V_1D05V_VGA_S0		5V_S5		PWR_VDDQ	
CPU DC/DC				CPU DC/DC			
TPS22976DPUR		88		APL5930KAI		51	
INPUTS		OUTPUTS		INPUTS		OUTPUTS	
3D3V_S0		3D3V_VGA_S0 3D3V_AON_S0		5V_S5		2D5V_S3	
				SYSTEM DC/DC			
				G5388K11U-GP		52	
				INPUTS		OUTPUTS	
				5V_S5		1D0V_S5	
				SYSTEM DC/DC			
				9661-25ADJ		53	
				INPUTS		OUTPUTS	
				3D3V_S5		1D8V_S5	
				SYSTEM Load switch			
				TPS22976		40	
				INPUTS		OUTPUTS	
				3D3V_S5		1D5V_S0	
				5V_S5		5V_S0	
				1D0V_S5		1V_VCCST	
				1D8V_S5		1D8V_S0	
				SYSTEM Load switch			
				APE8939		40	
				INPUTS		OUTPUTS	
				1D0V_S5		1V_VCCIO	

Main Func = CPU



(#543016) eDP_RCOMP Guideline

Signal	Trace Width	Isolation Spacing	Resistor Value	Length
eDP_RCOMP	20 mils	25 mils	24.9 Ω ±1%	Max = 100 mils

Design Guideline:
Skylake processor signal eDP_RCOMP should be connected to the VCCIO rail via a single 24.9 ±1% Ω resistor.

DIS

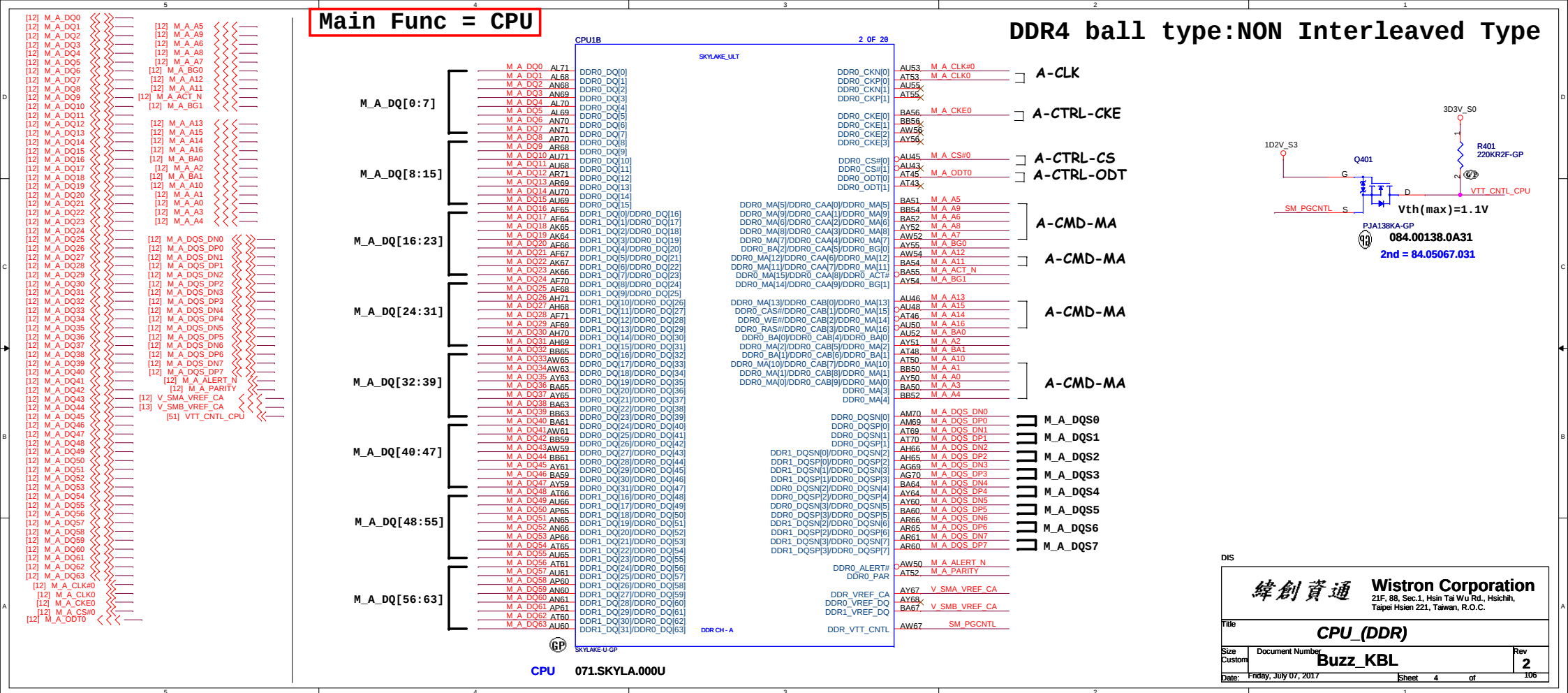
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Title **CPU_(DISPLAY)**

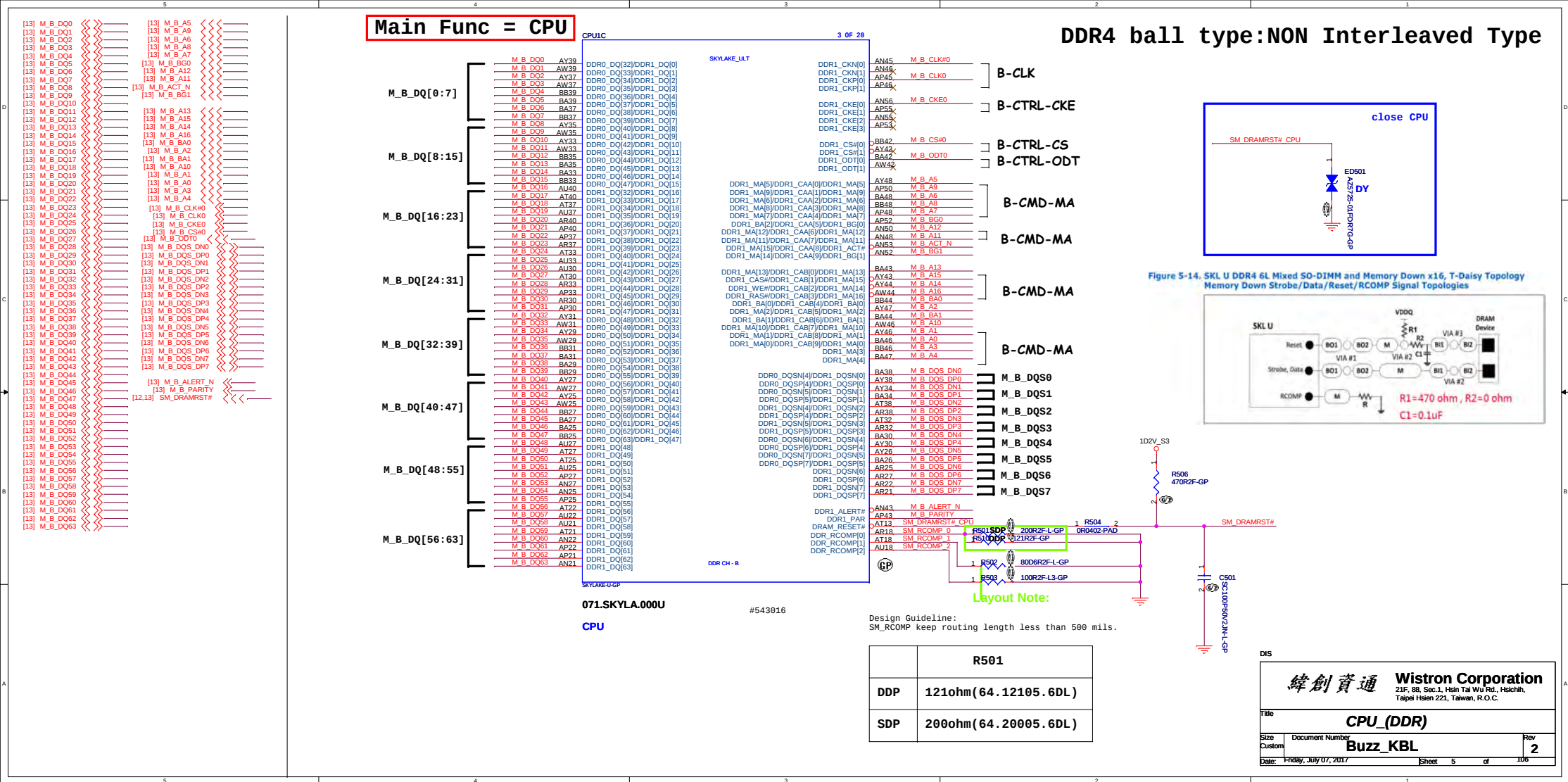
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Main Func = CPU

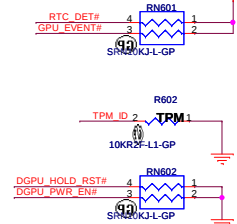
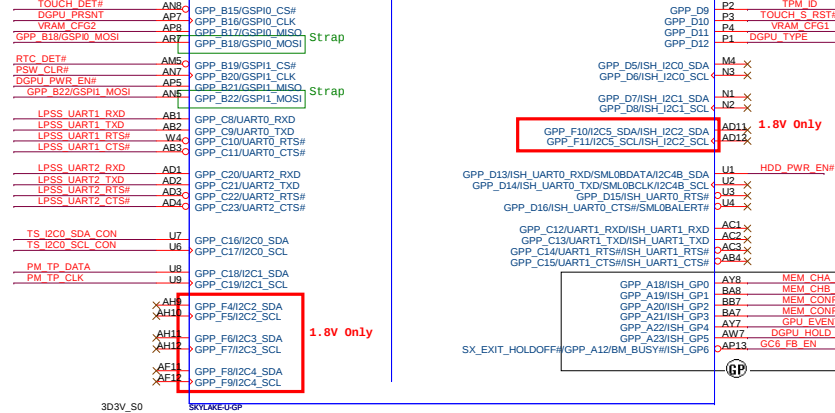
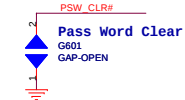
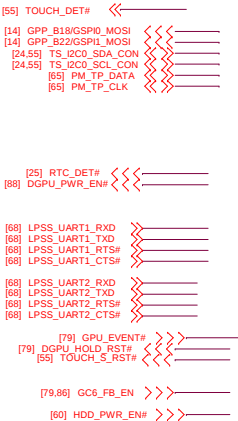
DDR4 ball type:NON Interleaved Type



DDR4 ball type:NON Interleaved Type



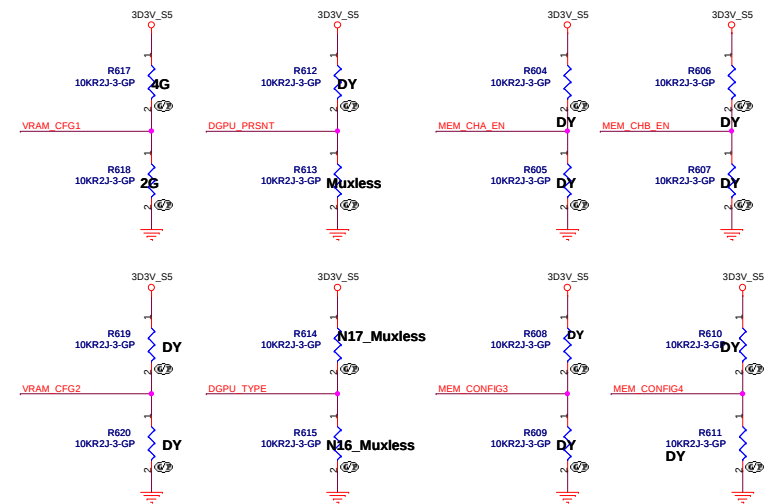
Main Func = PCH



GPIO Group Summary

GPIO Group	Power Pins	Voltage
Primary Well Group A (GPP_A)	VCCGPPA	1.8V or 3.3V
Primary Well Group B (GPP_B)	VCCGPPB	1.8V or 3.3V
Primary Well Group C (GPP_C)	VCCGPPC	1.8V or 3.3V
Primary Well Group D (GPP_D)	VCCGPPD	1.8V or 3.3V
Primary Well Group E (GPP_E)	VCCGPPE	1.8V or 3.3V
Primary Well Group F (GPP_F)	VCCGPPF	1.8V
Primary Well Group G (GPP_G)	VCCGPPG	1.8V or 3.3V
Deep Sleep Well Group (GPD)	VCCPDSW_3p3	3.3V

PCH_GPIO	Full-High	Full-Low
DGPU_PRSENT	UMA	DIS
DGPU_TYPE	N17	N16
VRAM_CFG1	4G	2G
VRAM_CFG2	NA	NA



Vendor	CONFIG4 (GPP_A19)	CONFIG3 (GPP_A18)	CONFIG2 (GPP_A21)	CONFIG1 (GPP_A20)	Mfr. PN	Wistron . P/N	Capacity
HYNIX	0	0	0	0	H5AN8G6NAFR-UHC	KN. 8GB0G. 049	8Gb
MICRON	0	0	0	1	MT40A512M16JY-083E:B	KN. 8GB04. 013	8Gb
SAMSUNG	0	0	1	0	K4A8G165WB-BCRC	KN. 8GB0B. 048	8Gb
HYNIX	0	0	1	1	H5AN4G6NAFR-TF	KN. 0040G. 015	4Gb
HYNIX	0	1	0	0	H5AN4G6NAFR-UHC	KN. 0040G. 016	4Gb
MICRON	0	1	0	1	MT40A256M16GE-083E:B	KN. 00404. 010	4Gb
SAMSUNG	0	1	1	0	K4A4G165WE-BCRC	KN. 0040B. 014	4Gb
HYNIX	0	1	1	1	H5ANAG6NAMR-UHC	KN. 0160G. 010	16Gb
MICRON	1	0	0	0	MT40A1G16WBWU-083E:B	KN. 01604. 001	16Gb

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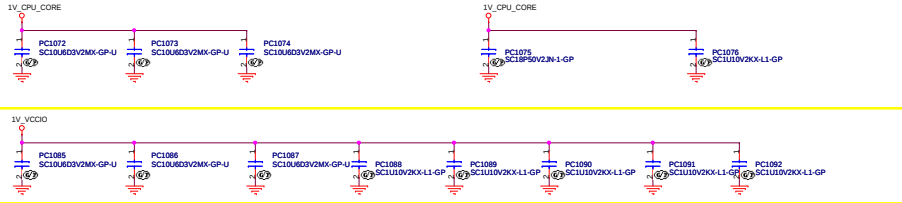
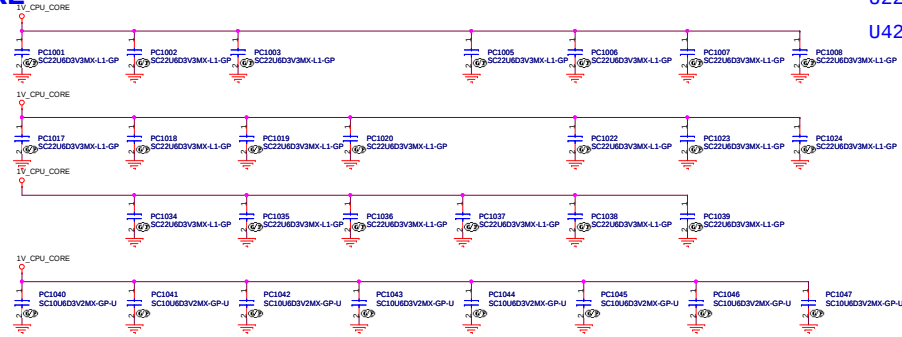
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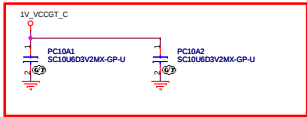
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VCORE



1V_VCCIO
10uF * 3 1uF * 4



1V_CPU_CORE

U22 0603 22uF *23 , 0402 10uF*20
U42 0603 22uF *4 , 0402 10uF*20

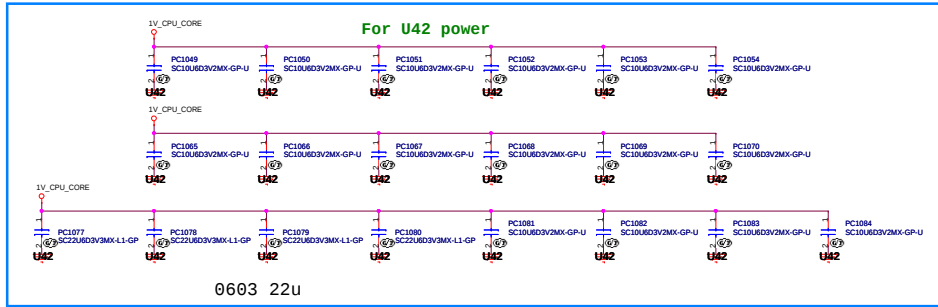
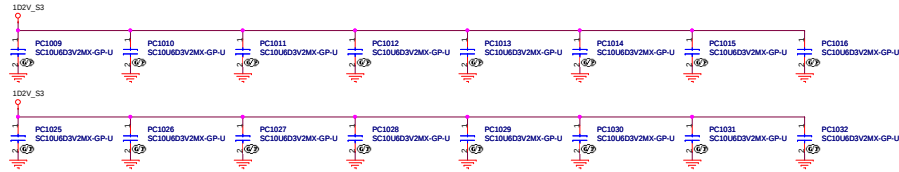


Table 48-4. Decoupling Requirements for KBL-R U 4+2 / KBL U 2+2 Processor (Sheet 2 of 3)

Domain	Backside cap	Primary side cap	Placement guideline
VCCA	7x 10 uF 0402 7x 1 uF 0402 or 0201		Place on secondary side, underneath the package
VCCD		6x 10 uF 0402	Place as close to the package as possible
VDDQ		4x 1 uF 0402	Place as close to the package as possible
VDDQ		4x 10 uF 0402	Place as close to the package as possible
VDDQ		3 x 22 uF 0603	Place as close to the package as possible
VDDQ		1 x 10 uF 0402	Preferred to place the 0402 10uF cap on the secondary under the package shadow near VDDQ pin and short to VDDQ rail under with a shape. Alternatively, if the 0402 cap cannot be placed on the backside, follow the example shown in Figure 48-3. The 0402 cap to VDDQ. BGA routing should not exceed 48mm (48in). RVP design uses Trace L=450mil, W=6mil between BGA and cap. Additional trace routing implemented in RVP design was not required.
VCCLL		1x 1 uF 0402	Place as close to the package as possible.
VCCLL_OC		1x 1 uF 0201	Do not route VCCLL, VCCLL_OC, VCCLL closest adjacent layer over any power net other than ground.
VCCGT		1x 1 uF 0402	For VCCST, Refer to Figure 48-2 for additional routing details for VCCST & VCCSTG.

Notes:
1. The 6.3V voltage is for the higher capacitance retention; more 6805 components will be required for a lower voltage capacitor rating. Assumption: VR loop bandwidth ~ 250kHz e.g., 1MHz switching VR
2. Component placement order: Package edge > 0402 caps > 0805 caps > Bulk caps > Power source
3. Due to the difference between the package designs, KBL U 2+2 design requires more on-board decoupling in order to maintain the same loading.
4. Diagram of placement for 0402 backside case for CPU decoupling.



Table 48-4. Decoupling Requirements for KBL-R U 4+2 / KBL U 2+2 Processor (Sheet 1 of 3)

Domain	Backside cap	Primary side cap	Placement guideline
Vcc	7x 10 uF 0402 31x 1 uF 0402 or 0201		Place on secondary side, underneath the package Refer to diagram in Note 4 below for placement recommendation of 0402 caps Refer to diagram in Note 5 below for placement recommendation of 0201 caps
Vcc/VccGT		9x 22 uF 0603 8x 47 uF 0805 (6.3V) ¹ 8x 10 uF 0402	Place as close to the package as possible
VccGT	5x 1 uF 0402 or 0201 12x 10 uF 0402 14x 1 uF 0402 or 0201		Place as close to the package as possible Place on secondary side, underneath the package
		7x 22 uF 0603 3x 47 uF 0805 (6.3V) ¹	Place as close to the package as possible

Power Layout



48.1.3 Kaby Lake U Compatible Design Recommendation

48.1.3.1 KBL-R U 4+2 / KBL U 2+2 Design Recommendation

Table 48-3. Bulk Decoupling Example (KBL-R U42/KBL U22)

Bulk Decoupling Locations	Example - U 4+2	Example - U 2+2	Notes
Vcc Power Plane at VR output	2x 220 uF (04.5mO ESR)	1x 220 uF (04.5mO ESR)	Placed at primary side near to VR output
VCCIO Power Plane at VR output	1x 220 uF (04.5mO ESR)		Placed at backside side near to VR output
VDDQ Power Plane at VR output	2x 220 uF (04.5mO ESR)		Placed at primary side near to VR output
VDDQ Power Plane at VR output	2x 47 uF 0805		Placed at primary side near to VR output
VCCIO Power Plane at VR output	2x 47 uF 0805		Placed at primary side near to VR output
VCCA Power Plane at VR output	2x 47 uF 0805		Placed at primary side near to VR output
VCCLL Power Plane at VDDPA VR output	1x 0.1uF 0402		Placed at primary side near to VR output

Notes:
1. These examples are based on 1MHz switching frequency VR with bandwidth of up to 250kHz.
2. Bulk decoupling is not a "requirement" but recommendation only. It is an example of VR design/VR bandwidth. Customer should work with respective vendor to validate their VR & bulk decoupling designs to ensure the electrical requirements are met.

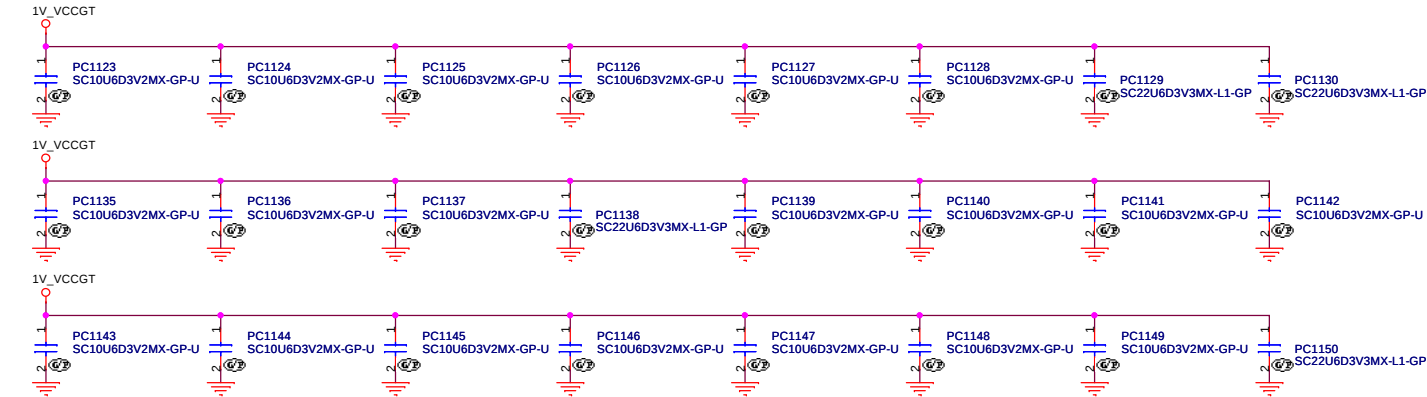
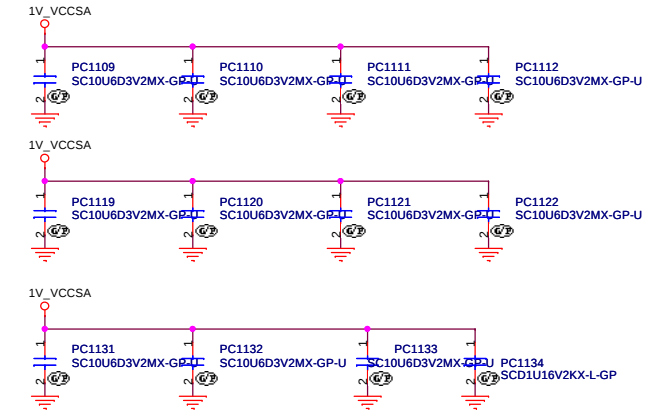
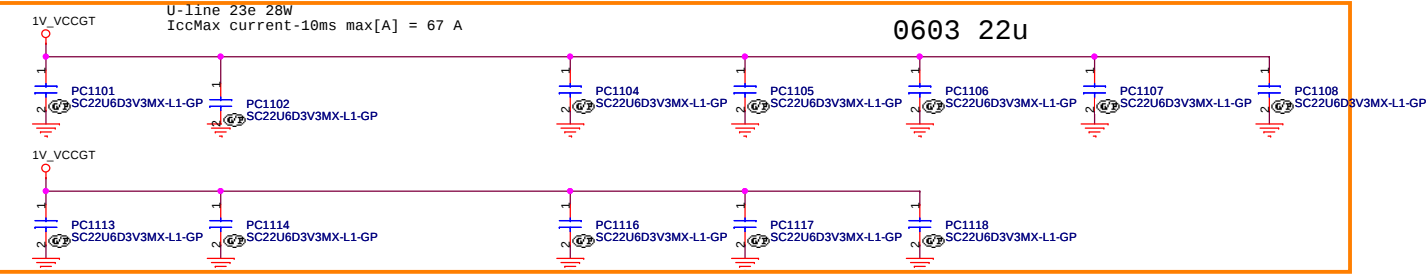
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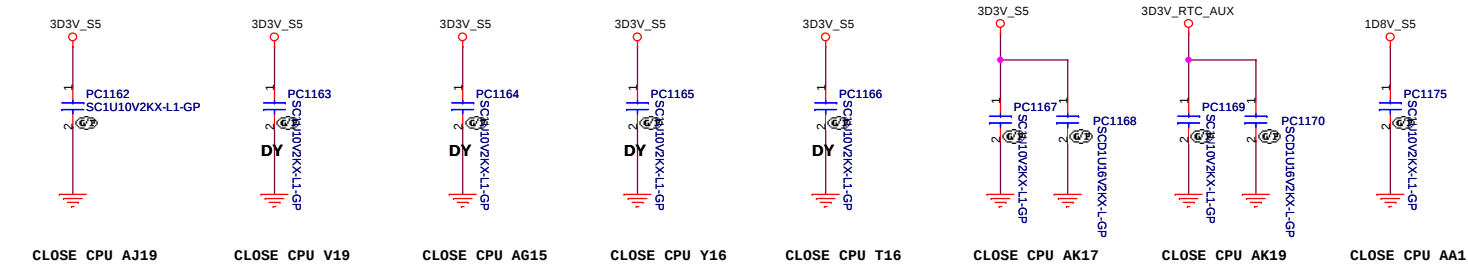
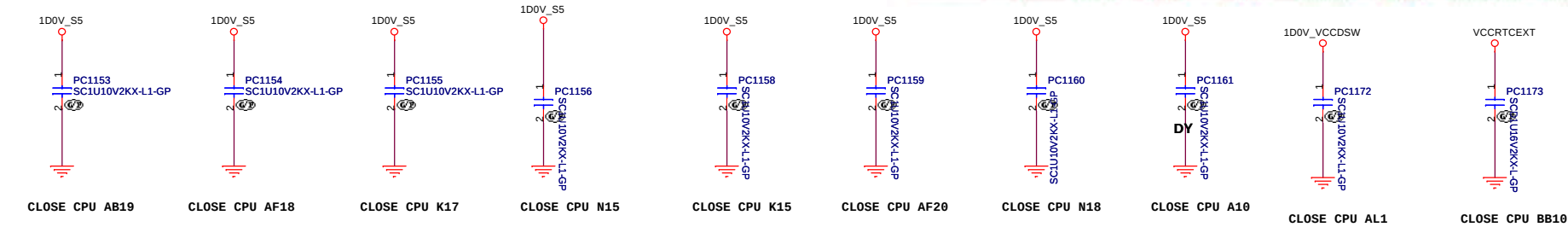
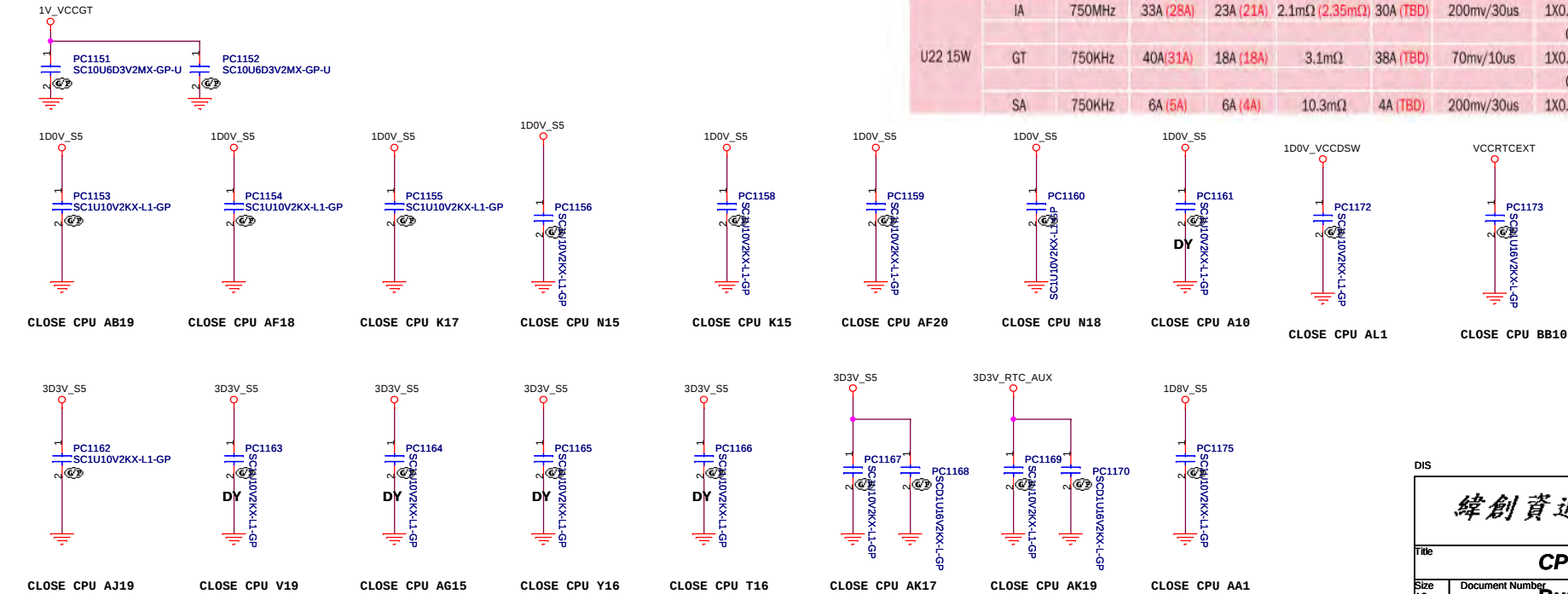
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Main Func = CPU

SLICED GT



U22 15W	IA	750MHz	33A (28A)	23A (21A)	2.1mΩ (2.35mΩ)	30A (TBD)	200mv/30us	1X0.15uH	2X330uF/9mW	30X22uF
	GT	750KHz	40A (31A)	18A (18A)	3.1mΩ	38A (TBD)	70mv/10us	1X0.15uH	2X330uF/9mW	36x22uF
								Or	1x330uF/9mW	36x22uF
	SA	750KHz	6A (5A)	6A (4A)	10.3mΩ	4A (TBD)	200mv/30us	1X0.42uH	None	5X22uF



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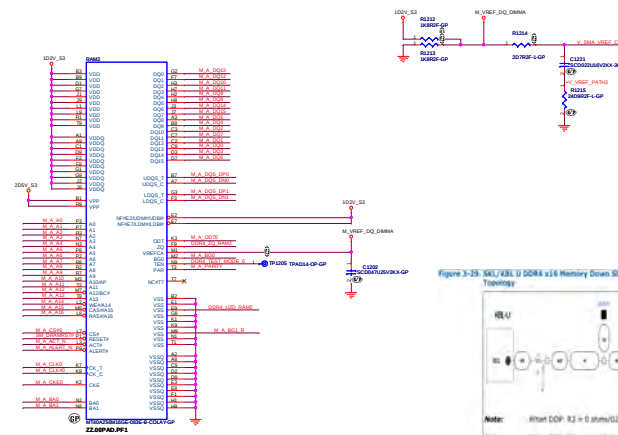
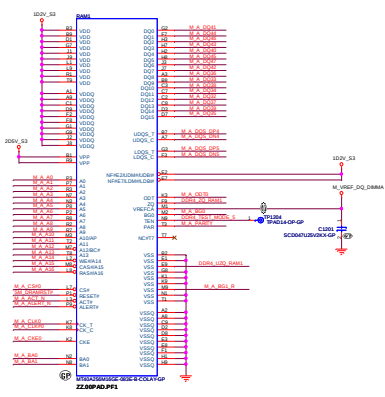
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Title CPU (Power CAP2)

Size A3 Document Number Buzz_KBL Rev 2

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DQS0	DQ0-DQ7
DQS1	DQ8-DQ15
DQS2	DQ16-DQ23
DQS3	DQ24-DQ31
DQS4	DQ32-DQ39
DQS5	DQ40-DQ47
DQS6	DQ48-DQ55
DQS7	DQ56-DQ63



The diagram shows a 1D chain of sites. The leftmost site is a square labeled 'M' with a dot inside, representing a magnetic impurity. It is connected to a chain of five circles, each containing a dot, representing spin-1/2 sites. Above the chain, four black rectangles represent a magnetic field B applied to the four spin-1/2 sites. The chain ends with an arrow pointing to the right, labeled ψ .

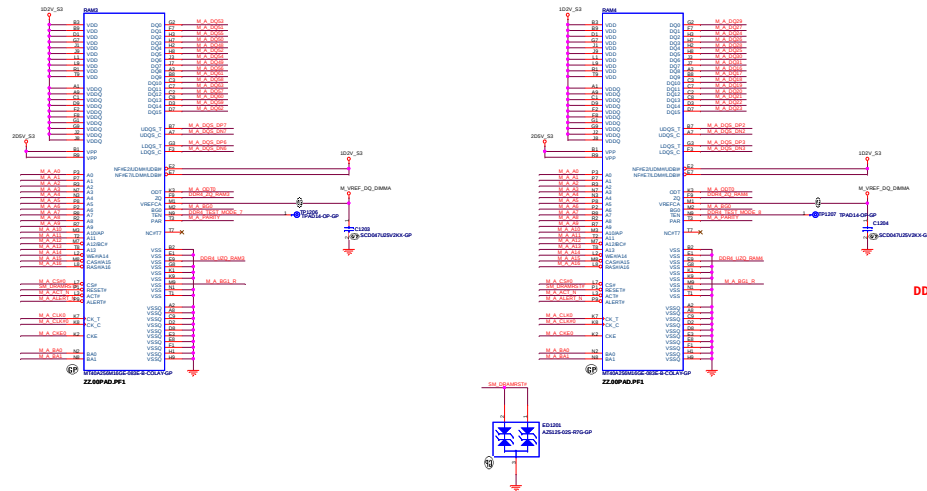
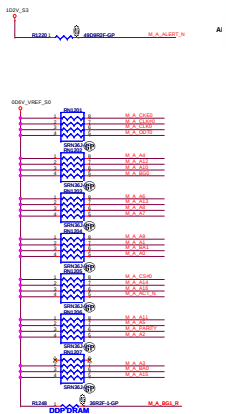


Table 4-27. DDR4 Memory Down Power Plane Decoupling (Sheet 1 of 2)

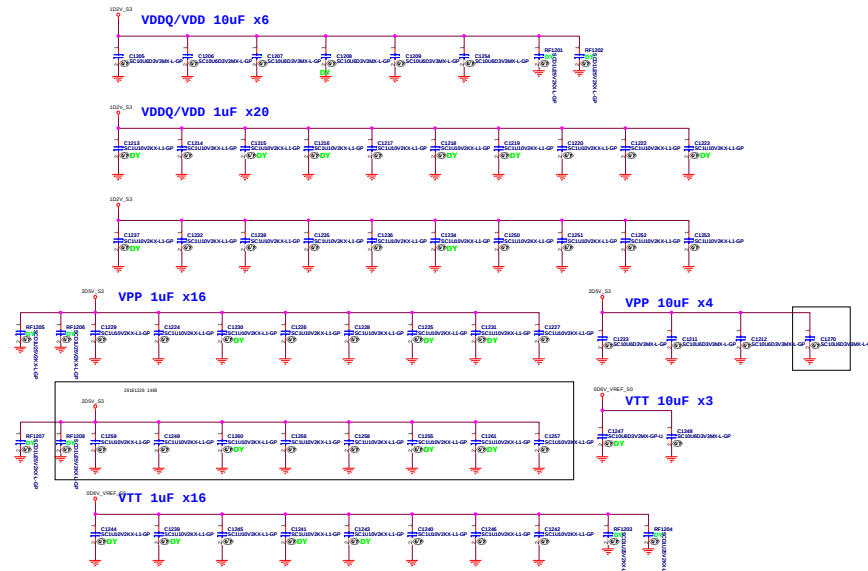
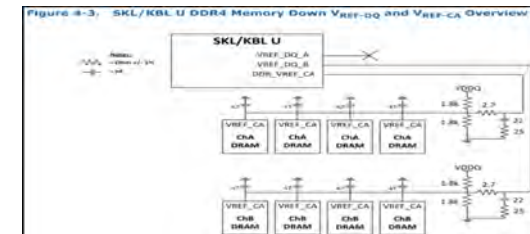
Memory Configuration	Power Source	Decoupling Location	Qty x μ F (s)
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Memory Configuration	Dominant Domain	Decoupling Location	Qty x μF (value)	Note
DDR4 Memory Domest x16 - 4 (devices per Channel)	VDDQ/VDD (shunt)	4 as near each x16 DRAM device as possible	32x 3 μF (0402) (All stuffed)	
		Distributed around the DRAM devices	10x 1 μF (0603) (All stuffed)	
	VPP	2 as near each x16 DRAM device as possible	16x 1 μF (0402)	
		Distributed around the DRAM devices	5x 1 μF (0603)	
	VTT	2 as near each x16 DRAM device as possible	16x 1 μF (0402)	
		Distributed around the DRAM devices	4x 1 μF (0603)	



- Alternate two layout, risk of VSS offset increases a little

100 *Journal of Management Inquiry*



[illegible]

The schematic diagram illustrates the power supply architecture of the STM32F405VCT6. It features several voltage regulators and their associated pins:

- 1.2V Regulator:** Connected to the 100V_S1 pin. It includes a 100nF capacitor (C100) and a 100V_S1 pin.
- 1.8V Regulator:** Connected to the 250V_S1 pin. It includes a 100nF capacitor (C100) and a 250V_S1 pin.
- 3.3V Regulator:** Connected to the 3.3V pin. It includes a 100nF capacitor (C100) and a 3.3V pin.
- 5V Regulator:** Connected to the 5V pin. It includes a 100nF capacitor (C100) and a 5V pin.
- Internal Components:** The diagram shows various internal components, including the 1.2V regulator, 1.8V regulator, 3.3V regulator, 5V regulator, and the 100V_S1 and 250V_S1 pins.

The diagram also includes labels for various pins and internal components, such as the 1.2V regulator, 1.8V regulator, 3.3V regulator, 5V regulator, and the 100V_S1 and 250V_S1 pins.

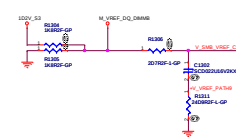
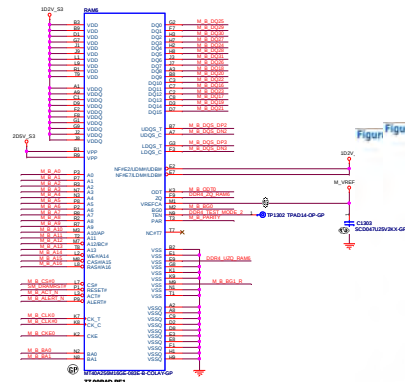
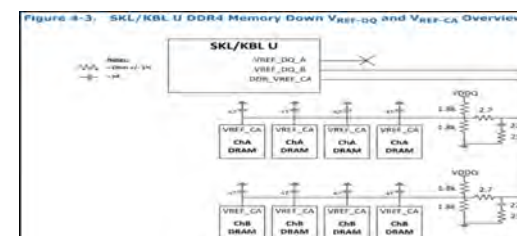
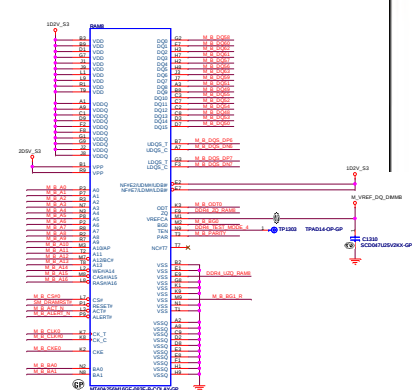
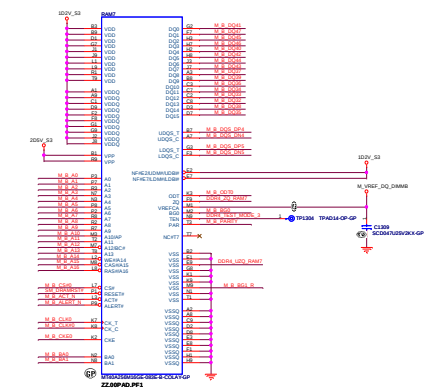
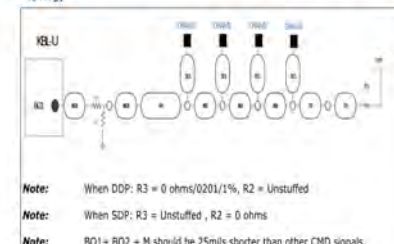
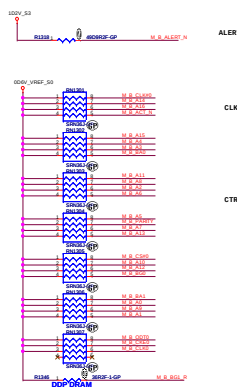
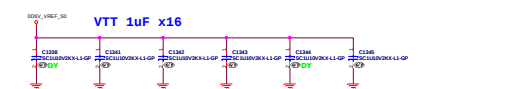
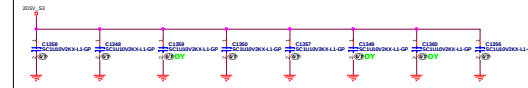
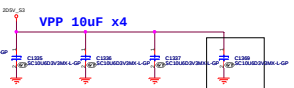
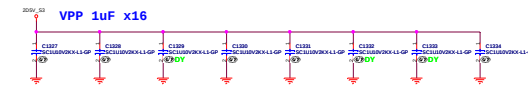
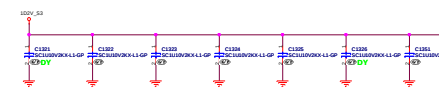
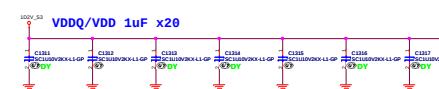


Figure 10 illustrates three circuit layouts for DDP (Dual Data Path) and SDP (Single Data Path) configurations. The top diagram shows a DDP layout with a 100k resistor, a 100pF capacitor, and a 100k resistor connected to a 100k resistor, with a 100k resistor connected to a 100k resistor. The middle diagram shows an SDP layout with a 100k resistor, a 100pF capacitor, and a 100k resistor connected to a 100k resistor, with a 100k resistor connected to a 100k resistor. The bottom diagram shows a DDP layout with a 100k resistor, a 100pF capacitor, and a 100k resistor connected to a 100k resistor, with a 100k resistor connected to a 100k resistor.



VDDQ/VDD 10uF x6



SSID = STRAP

Description	Display Port B Detected	Display Port C Detected	Reserved	No reboot	Boot BIOS strap bit BBS	Flash descriptor security override	Display Port D Detected
GPIO	GPP_E19	GPP_E21	SPI0_MISO	GPP_B18	GPP_B22	HDA_SDO	GPP_E23
Schematic							
High	Detected	Detected	Detected	Enable	LPC	Disable	Detected
Low	Not Detected	Not Detected	Not Detected	Disable	SPI	Enable	Not Detected
	internal pull-down	internal pull-down	internal pull-up	internal pull-down	internal pull-down	internal pull-down	internal pull-down

Description	Top Swap Override	Reserved	Reserved	Reserved	TLS Confidentiality	eSPI or LPC	Reserved
GPIO	GPP_B14	SPI0_MOSI	SPI0_IO2	SPI0_IO3	GPP_C2	GPP_C5	GPP_B23
Schematic							
High	Enable				Enable	eSPI	
Low	Disable				Disable	LPC	
	internal pull-down	internal pull-up	internal pull-up	internal pull-up	internal pull-down	internal pull-down	internal pull-down

STRAP RESISTORS SHOULD BE PLACED CLOSE TO SOC
SHOULD BE PLACED OUTSIDE KOZ AREA

Name	Internal Pull-up/ Pull Down (Note 1)	De-Bunch (Note 2)	Input	Output	Multiplexed With	Default	RM or SMI Capable	Note
GPP_B22	20K PD (see note)	No	No	No	SPI0_MOSI	GPD	None	• Also used as a strap. • The pull-down resistor is disabled after PLTRST# de-asserts.
GPP_B23	20K PD (see note)	Yes	No	No	SMI_ALERT# / PCIMPT#	GPD	RM SMI	• Also used as a strap. • The pull-down resistor is disabled after PLTRST# de-asserts.

Signal Name	Power Plane	During Reset	Immediately after Reset	S3/S4/S5	Drop 5K
HD Audio Interface					
HDA_GST#	Primary	Driven Low (See Note 1)	Driven Low	Driven Low	OFF
HDA_STREQ	Primary	Internal Pull- down	Driven Low	Internal Pull- down	OFF
HDA_BLK	Primary	Driven Low	Driven Low	Driven Low	OFF
HDA_SDO	Primary	Internal Pull- down	Driven Low	Driven Low	OFF
HDA_SDI[1:0]	Primary	Internal Pull- down	Internal Pull- down		OFF

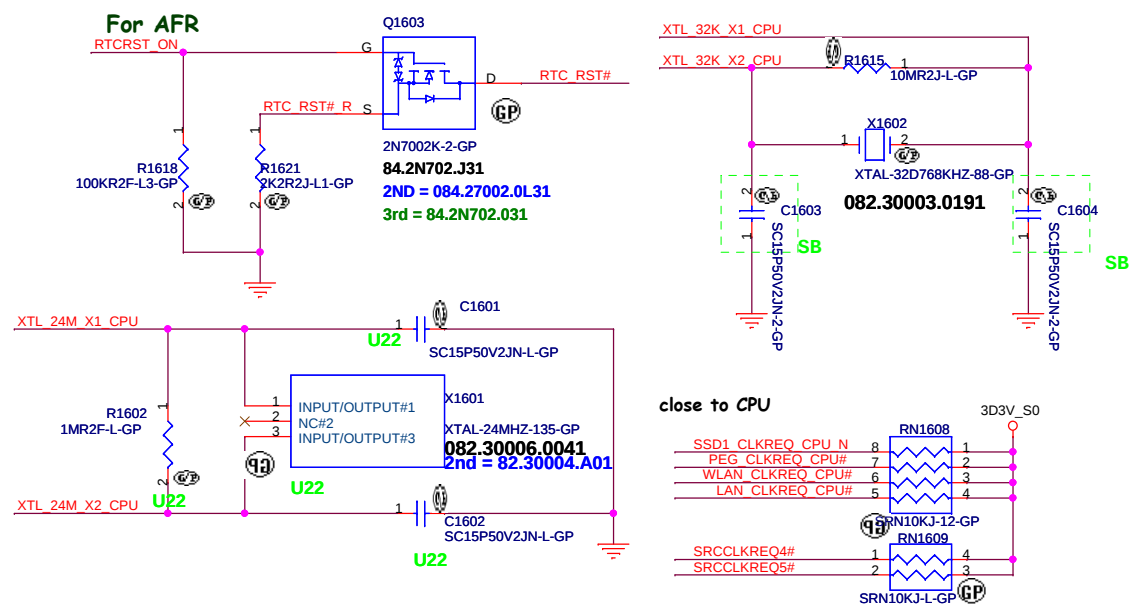
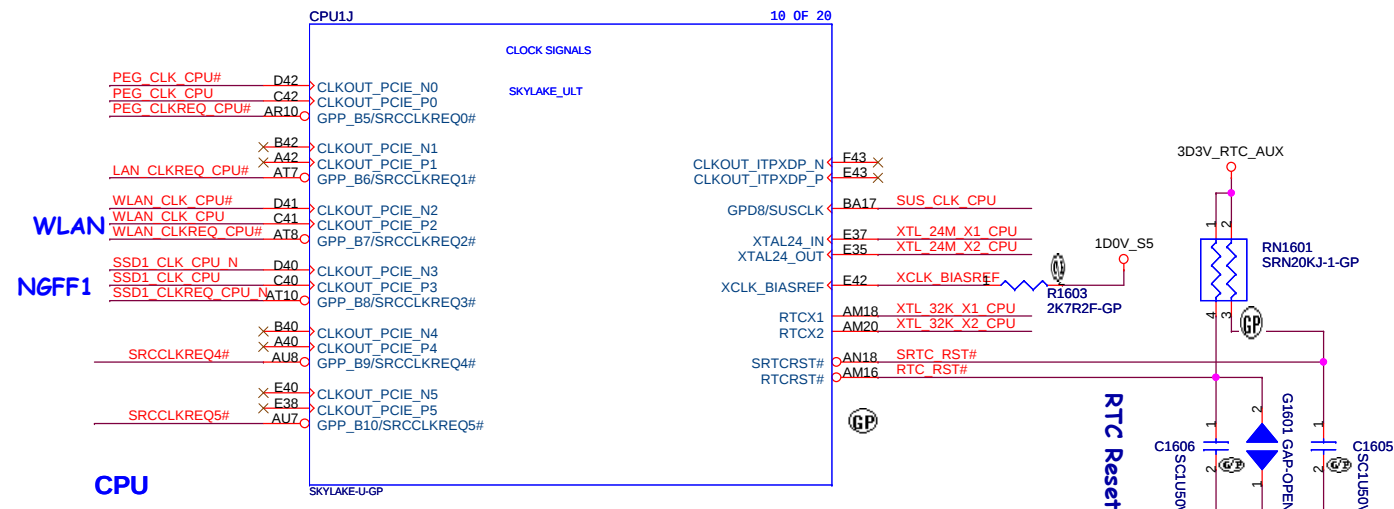
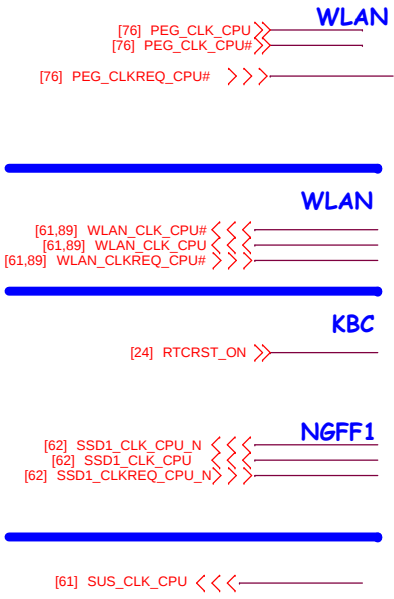
I/O Signal Planes and States

Signal Name	Power Plane	During Reset	Immediately after Reset	S3/S4/S5	Drop 5K
SPI0_CLK	Primary	Driven Low (See Note 1)	Driven Low	Driven Low	OFF
SPI0_MOSI	Primary	Internal Pull-up/ Pull-down (See Note 1 & 2)	Driven Low	Driven Low	OFF
SPI0_MISO	Primary	Internal Pull-up	Internal Pull-up	Internal Pull-up	OFF
SPI0_CS0#	Primary	Driven High (See Note 1)	Driven High	Driven High	OFF
SPI0_CS1#	Primary	Internal Pull-up (See Note 1)	Driven High	Driven High	OFF
SPI0_CS2#	Primary	Driven High (See Note 1)	Driven High	Driven High	OFF
SPI0_IO[2:1]	Primary	Internal Pull-up (See Note 1)	Internal Pull-up	Internal Pull-up	OFF
SPI1_CLK	Primary	Undriven	Undriven	Undriven	OFF
SPI1_MOSI	Primary	Undriven	Undriven	Undriven	OFF
SPI1_MISO	Primary	Undriven	Undriven	Undriven	OFF
SPI1_CS#	Primary	Undriven	Undriven	Undriven	OFF
SPI1_IO[2:1]	Primary	Undriven	Undriven	Undriven	OFF

Notes:
1. Pins are tri-stated (with weak internal pull-up) prior to RSMRST# de-assertion.
2. Weak internal pull-up resistor is enabled when RSMRST# is asserted and is switched to a weak internal pull-down when RSMRST# is de-asserted.

DDPB_CTRLDATA / GPP_E19	Display Port B Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port B is not detected. 1 = Port B is detected. Notes: 1. This internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
DDPC_CTRLDATA / GPP_E21	Display Port C Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port C is not detected. 1 = Port C is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
GSPT0_MOST / GPP_B18	No Reboot	Rising edge of PCH_PWROK	The signal has a weak internal pull-down. 0 = Disable "No Reboot" mode. 1 = Enable "No Reboot" mode (PCH will disable the TCO Timer system reboot feature). This function is useful when running ITP/XDP. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. The status of this strap is readable using the NO REBOOT bit (Chipset Configuration Registers: RCBA + Offset 3410h:Bit 5). 3. This signal is in the primary well.
GSPI1_MOSI / GPP_B22	Boot BIOS Strap Bit BBS	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. This field determines the destination of accesses to the BIOS memory (readable). Also, a weak internal pull-down is present on this signal. Accesses to the BIOS memory are restricted by the BIOS Destination bit (Chipset Configuration Registers: Offset 3410h:Bit 4). This strap is used in conjunction with Boot BIOS Destination Selection 0 strap. 0 = SPI 1 = LPC Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. The status of this strap is readable using the NO REBOOT bit (Chipset Configuration Registers: RCBA + Offset 3410h:Bit 5). 3. This signal is in the primary well.
signal	Usage	When Sampled	Comment
DDPB_CTRLDATA / GPP_E19	Display Port B Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port D is not detected. 1 = Port D is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
SPKR / GPP_B14	Top Swap Override	Rising edge of PCH_PWROK	The signal has a weak internal pull-down. 0 = Disable "Top Swap" mode. (Default) 1 = Enable "Top Swap" mode. This inverts an address on access to SPI and firmware hub, so the processor believes it fetches the alternate boot block instead of the original boot block. PCH will invert A16 (default) for cycles going to the upper two cache blocks, in the VPH or the appropriate address lines (A16, A17, or A18) as selected in Top Swap Block Size soft strap (handled through FITC). Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. Software will not be able to clear the Top Swap bit until the system is rebooted. 3. The status of this strap is readable using the Top Swap bit (Device33, Function0, Offset 0ch:Bit 4). 4. This signal is in the primary well.
SMI_ALERT# / GPP_C2	TLS Confidentiality	Rising edge of RSMRST#	This signal has a weak internal pull-down. 0 = Disable Intel ME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality). 1 = Enable Intel ME Crypto Transport Layer Security (TLS) cipher suite (with confidentiality). Must be pulled up to support Intel AMT with TLS and Intel SBA (Small Business Advantage) with TLS. Notes: 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well.
SMI_ALERT# / GPP_C3	eSPI or LPC	Rising edge of RSMRST#	This signal has a weak internal pull-down. 0 = LPC is selected for EC. 1 = eSPI is selected for EC. Notes: 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well.

Main Func = PCH



DIS

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Title MCP_CLOCK

Size Custom Document Number Buzz_KBL Rev 2

Date: Friday, July 07, 2017 Sheet 16 of 106

Main Func = PCH

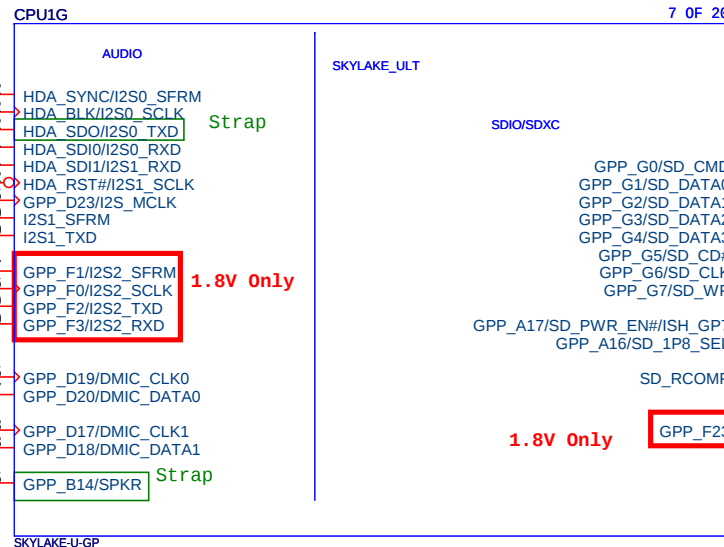
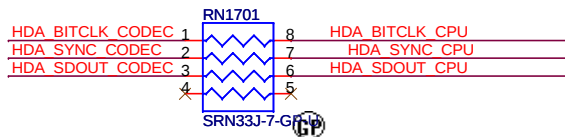
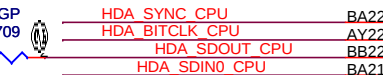
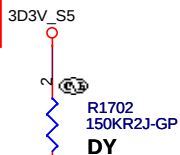
Audio Code

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[17,27] HDA_BITCLK_CODEEC <<<<—
[27] HDA_SDOUT_CODEEC <<<<—
[27] HDA_SDIN0_CPU <<<<—
[14,27] HDA_SPKR <<<<—

[24] ME_UNLOCK <<<<—

[17,27] HDA_SYNC_CODEEC <<<<—
[17,27] HDA_BITCLK_CODEEC <<<<—

[29] DMIC2_DATA_CPU <<<<—
[29] DMIC2_CLK_CPU <<<<—
[29] DMIC1_DATA_CPU <<<<—
[29] DMIC1_CLK_CPU <<<<—



AB11
AB13
AB12
W12
W11
W10
W8
W7

BA9
BB9

AB7

AF13

GP

18.3 Terminating Unused SDXC Signals

SDXC signals are multiplexed with GPIOs and default to GPIO functionality (as input). If SDXC interface is not used, the signals can be used as GPIOs instead. If the GPIO functionality is also not used, the signals can be left as no-connect.

Additionally, if SDXC interface is not used, the SD_RCOMP pin does not need to be connected to a RCOMP resistor.

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Size Custom Document Number **Buzz_KBL**

Rev **2**

Date: Friday, July 07, 2017 Sheet 17 of 106

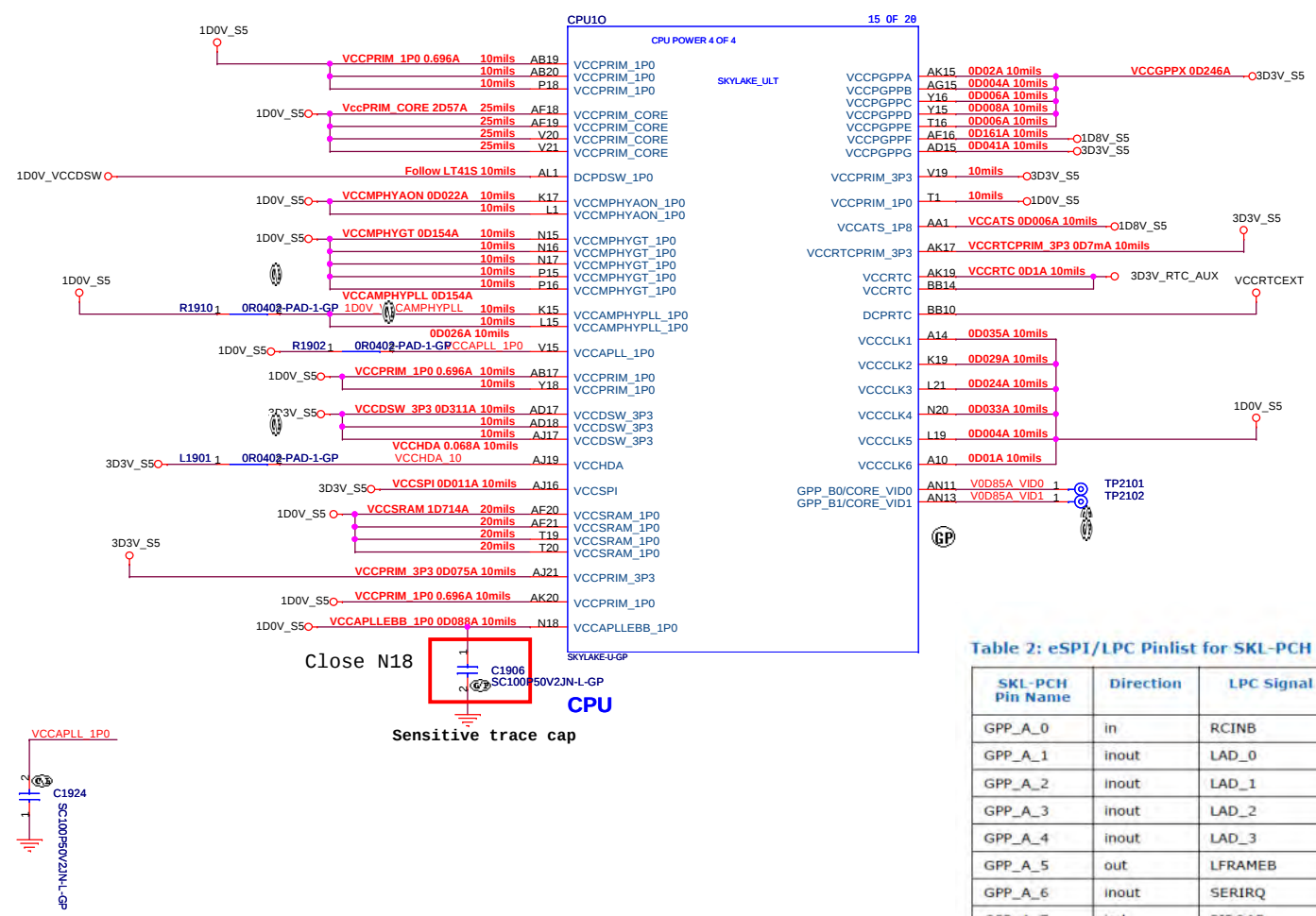


Table 2: eSPI/LPC Pinlist for SKL-PCH

SKL-PCH Pin Name	Direction	LPC Signal	eSPI Signal	Pin Description
GPP_A_0	in	RCINB	<GPIO>	
GPP_A_1	inout	LAD_0	ESPI_IO_[0]	LPC Cmd/Addr/Data or eSPI Data [0]
GPP_A_2	inout	LAD_1	ESPI_IO_[1]	LPC Cmd/Addr/Data or eSPI Data [1]
GPP_A_3	inout	LAD_2	ESPI_IO_[2]	LPC Cmd/Addr/Data or eSPI Data [2]
GPP_A_4	inout	LAD_3	ESPI_IO_[3]	LPC Cmd/Addr/Data or eSPI Data [3]
GPP_A_5	out	LFRAMEB	ESPI_CSB	LPC Frame or eSPI Chip Select
GPP_A_6	inout	SERIRQ	<GPIO>	
GPP_A_7	iod	PIRQAB	<GPIO>	
GPP_A_9	out	LPC_CLKOUT_0	ESPI_CLK	
GPP_A_14	out	SUS_STATB	ESPI_RESETB	
GPP_C_5_SM LOALERTB	input	ESPI_EN Pin Strap		eSPI Enable Pin Strap; sampled at RMSRST# deassertion 0: LPC; 1: eSPI
VCCPGPPA	-	3.3V	1.8V	Voltage for all GPIOs in GPP_A group

NOTE: All pin mappings are subject to change. Refer to the SKL-PCH EDS for final pin list.

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Title

CPU_POWER3

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Document Number

Buzz_KBL

Date

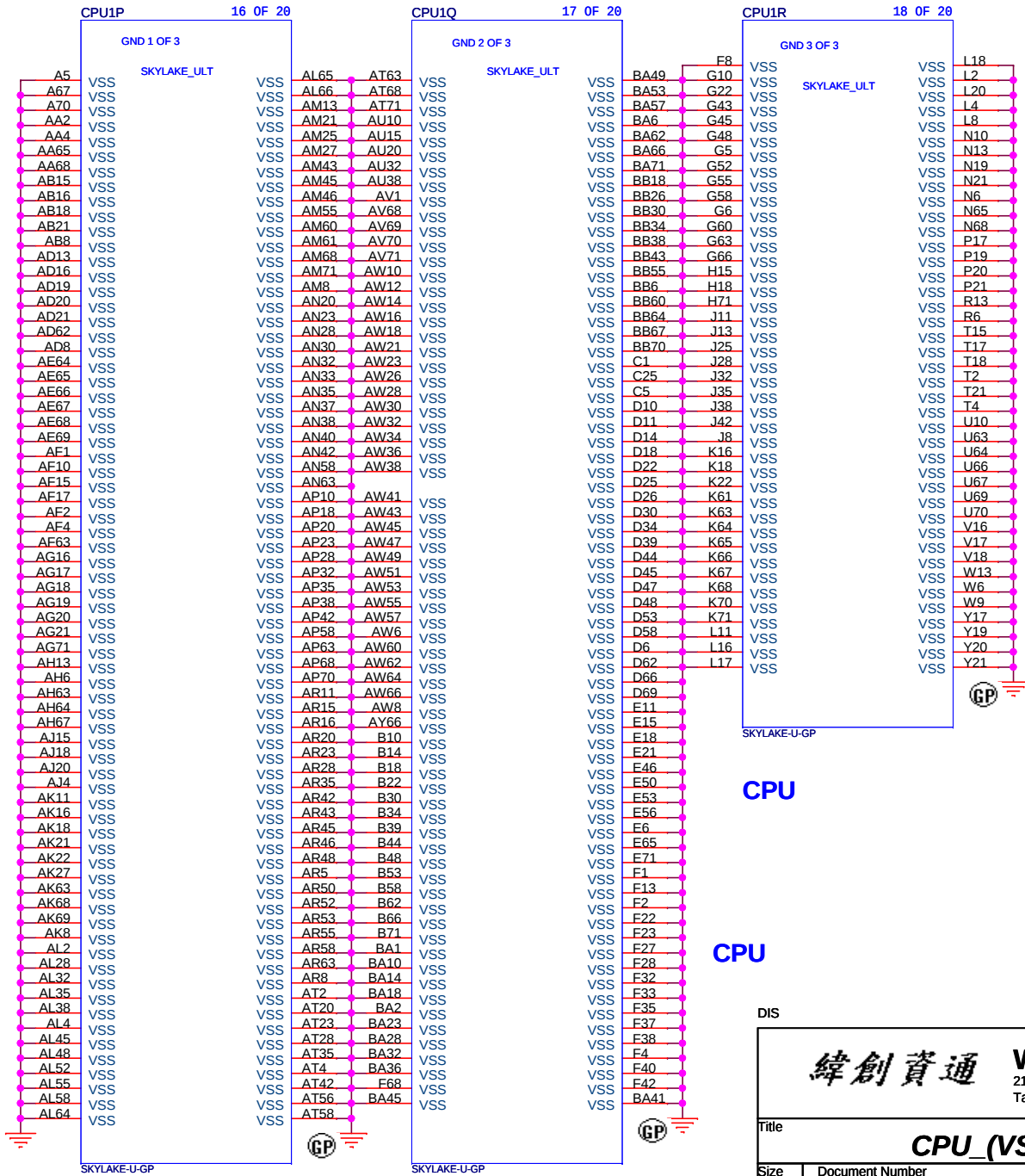
Friday, July 07, 2017

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Rev

2

Main Func = PCH



CPU

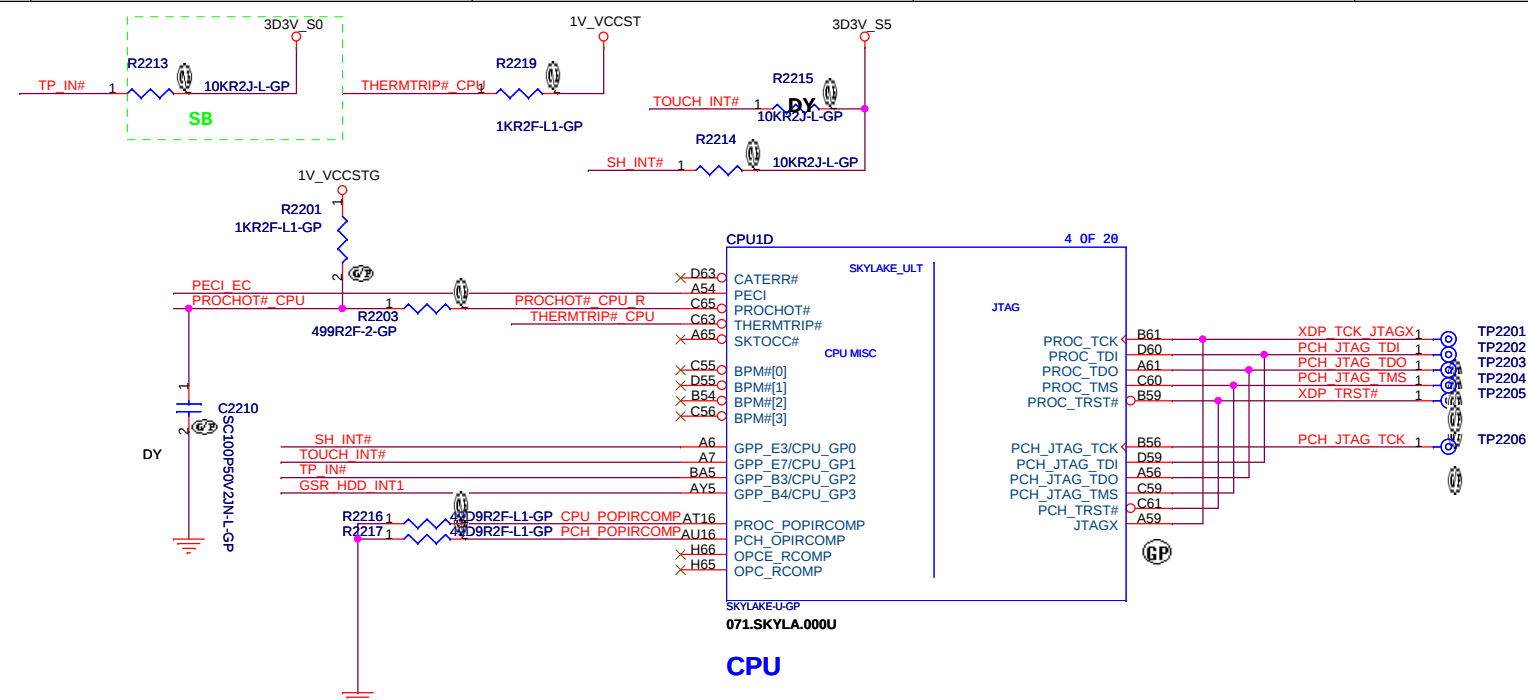
CPU

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Title					
CPU_(VSS)					
Size	Document Number				Rev
Custom	Buzz_KBL				2
Date:	Friday, July 07, 2017		Sheet	21	of 106

Main Func = CPU

- [24] PECI_EC <<>>—
- [24,44,46] PROCHOT#_CPU <<>>—
- [24] SH_INT# >>>—
- [55] TOUCH_INT# >>>—
- [65] TP_IN# >>>—
- [69] GSR_HDD_INT1 >>>—



PROCHOT#	Processor Hot: PROCHOT# goes active when the processor temperature monitoring sensor(s) detects that the processor has reached its maximum safe operating temperature. This indicates that the processor Thermal Control Circuit (TCC) has been activated, if enabled. This signal can also be driven to the processor to activate the TCC.	I/O	GTL I OD 0	SE	All processor lines
THERMTRIP#	Thermal Trip: The processor protects itself from catastrophic overheating by use of an internal thermal sensor. This sensor is set well above the normal operating temperature to ensure that there are no false trips. The processor will stop all executions when the junction temperature exceeds approximately 130 °C. This is signaled to the system by the THERMTRIP# pin. Refer to the appropriate platform design guide for termination requirements.	0	OD	SE	All processor lines

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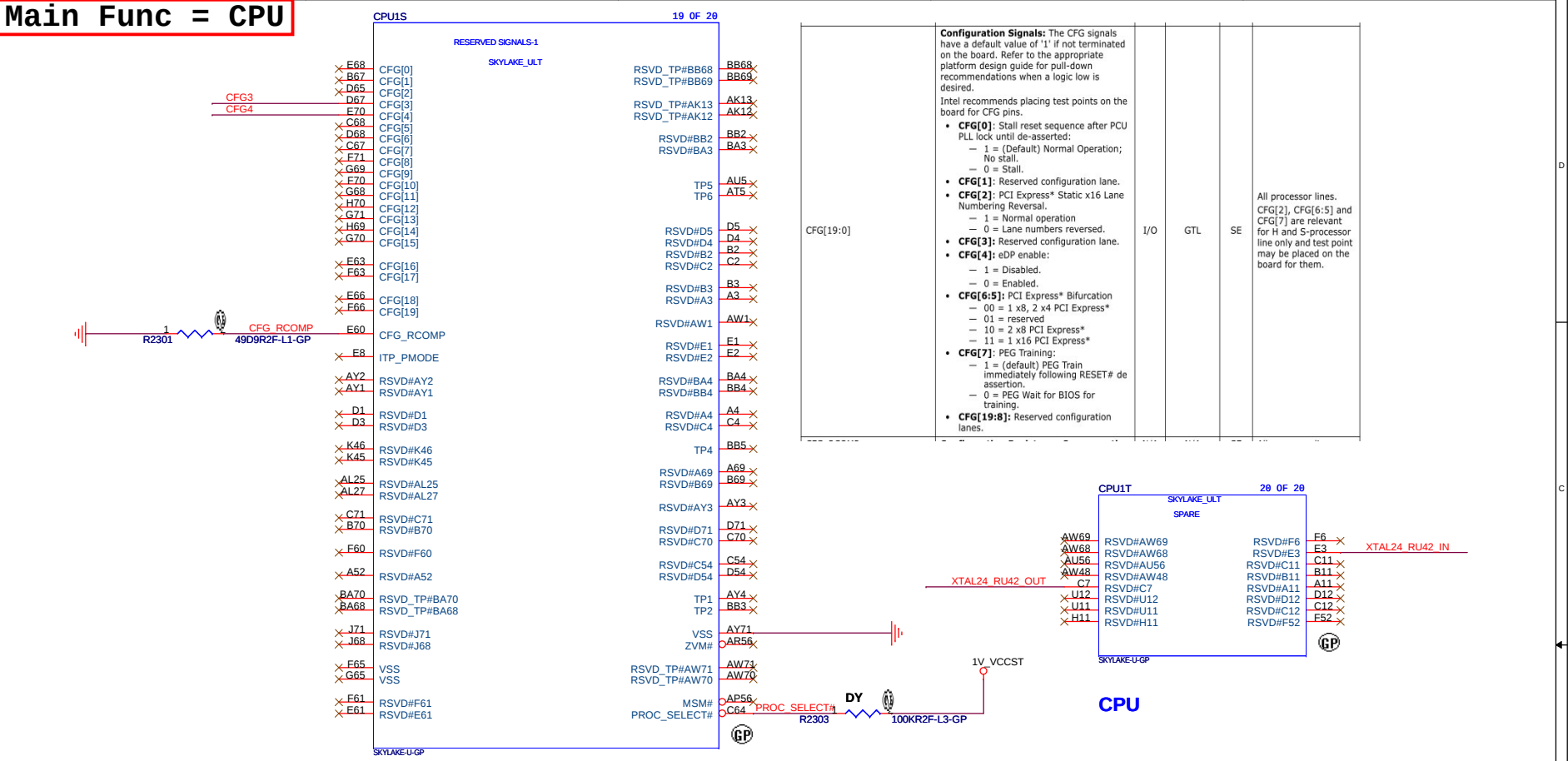
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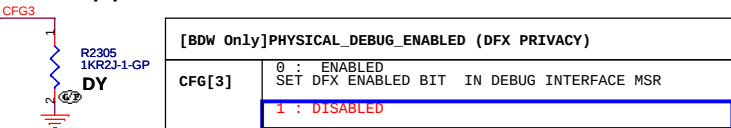
Title **CPU_(JTAG/CPU SIDE BAND)**

Size Custom	Document Number Woody KBL	Rev 2
Date: Friday, July 07, 2017	Sheet 22 of 106	

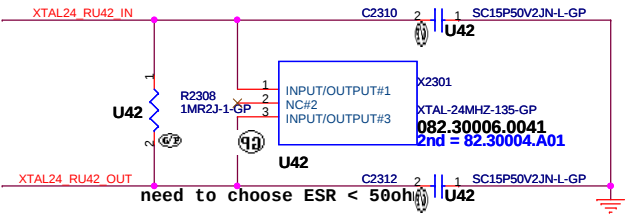
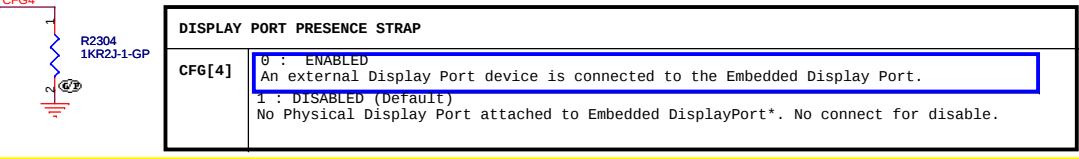
Main Func = CPU



PCH strap pin:



PCH strap pin:



PROC_SELECT#	Processor Select: This pin is for compatibility with future platforms. It should be unconnected for SKL.			N/A	All processor lines
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Title

CPU_RESERVED,CFG

Size Custom

Document Number

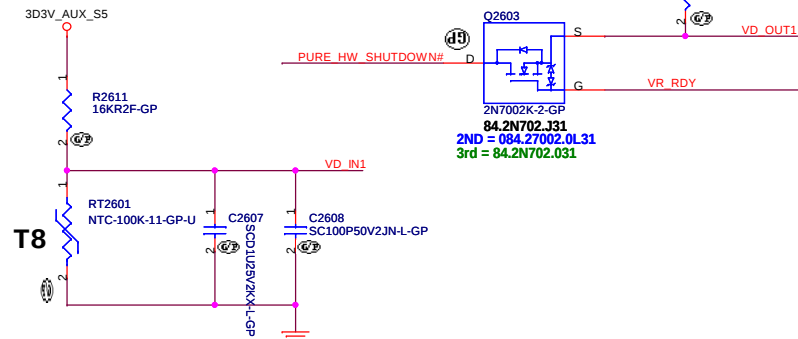
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Rev 2

Date: Friday, July 07, 2017

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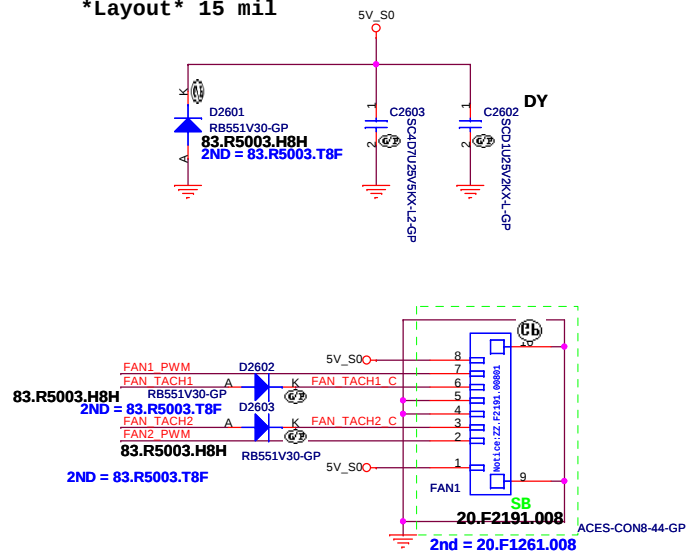
SSID = Thermal



RT2601 close CPU and Vcore chock

VD_IN1 trace 10 mli

Layout 15 mil



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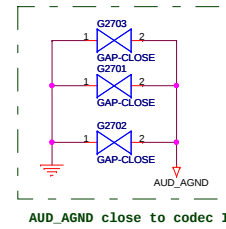
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Thermal 7718/Fan Controller P2793

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- SSID = AUDIO**



Closed U2701



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(LAN+VGA) CONNECTOR		
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RTS5170(CARD READER)		
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SSID = SDIO

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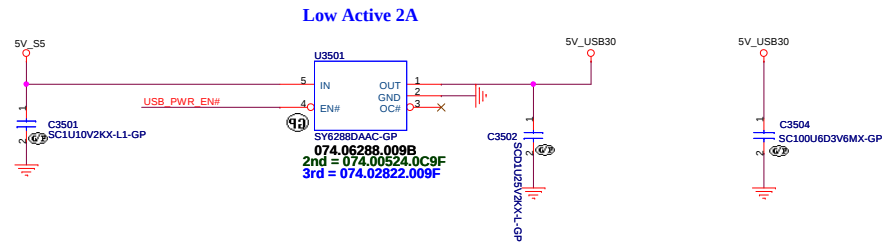
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[15] USB1_USB30_TX_N << >>
[15] USB1_USB30_TX_P << >>
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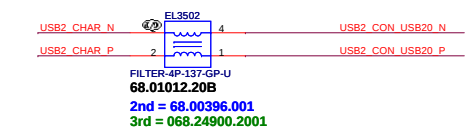
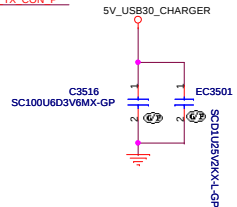
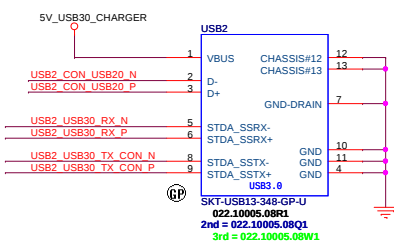
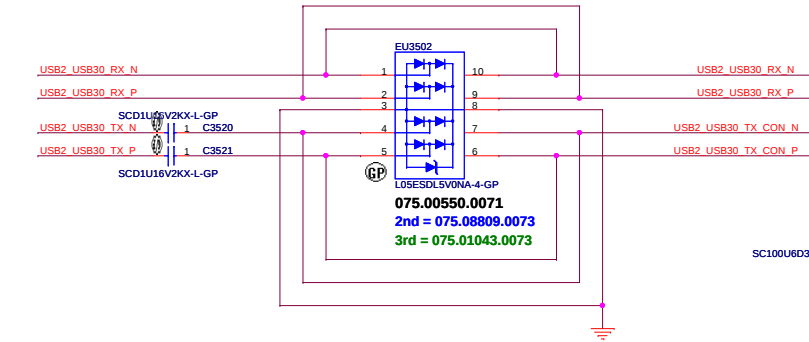
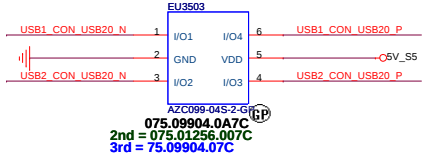
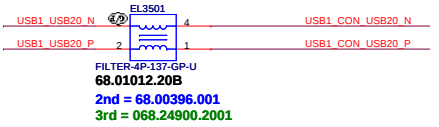
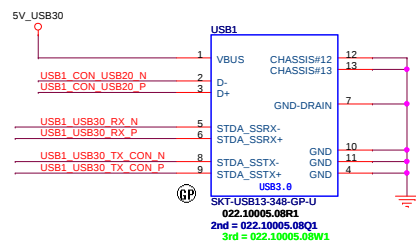
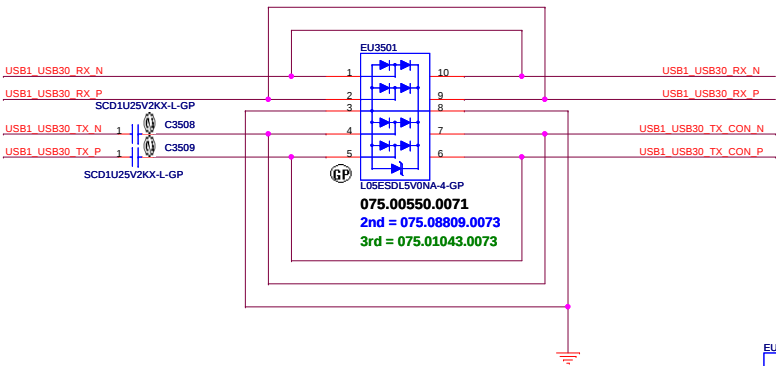
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[15] USB2_USB30_TX_N << >>
[15] USB2_USB30_TX_P << >>

[89] USB2_CON_USB20_N << >>
[89] USB2_CON_USB20_P << >>



USB 3.0 Connector Pin definition	
1	POWER
2	USB 2.0 D-
3	USB 2.0 D+
4	GND
5	StdA_SSRX- SuperSpeed RX
6	StdA_SSRX+
7	GND
8	StdA_SSTX- SuperSpeed TX
9	StdA_SSTX+



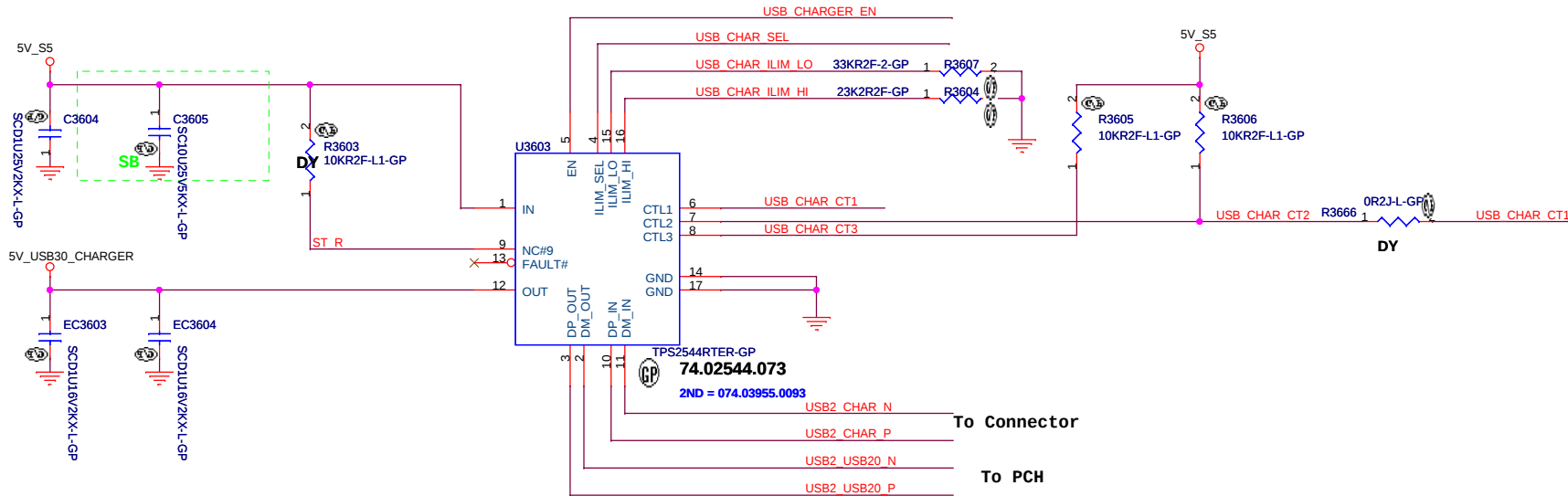
[24] USB_CHARGER_EN >>>
[24] USB_CHAR_SEL >>>
[24] USB_CHAR_CT1 >>>

To Connector

[35] USB2_CHAR_N <<<
[35] USB2_CHAR_P <<<

To PCH

[15] USB2_USB20_N <<<
[15] USB2_USB20_P <<<



CTL1	CTL2	CTL3	ILIM_SEL	Mode	Current Limit Setting	Comment
0	0	0	0	Discharge	NA	OUT held low
0	0	0	1	Discharge	NA	
0	0	1	0	DCP_Auto	ILIM_HI	Data Lines Disconnected
0	1	1	X			
0	1	0	0	SDP1	ILIM_LO	Data Lines connected
0	1	0	1		ILIM_HI	
1	0	0	0	DCP Forced Shorted	ILIM_LO	Device Forced to stay in DCP BC 1.2 charging mode
1	0	0	1		ILIM_HI	
1	0	1	0	DCP / Divider1	ILIM_LO	Device Forced to stay in DCP Divider 1 Charging Mode
1	0	1	1		ILIM_HI	
1	1	0	0	SDP1	ILIM_LO	Data Lines Connected
1	1	0	1	SDP1	ILIM_HI	
1	1	1	0	SDP2 ⁽¹⁾	ILIM_LO	
1	1	1	1	CDP ⁽¹⁾	ILIM_HI	Data Lines Connected

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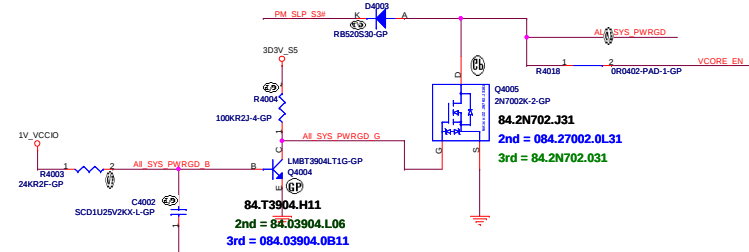
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```

[26.46] VR_RDY >>>
[20.24.45] PM_SLP_S3# >>>
[20] PCH_PWROK <<<
[24] 3V_S5_ENABLE >>
[45] 3V_EN <<>>

[24.26] PURE_HW_SHUTDOWN# >>>
[20.24] ALL_SYS_PWRGD <<<
[46] WCORE_EN <<<
[20.24.51] PM_SLP_S4# >>>
[20.60.91] PM_SLP_S0# >>>

```



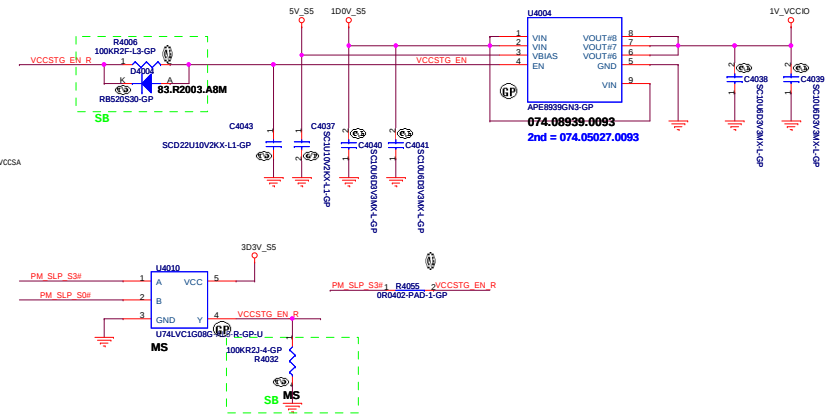
```
1126 Simon
Tuning RC for DRAM
VCCIO = SLP_S3
2.5v = SLP_S4
VCCIO effect VCCSA

Sequence should
DDR4 =
SLP_S4 > 2.5V > VDDQ > VCCIO

SLP_S4 =
SLP_S4 > VDDQ > VDDIO > VDDSA

DDR4
R4006 = 100K
C4043 = 0.22u
D5762 = stuff

DDR3
R4006 = 33K
C4043 = 0.1u
D5762 = stuff
```



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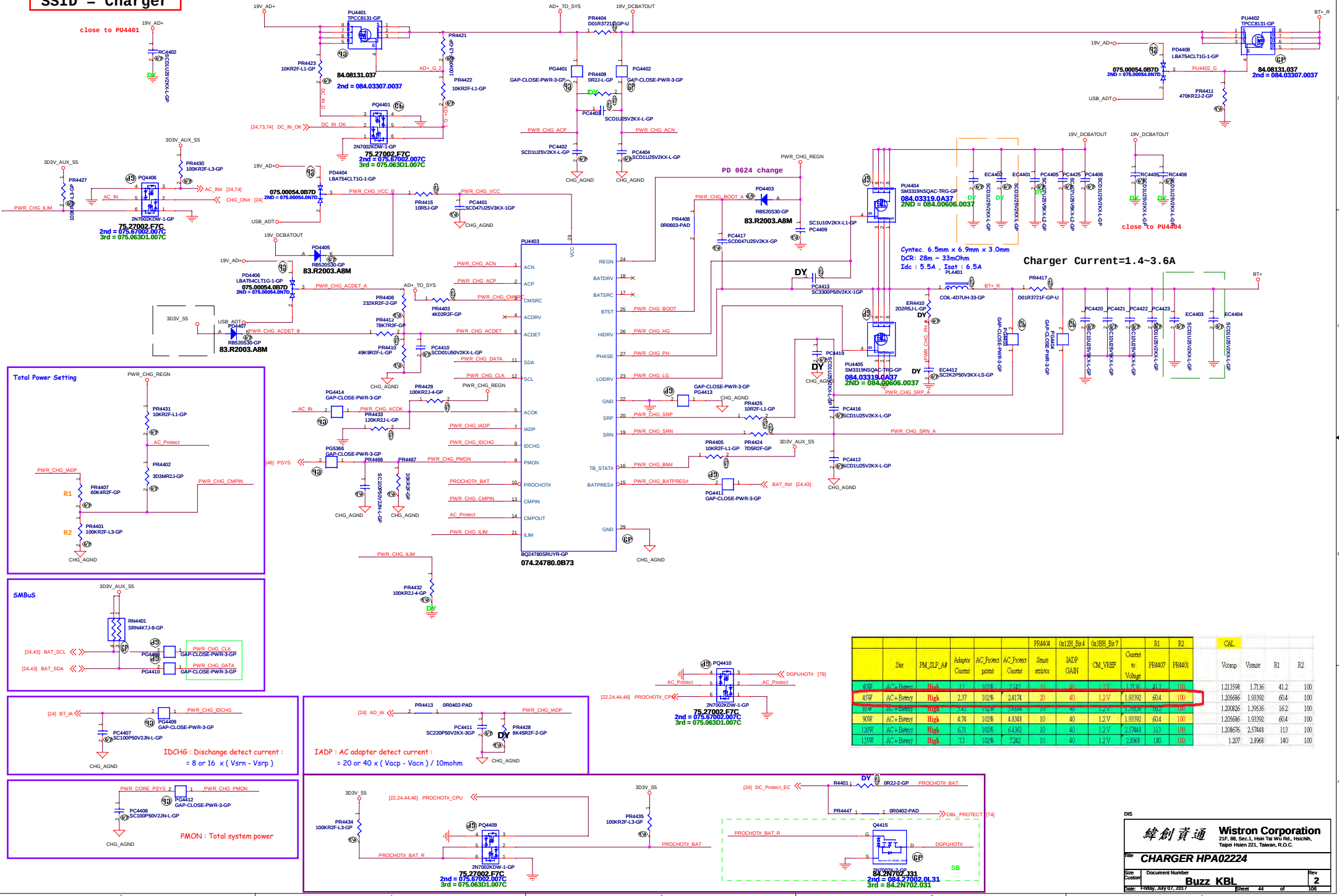
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Adaptor in to generate DCBATOUT



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SSID = Charger



[24] 5V_EN >>> PWR 5V_EN

40] PM_SLP_S3# >>>



PM_SLP_S3#

Q4501

PWR_5V_EN_R

100KR23-1-GP

2N7000K-2 GP

842N702.J31

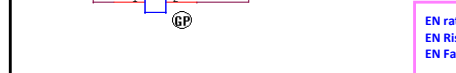
2ND = 084.27002.0L31

3rd = 84.2N702.031

2017/07/03 - 2

Rober modify by Ultrasonic Mode

Vin Operating range : 5.5~24V
Vin_Max : 27V
Ilimit : 10A



Q4502

The diagram shows a MOSFET circuit labeled Q4502. It features a 2N7000K-2-GP MOSFET with its gate connected to G and its source to S. The drain is connected to a network of components including a 84.2N702.J31 component, a 2ND = 084.27002.0L31 component, and a 3rd = 84.2N702.031 component. A DY component is also present. Power connections are indicated as PWR_3D3V_EN_R and PWR_3D3V_EN.

G
S

D PWR_3D3V_EN_R PWR_3D3V_EN

(CP)

2N7000K-2-GP

84.2N702.J31

2ND = 084.27002.0L31

3rd = 84.2N702.031

DY

PR4512

100KR2J-1-GP

DY

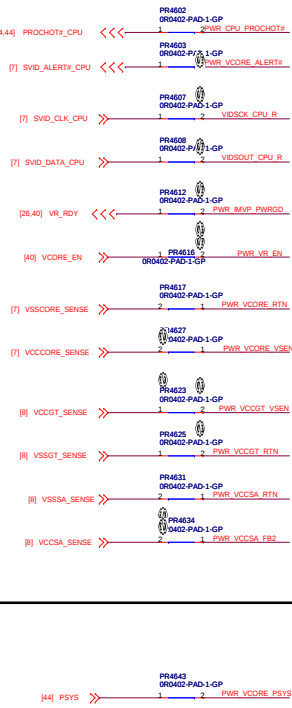
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Rober modify by Ultrasonic Mode

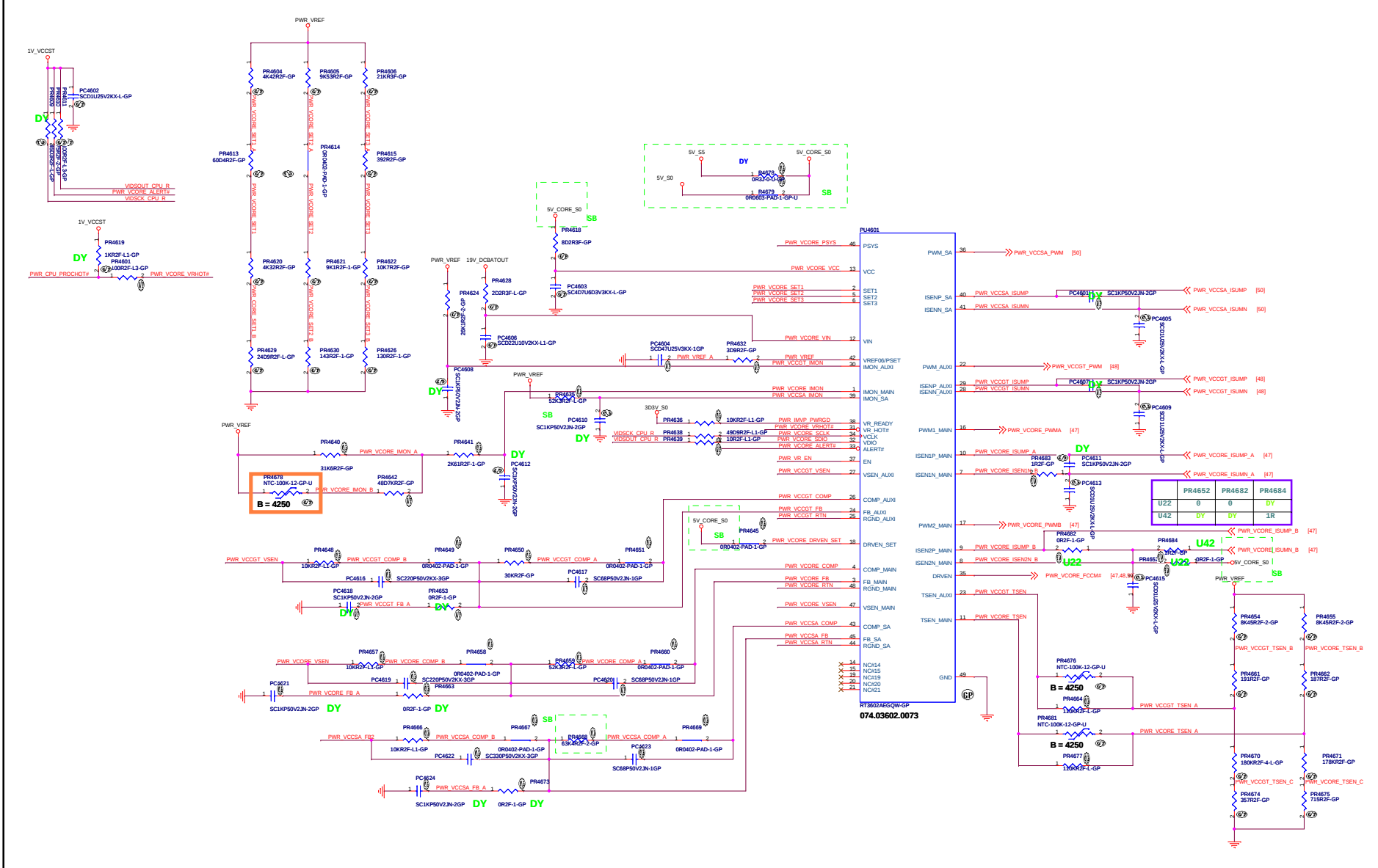
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OCP : 9A

IDC : 6A
OCP : 10A

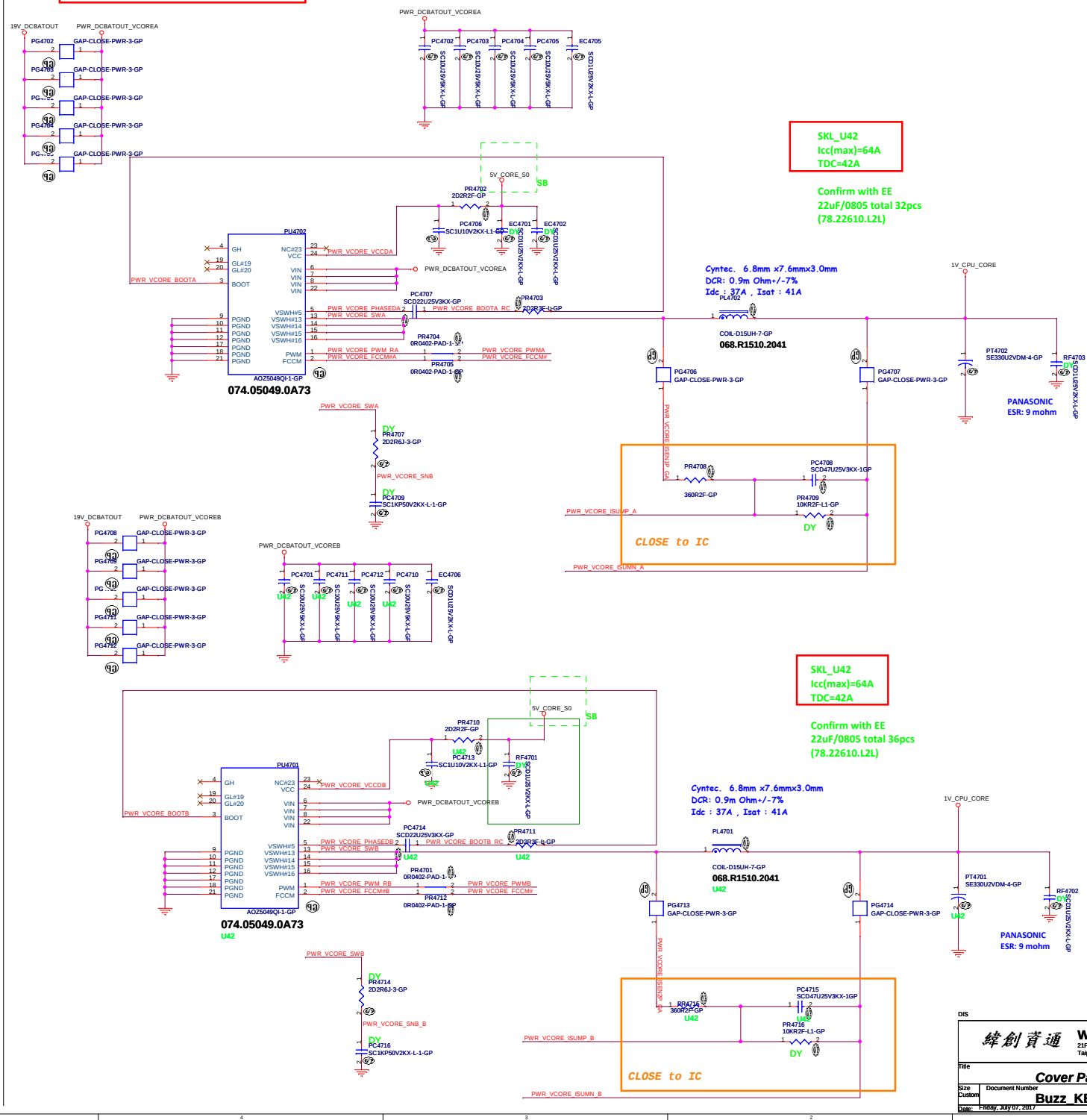
OFFPAGE



Main Func = CPU_CORE



Main Func = CPU_CORE



SKL_U42
Icc(max)=64A
TDC=42A

Confirm with EE
22uF/0805 total 32pcs
(78.22610.L2L)

Cyntec. 6.8mm x7.6mmx3.0mm
DCR: 0.9m Ohm+/-7%
Idc : 37A , Isat : 41A

068.R1510.2041

PANASONIC
ESR: 9 mohm

CLOSE to IC

SKL_U42
Icc(max)=64A
TDC=42A

Confirm with EE
22uF/0805 total 36pcs
(78.22610.L2L)

Cyntec. 6.8mm x7.6mmx3.0mm
DCR: 0.9m Ohm+/-7%
Idc : 37A , Isat : 41A

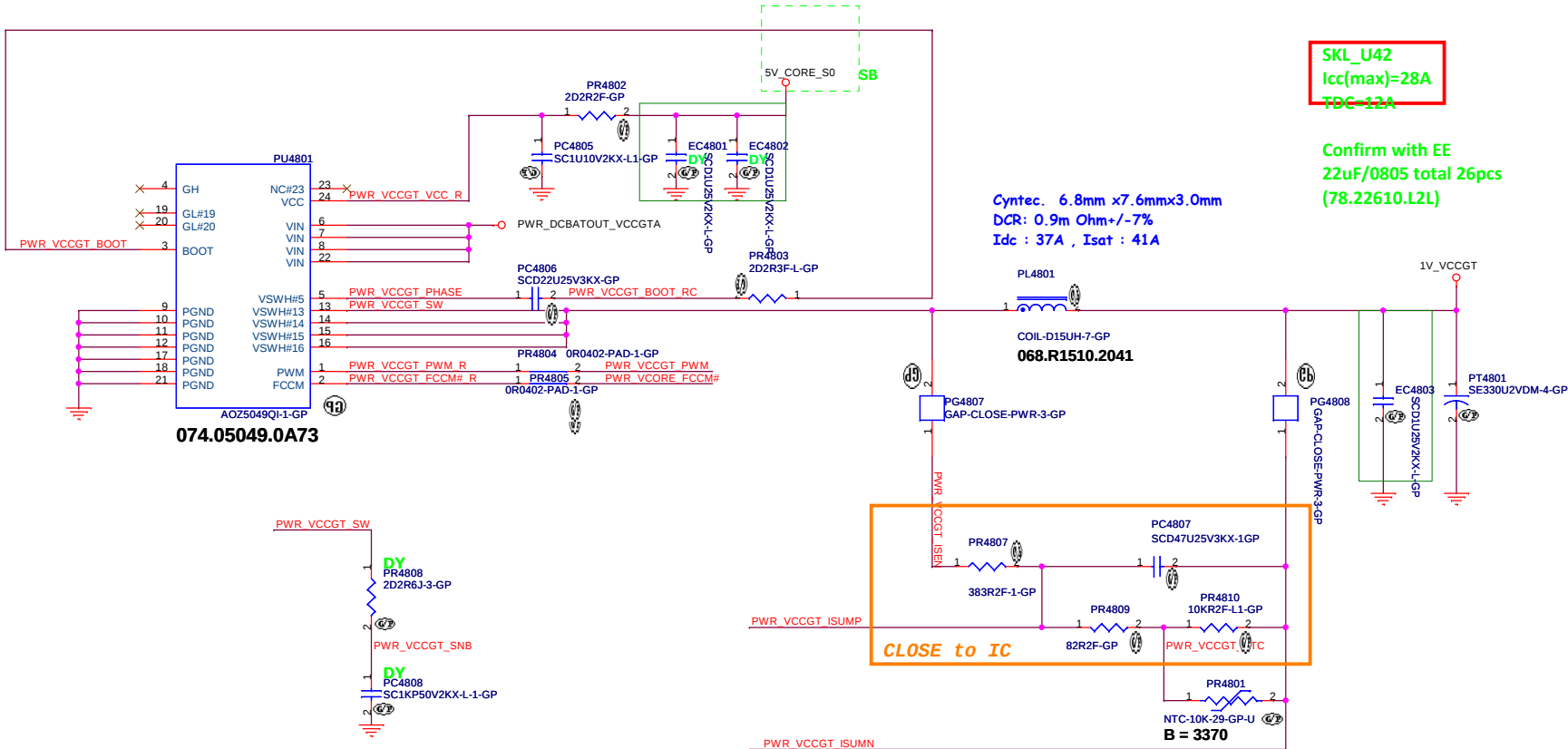
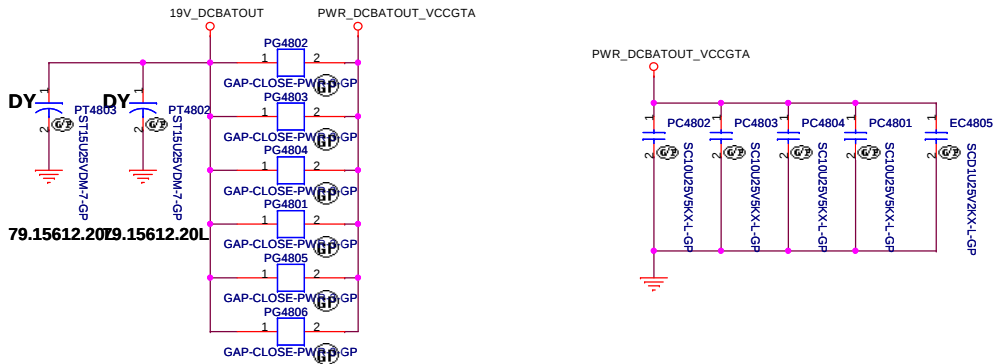
068.R1510.2041

PANASONIC
ESR: 9 mohm

CLOSE to IC

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Main Func = CPU_CORE



SKL_U42
Icc(max)=28A
TDC=12A

Confirm with EE
22uF/0805 total 26pcs
(78.22610.L2L)

Cyntec. 6.8mm x7.6mmx3.0mm
DCR: 0.9m Ohm+/-7%
Idc : 37A , Isat : 41A

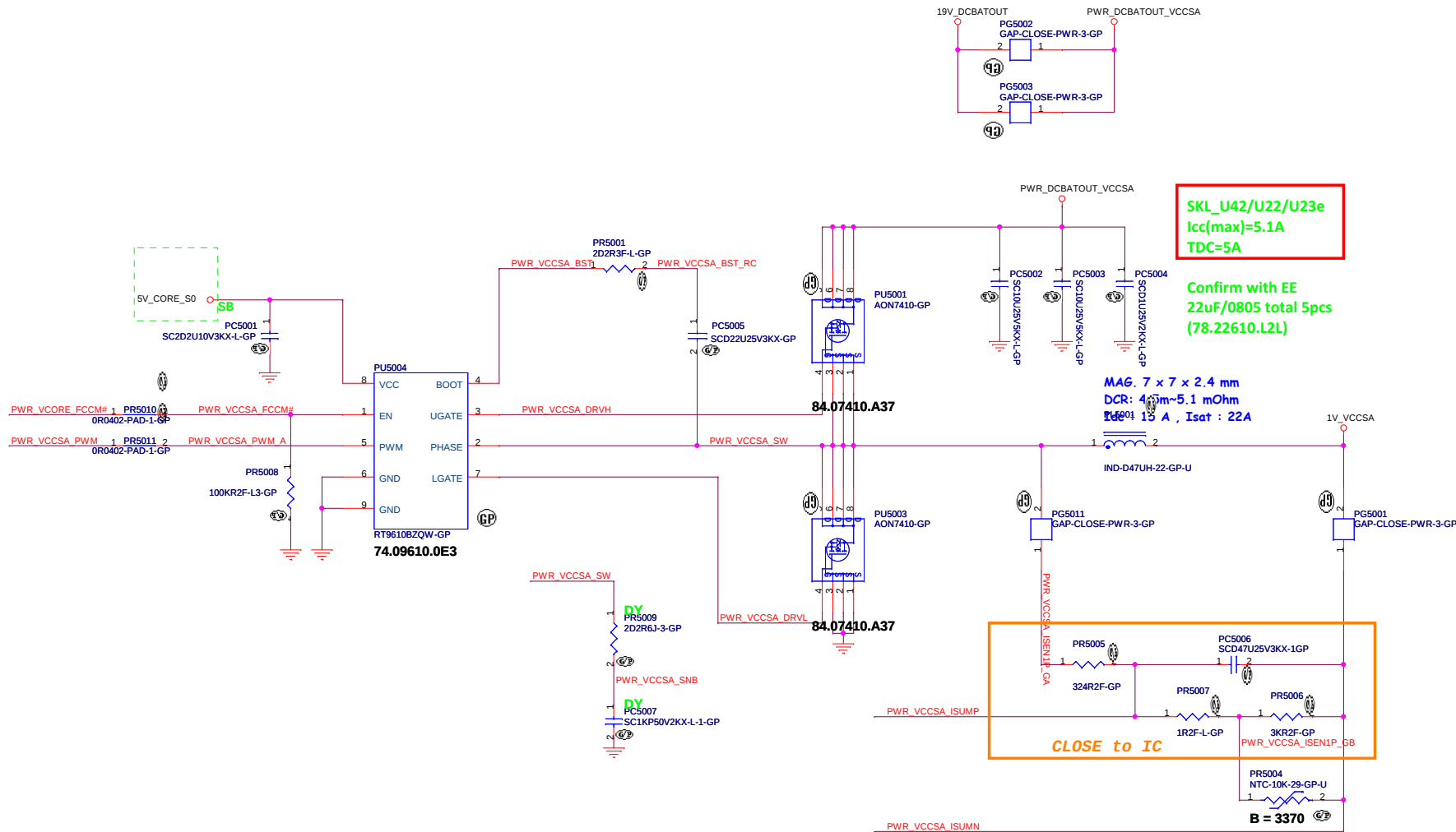
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Main Func = CPU_CORE

[46,47,48] PWR_VCORE_FCCM# >>>
 [46] PWR_VCCSA_PWM >>>
 [46] PWR_VCCSA_ISUMP <<<
 [46] PWR_VCCSA_ISUMN <<<



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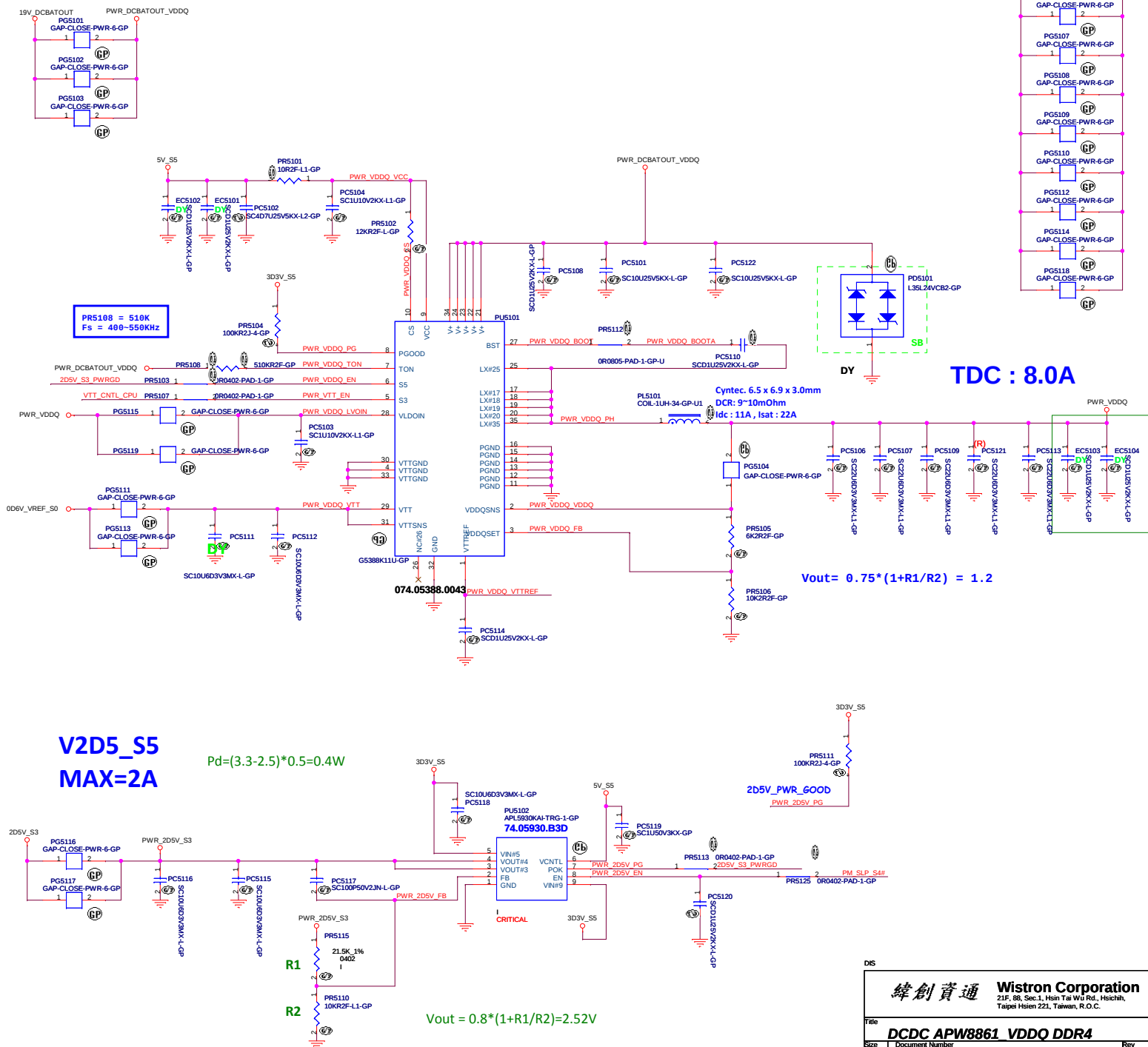
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D5V ENABLE CONTROL

[4] VTT_CNTL_CPU >>—

[20,24,40] PM SLP S4# >>>_____

[20,24,40] PM_SLP_S4# >>>_____



TDC : 8.0A

$$V_{out} = 0.75 * (1 + R1/R2) = 1.2$$

V2D5_S5
MAX=2A

$$P_d = (3.3 - 2.5) \times 0.5 = 0.4 \text{ W}$$

$$V_{out} = 0.8 * (1 + R1/R2) = 2.52V$$

[53] 1D8V_S5_PWRGD >>_____



$$V_{out} = 0.75 * (1 + R1/R2) = 1.0V$$

1D8V_S5 POWER GOOD

1D8V_S5_PWRGD [52]

3V_5V_POK [20,45,73]

1D8V_S5

$PD = (V_{in} - V_{out}) \times I_{out}$
 $= (3.3 - 1.8) \times 0.3A = 0.45W$
 $PD \text{ de-rating}(\%) = 0.45W / 1.33W = 33.8\%$
1125 Simon
Vendor suggest to replace 74.09025.A3D by 74.09025.D3D

PU5301
G9661-25ADJF11U-GP-U
74.09661.07D

PWR 1D8V_S5_PWRGD	1	POK	GND	9
PWR 1D8V_S5_EN	2	VEN	GND	8
PWR 1D8V_S5_PVDD	3	VIN	ADJ	7
PWR 1D8V_S5_VDD	4	VPP	VO	6
			NC#5	5

R1 PR5303 12K7R2F-GP
R2 PR5304 10KR2F-L1-GP

Vout Setting
 $V_{out} = 0.8 * (1 + R1/R2)$
 $= 0.8 * (1 + 12K7 / 10K)$
 $= 1.816V$

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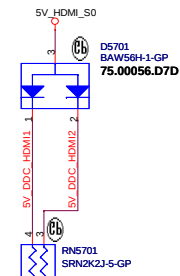
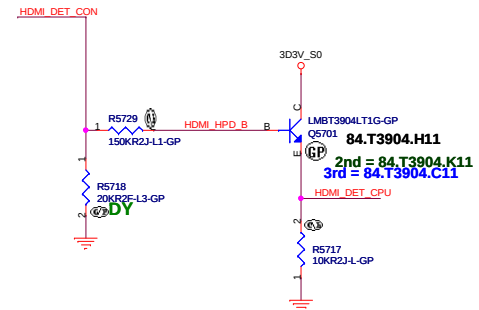
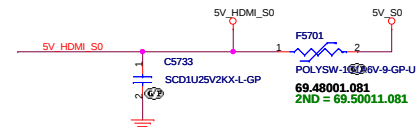
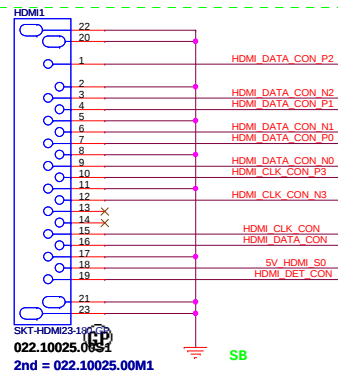
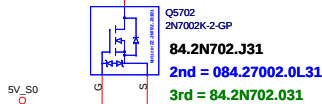
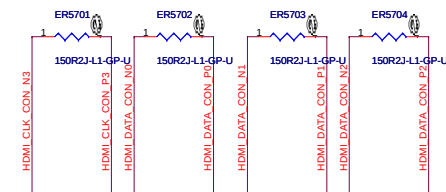
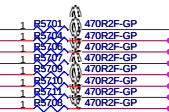
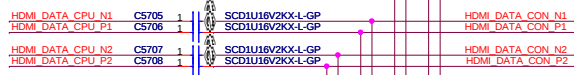
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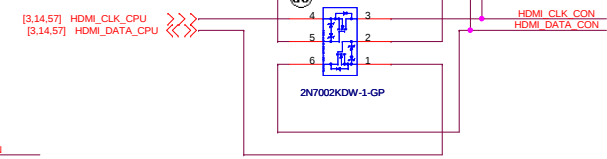
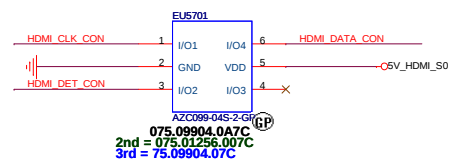
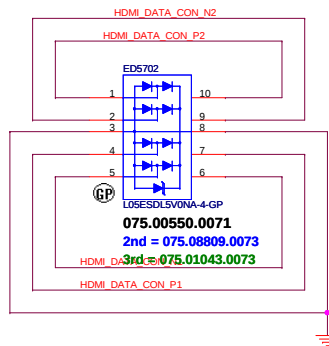
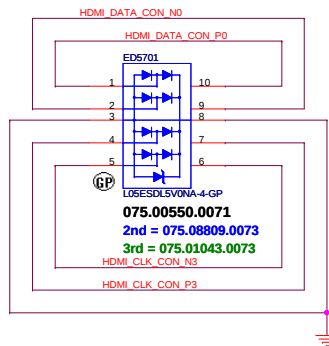
SSID = VIDEO

HDMI CONN

HDMI Level Shifter & CONNECTOR



EMI Request :



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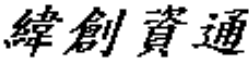
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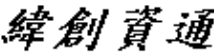
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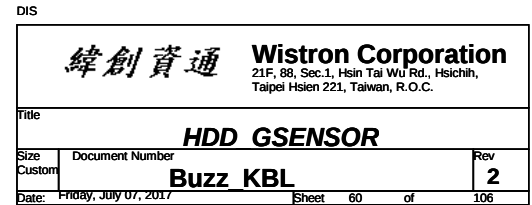
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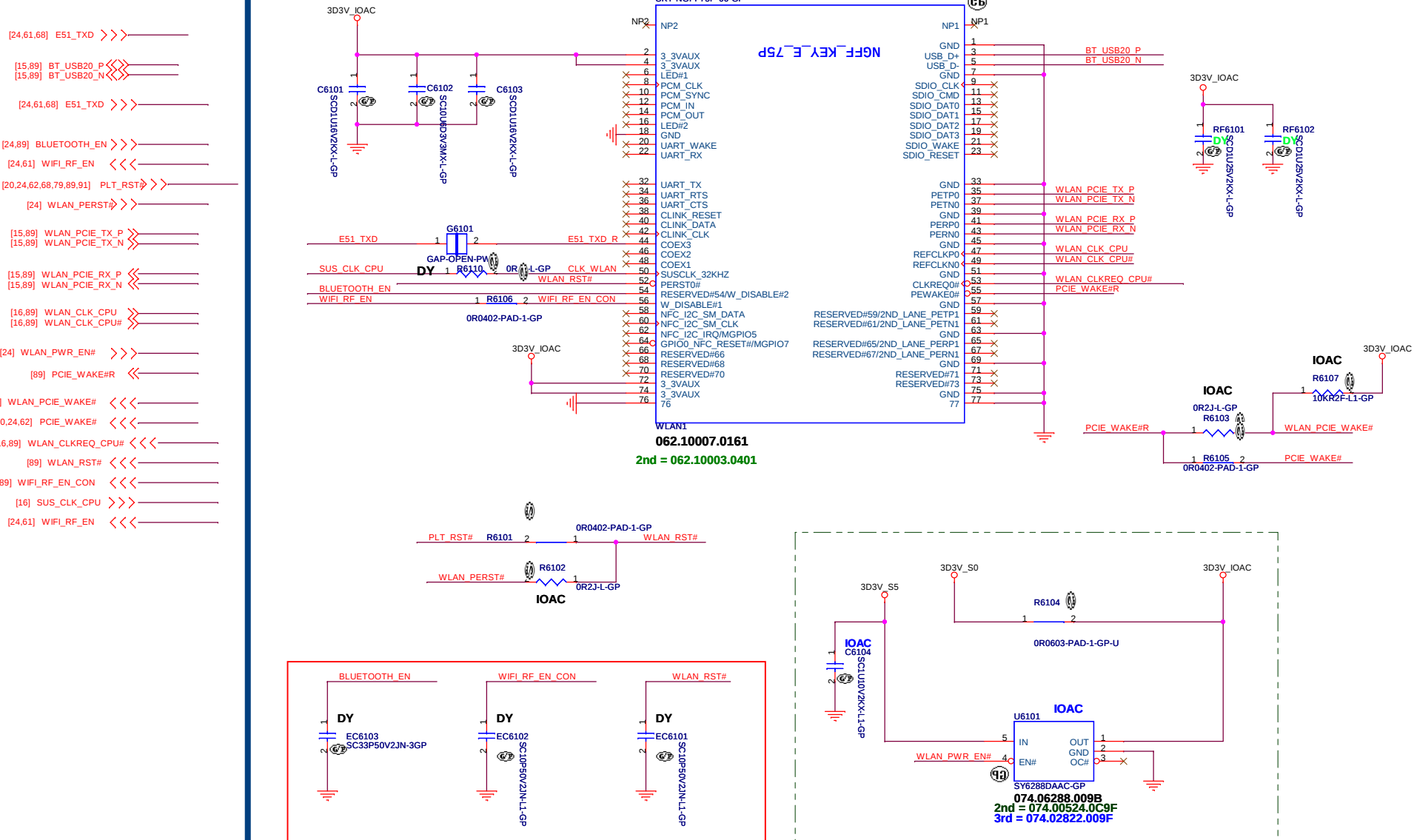
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SSID = Wireless Mini Card Connector(802.11a/b/g/n)



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SSID = mSATA

Mini Card Connector(mSATA)

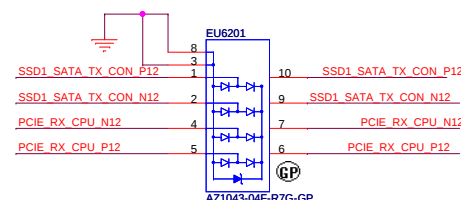
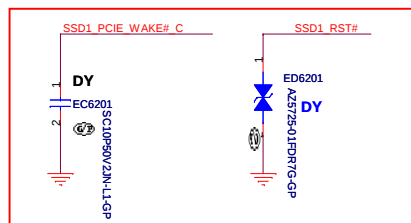
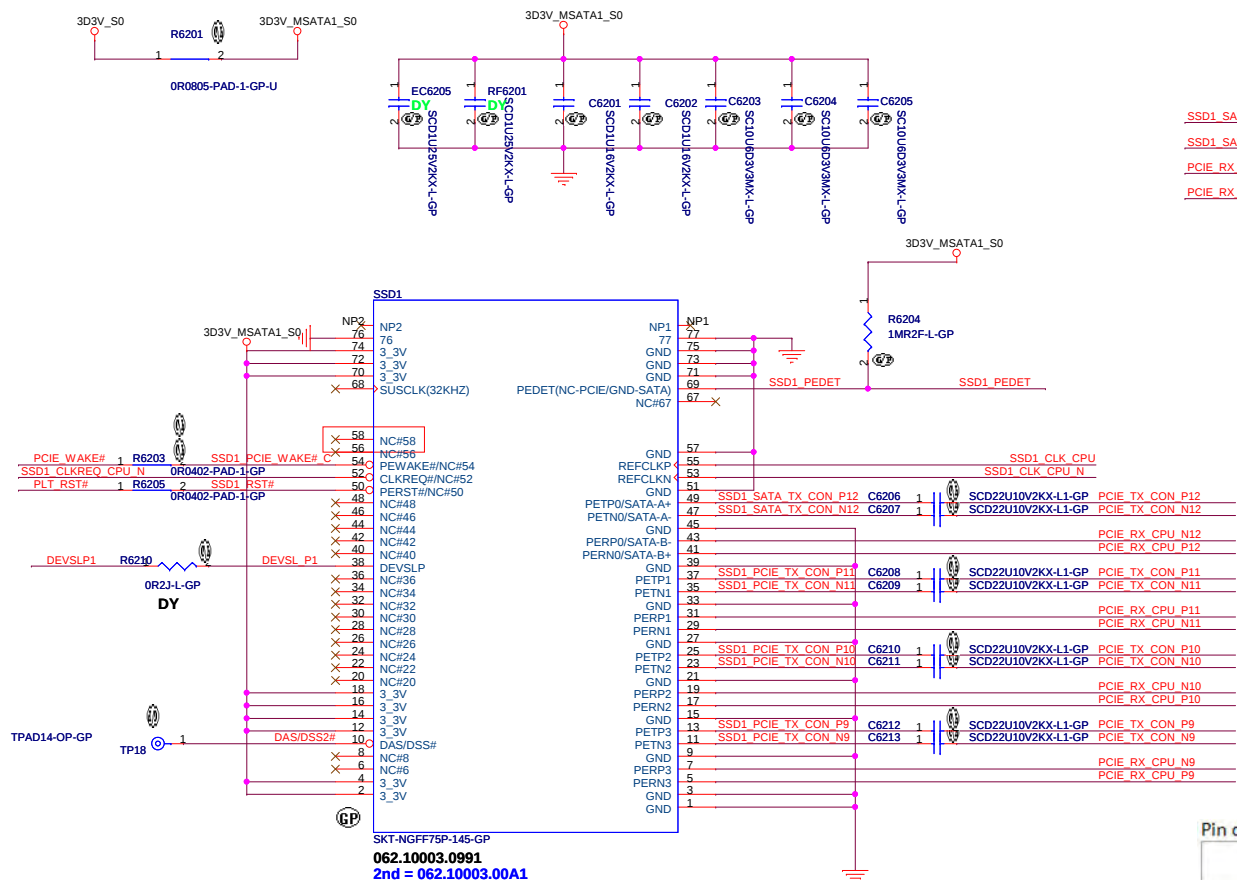
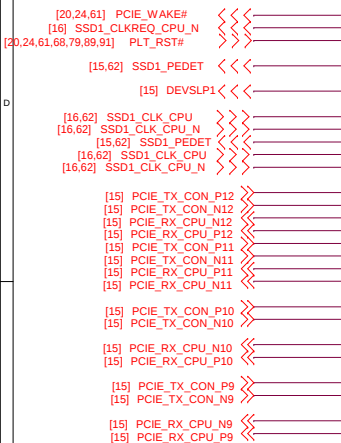


Figure 12-1. PCI Express® Link Configurations Supported by the Guidelines in this Chapter

PCH-LP Details		PCIe* Controller #1				PCIe* Controller #2				PCIe* Controller #3			
Flex I/O Lane #		5	6	7	8	5	6	7	8	5	6	7	8
PCIe Lane #		1	2	3	4	1	2	3	4	1	2	3	4
Base-U	3x4	DP 1				DP 2				DP 3			
	2x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x2+1x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x4	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	2x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
Premium-U	3x4	DP 1				DP 2				DP 3			
	2x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x2+1x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x4	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	2x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
Premium-Y	3x4	DP 1				DP 2				DP 3			
	2x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x2+1x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	1x4	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12
	2x2	DP 1	DP 2	DP 3	DP 4	DP 5	DP 6	DP 7	DP 8	DP 9	DP 10	DP 11	DP 12

Pin define from PCH and socket side.

	High (1)	Low (0)
PCH GPIO	SATA	PCIe
M.2 CONFIG_1	PCIe**	SATA

**** Native: Internal Pull-Up (15k-40k) when function**

Table 27. Socket 2 Module Configuration

State #	Module Configuration Decodes				Module Type and Main Host Interface	Port Configuration ¹
	CONFIG_0 (Pin 21)	CONFIG_1 (Pin 69)	CONFIG_2 (Pin 75)	CONFIG_3 (Pin 1)		
0	GND	GND	GND	GND	SSD – SATA	N/A
1	GND	N/C	GND	GND	SSD – PCIe	N/A

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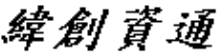
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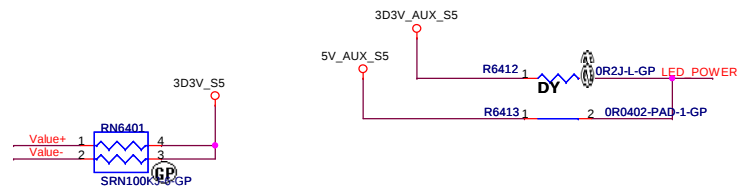
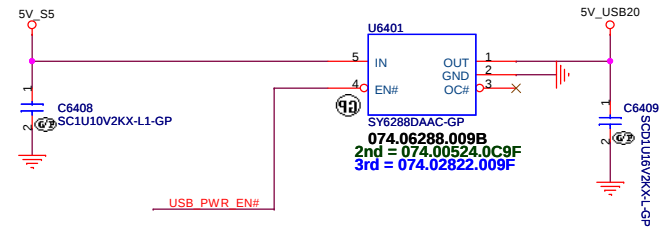
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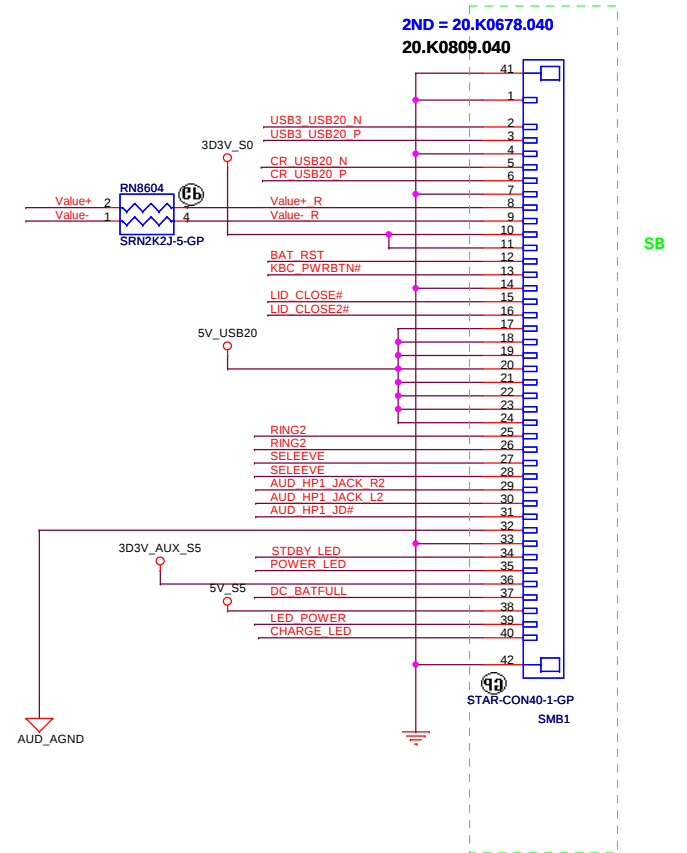
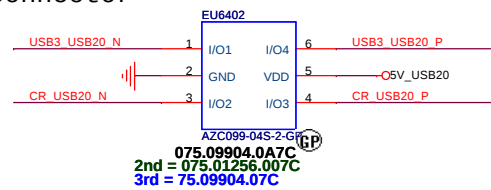
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title		
Size A4	Document Number Buzz KBL	Rev 2
Date: Friday, July 07, 2017		Sheet 63 of 106

SSID = User.Interface

Low Active 2A



Close connector



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Title			LED Bard/Power Button		
Size	Document Number				Rev
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Date:	Friday, July 07, 2017				Sheet 64 of 106

[24,89] KSI[0..7] >>> _____

[24,89] KSOQ[0..17] <<< _____

[24] EC_TPCLK <<< _____

[24] EC_TPDATA <<< _____

[24,89] FUN_OFFR >>> _____

[89] EC_TP_CLK_C <<< _____

[89] EC_TP_DATA_C <<< _____

[89] I2C1_DATA_TP <<< _____

[89] I2C1_CLK_TP <<< _____

[89] TP_INIF_R <<< _____

1] PTP_PWR_EN# >>> _____

[22] TP_IN# <<< _____

[24] EC_TP_IN# <<< _____

[6] PM_TP_CLK <<< _____

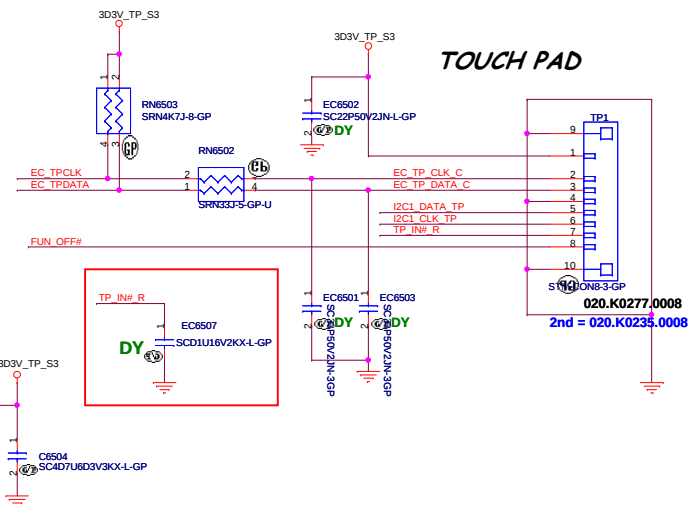
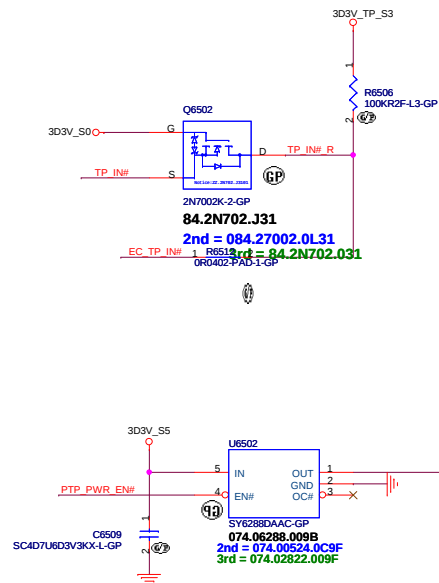
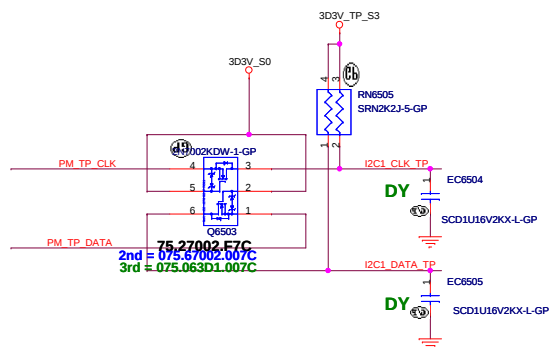
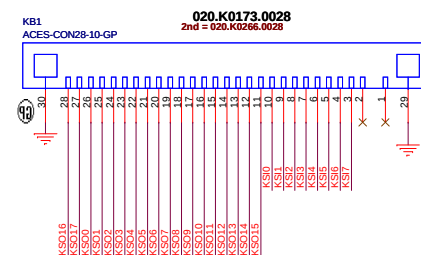
[6] PM_TP_DATA <<< _____

[24] KB_BL_PWM >>> _____

[24] KB_BL_DET <<< _____

[89] KB_LED_PWM# >>> _____

[89] KB_BL_DET_R <<< _____

[illegible]

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Title Key Board/Touch Pad			
Size Custom	Document Number Buzz KBL		Rev 2
Date	Friday, July 07, 2017	Sheet 65 of	106

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Title

Reserved

Size
A4

Document Number

Buzz KBL

Rev
2

Date: Friday, July 07, 2017

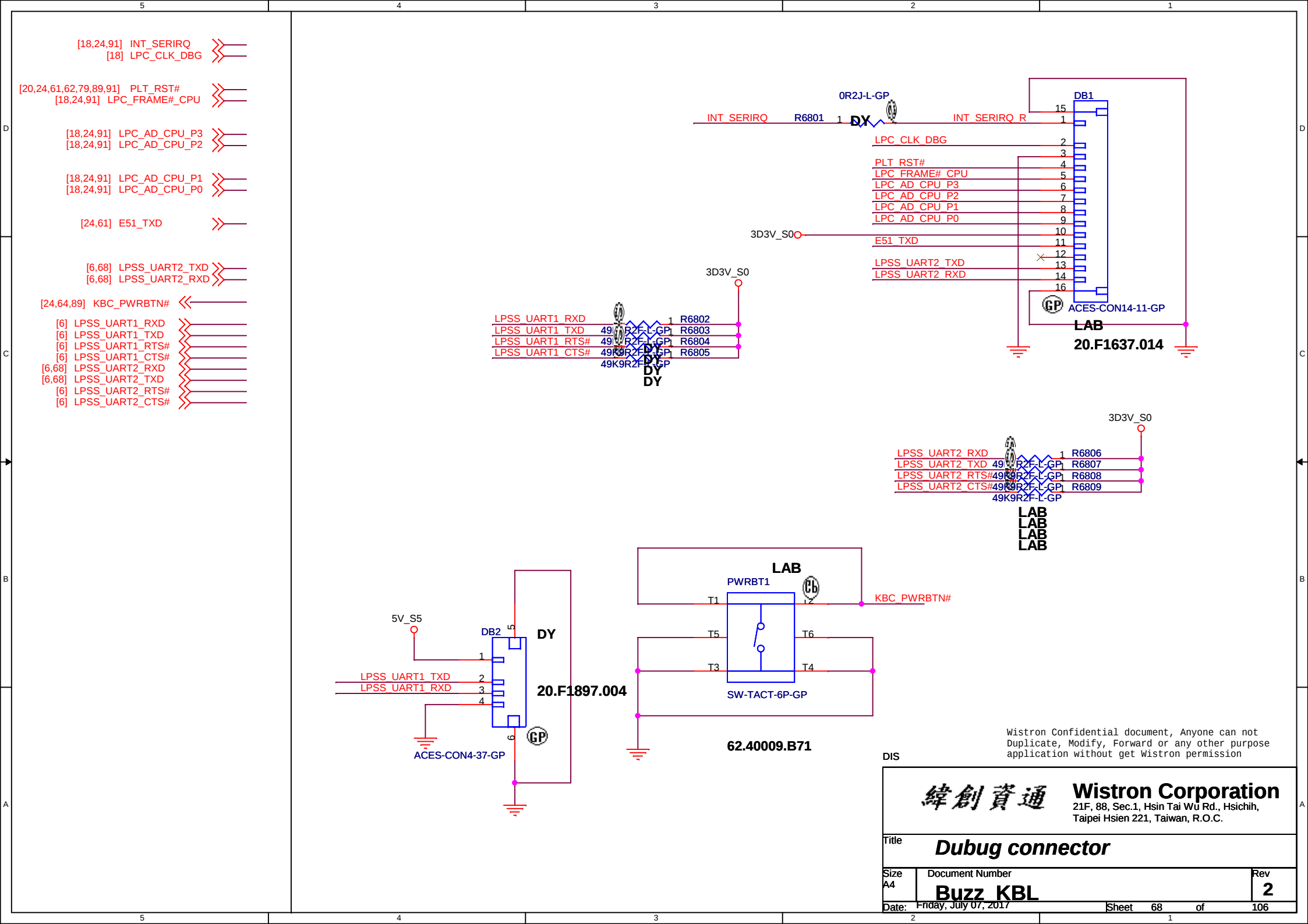
Sheet 66 of 106

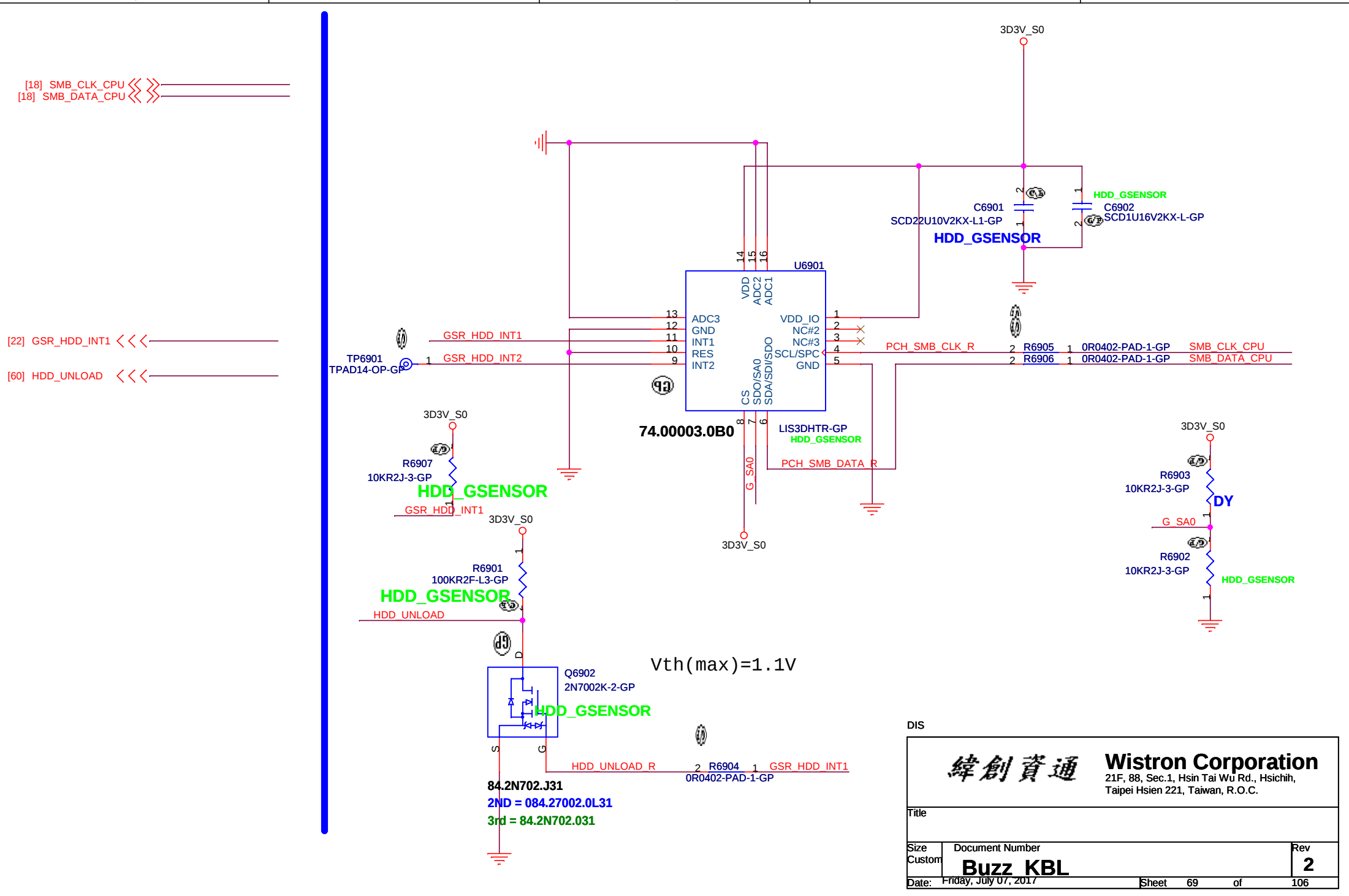
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Title		
Reserved		
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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.					
Title					
Size	Document Number				Rev
Custom	Buzz KBL				2
Date:	Friday, July 07, 2017				Sheet 69 of 106

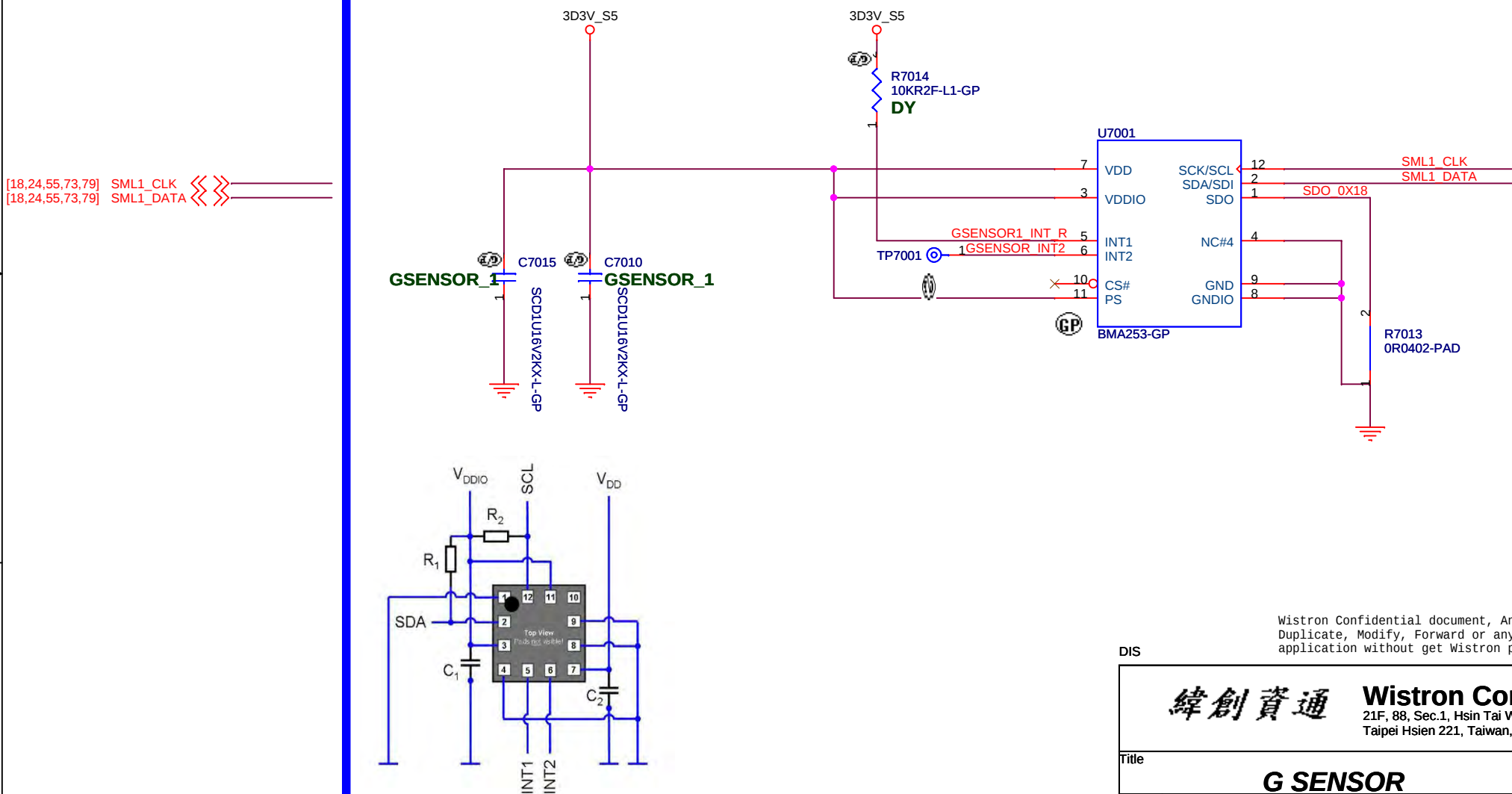
SSID = User.Interface

G Sensor

Note

- no via, trace, under the sensor (keep out area around 2mm)
- stay away from the screw hole or metal shield soldering joints
- design PCB pad based on our sensor LGA pad size (add 0.1mm)
- solder stencil opening to 90% of the PCB pad size
- mount the sensor near the center of mass of the NB as possible as you can

The default I²C address of the device is 0011000b (0x18). It is used if the SDO pin is pulled to 'GND'. The alternative address 0011001b (0x19) is selected by pulling the SDO pin to 'V_{DDIO}'.



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Title

G SENSOR

Size Custom

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Rev

2

Date: Friday, July 07, 2017

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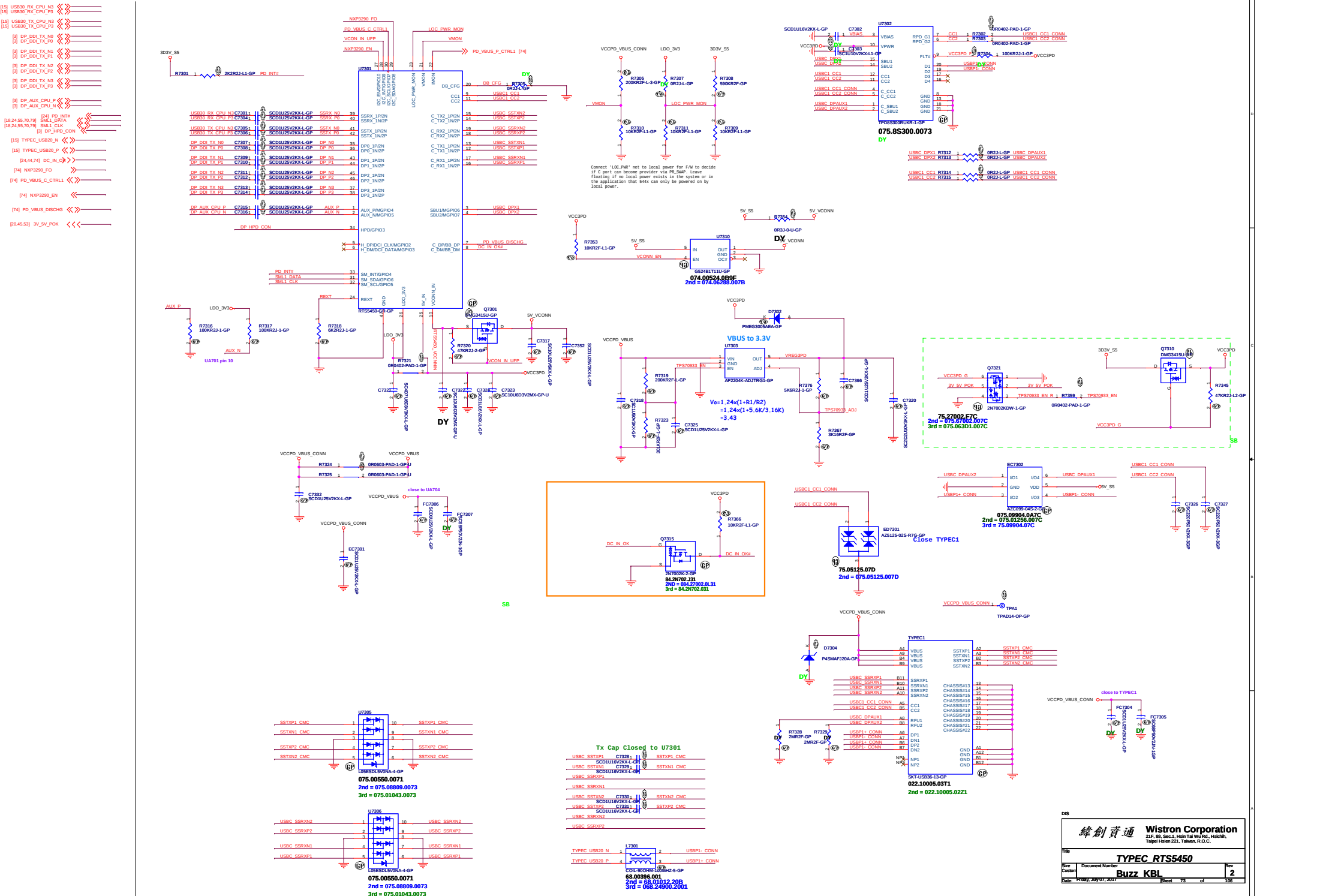
DIS

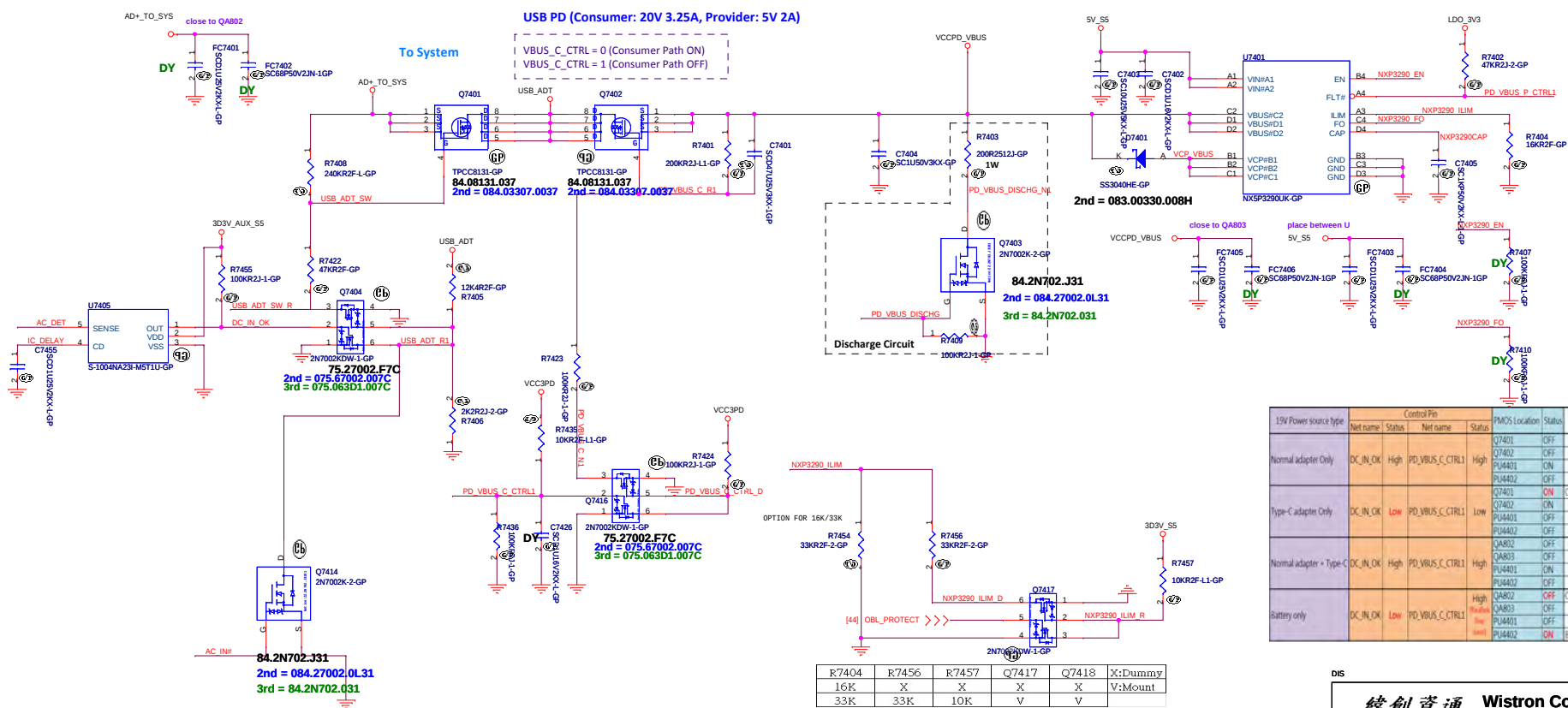
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
Thunderbolt (4/5)		
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Title		
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19V Power source type	Control Pin		Control Pin		PMOS Location	Status	Remark
	Net name	Status	Net name	Status			
Normal adapter Only	DC_IN_OK	High	PD_VBUS_C_CTRL1	High	Q7401	OFF	
					Q7402	OFF	
					PU4401	ON	
Type-C adapter Only	DC_IN_OK	Low	PD_VBUS_C_CTRL1	Low	Q7401	ON	Control by Charger DC_IN_OK
					Q7402	ON	
					PU4401	OFF	
Normal adapter + Type-C	DC_IN_OK	High	PD_VBUS_C_CTRL1	High	Q7401	OFF	
					Q7402	OFF	
					PU4401	ON	
Battery only	DC_IN_OK	Low	PD_VBUS_C_CTRL1	Low	Q7401	ON	Control by Charger ACOK_IN_M
					Q7402	OFF	
					PU4401	OFF	

R7404	R7456	R7457	Q7417	Q7418	X:Dummy
16K	X	X	X	X	V:Mount
33K	33K	10K	V	V	

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Title

GPU (DIGITALOUT)

Size

Custom

Date

Friday, JULY 07, 2017

Document Number

Buzz KBL

Rev

2

Sheet

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of

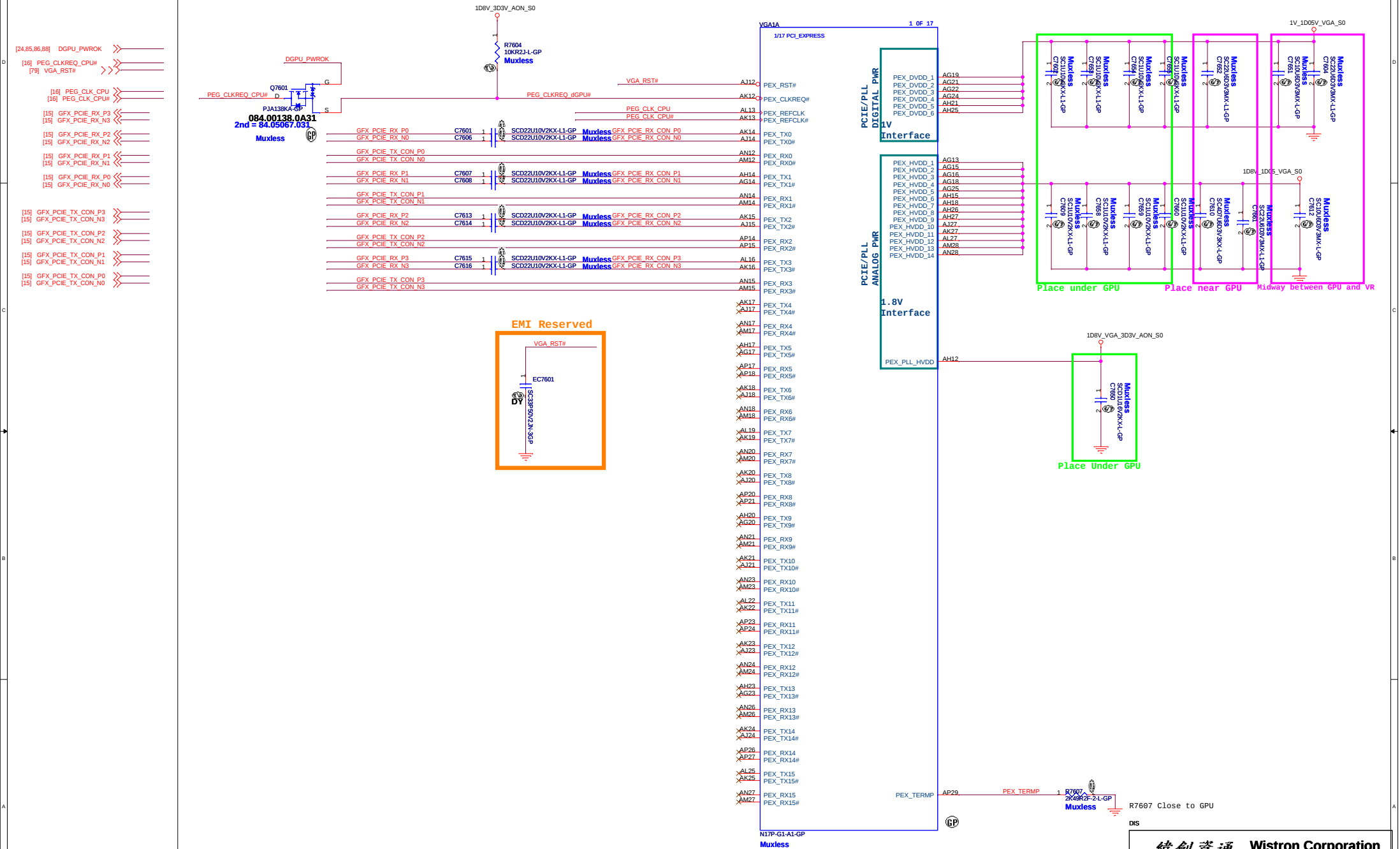
106

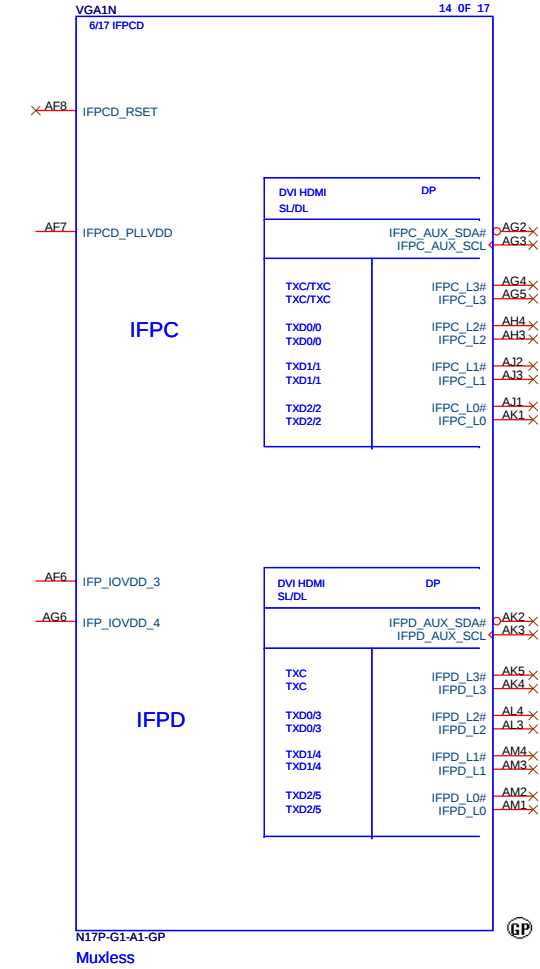
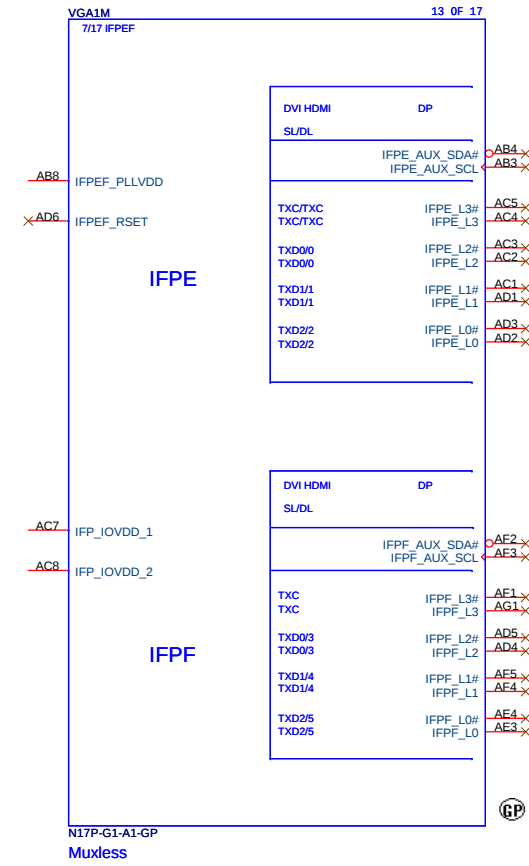
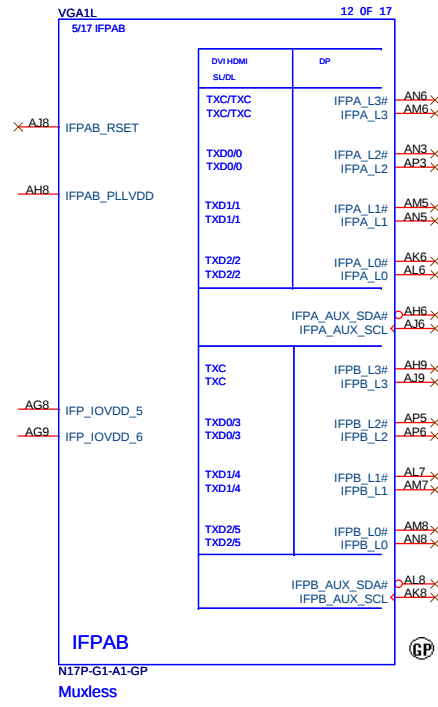
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Title		
GPU (VRAM I/F)		
Size	Document Number	Rev
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Friday, July 07, 2017		

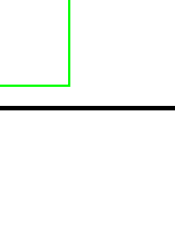
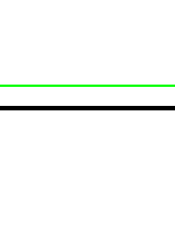
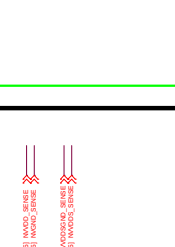
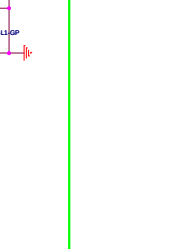
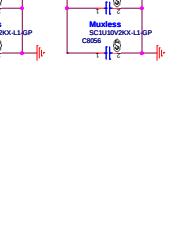
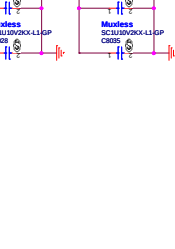
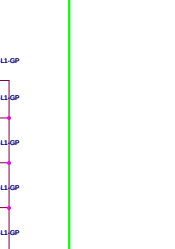
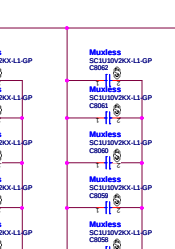
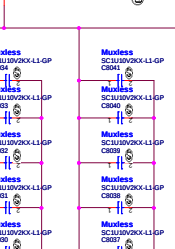
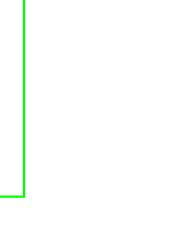
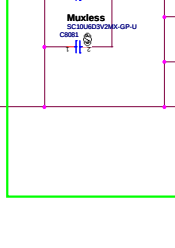
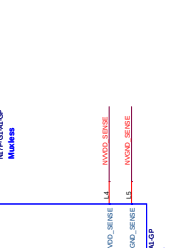
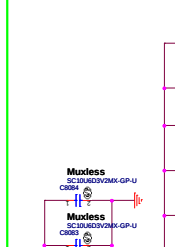
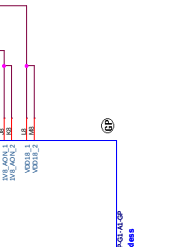
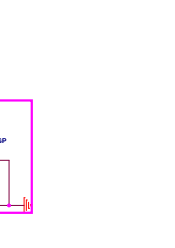
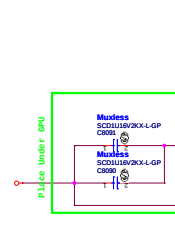
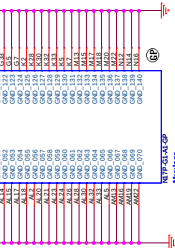
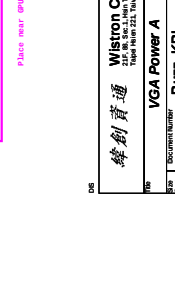
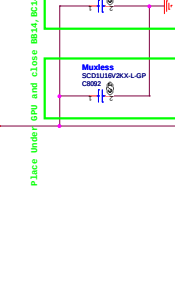
- PEX_HVDD and PEX_PLL_HVDD rails must be shared with 1V8_AON for GC6 2.1











[78] MDA[63..0] << >>

[78] FBA_CMD[31..0] << >>

[78] DQMA0
[78] DQMA1
[78] DQMA2
[78] DQMA3
[78] DQMA4
[78] DQMA5
[78] DQMA6
[78] DQMA7

[78] QSAP_0
[78] QSAP_1
[78] QSAP_2
[78] QSAP_3
[78] QSAP_4
[78] QSAP_5
[78] QSAP_6
[78] QSAP_7

[78] FBA_WCK01
[78] -FBA_WCK01
[78] FBA_WCK23
[78] -FBA_WCK23
[78] FBA_WCK45
[78] -FBA_WCK45
[78] FBA_WCK67
[78] -FBA_WCK67

[78] CLKA0
[78] CLKA0#
[78] CLKA1
[78] CLKA1#

FBA_CMD[31..0]

MF=0

VRAM1B 2 OF 2

FBA_CMD6 K4
FBA_CMD11 H5
FBA_CMD10 H4
FBA_CMD7 K5
FBA_CMD9 J5
FBA_CMD2 H11
FBA_CMD4 K10
FBA_CMD3 K11
FBA_CMD1 H10

FBA_CMD8 J4
FBA_CMD12 G3
FBA_CMD0 G12
FBA_CMD15 L3
FBA_CMD5 L12
CLKA0 J12
CLKA0# J11
FBA_CMD14 J3

DQMA0 D2
DQMA1 D13
DQMA2 P13
DQMA3 P2

FBA_CMD13 J2

FBA0 SEN1 J10
FBA0 ZQ1 J13
FBA0 MF1 J1

FBA_WCK01 D4
-FBA_WCK01 D5
FBA_WCK23 P4
-FBA_WCK23 P5

FBA0 SEN1 J10
FBA0 ZQ1 J13
FBA0 MF1 J1

FBA_WCK01 D4
-FBA_WCK01 D5
FBA_WCK23 P4
-FBA_WCK23 P5

H5GC2H24BFR-T2C-GP

Muxless

072.05224.000U

DQ0 A4 MDA0
DQ1 A2 MDA1
DQ2 B4 MDA2
DQ3 E4 MDA3
DQ4 E2 MDA5
DQ5 F4 MDA6
DQ6 F2 MDA7
DQ7 A11 MDA8
DQ8 A13 MDA9
DQ9 B11 MDA10
DQ10 B13 MDA11
DQ11 E11 MDA12
DQ12 E13 MDA13
DQ13 F11 MDA14
DQ14 F13 MDA15
DQ15 U11 MDA16
DQ16 U13 MDA17
DQ17 T11 MDA18
DQ18 T13 MDA19
DQ19 N11 MDA20
DQ20 N13 MDA21
DQ21 M11 MDA22
DQ22 M13 MDA23
DQ23 U4 MDA24
DQ24 U2 MDA25
DQ25 T4 MDA26
DQ26 T2 MDA27
DQ27 N4 MDA28
DQ28 N2 MDA29
DQ29 M4 MDA30
DQ30 M2 MDA31
DQ31

C2 QSAP_0
C13 QSAP_1
R13 QSAP_2
R2 QSAP_3

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MF=1

VRAM2B 2 OF 2

FBA_CMD26 K4
FBA_CMD23 H5
FBA_CMD22 H4
FBA_CMD27 K5
FBA_CMD25 J5
FBA_CMD19 H11
FBA_CMD17 K10
FBA_CMD18 K11
FBA_CMD20 H10

FBA_CMD24 J4
FBA_CMD31 G3
FBA_CMD21 G12
FBA_CMD28 L3
FBA_CMD16 L12
CLKA1 J12
CLKA1# J11
FBA_CMD30 J3

DQMA7 D2
DQMA6 D13
DQMA5 P13
DQMA4 P2

FBA_CMD29 J2

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

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FBA1 ZQ2 J13
FBA1 MF2 J1

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-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
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FBA1 MF2 J1

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-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
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FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
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FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

FBA_WCK67 D4
-FBA_WCK67 D5
FBA_WCK45 P4
-FBA_WCK45 P5

FBA1 SEN2 J10
FBA1 ZQ2 J13
FBA1 MF2 J1

A4 MDA56
A2 MDA57
B4 MDA58
B2 MDA59
E4 MDA60
E2 MDA61
F4 MDA62
F2 MDA63
A11 MDA48
A13 MDA49
B11 MDA50
B13 MDA51
E11 MDA52
E13 MDA53
F11 MDA54
F13 MDA55
U11 MDA40
U13 MDA41
T11 MDA42
T13 MDA43
N11 MDA44
N13 MDA45
M11 MDA46
M13 MDA47
U4 MDA32
U2 MDA33
T4 MDA34
T2 MDA35
N4 MDA36
N2 MDA37
M4 MDA38
M2 MDA39

C2 QSAP_7
C13 QSAP_6
R13 QSAP_5
R2 QSAP_4

EDC0
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EDC2
EDC3

EDC0
EDC1
EDC2
EDC3

EDC0
EDC1
EDC2
EDC3

EDC0
EDC1
EDC2
EDC3

EDC0
EDC1
EDC2
EDC3

EDC0
EDC1
EDC2
EDC3

EDC0
EDC1
EDC2
EDC3

EDC0
EDC1
EDC2
EDC3

GDDR5 Data Mapping							
BYTE0 (BYTE4)		BYTE1 (BYTE5)		BYTE2 (BYTE6)		BYTE3 (BYTE7)	
MF=0	MF=1	MF=0	MF=1	MF=0	MF=1	MF=0	MF=1
DQ0	DQ24 (DQ32)	DQ8	DQ16 (DQ40)	DQ16	DQ8 (DQ48)	DQ24	DQ0 (DQ96)
DQ1	DQ25 (DQ33)	DQ9	DQ17 (DQ41)	DQ17	DQ9 (DQ49)	DQ25	DQ1 (DQ97)
DQ2	DQ26 (DQ34)	DQ10	DQ18 (DQ42)	DQ18	DQ10 (DQ50)	DQ26	DQ2 (DQ98)
DQ3	DQ27 (DQ35)	DQ11	DQ19 (DQ43)	DQ19	DQ11 (DQ51)	DQ27	DQ3 (DQ99)
DQ4	DQ28 (DQ36)	DQ12	DQ20 (DQ44)	DQ20	DQ12 (DQ52)	DQ28	DQ4 (DQ100)
DQ5	DQ29 (DQ37)	DQ13	DQ21 (DQ45)	DQ21	DQ13 (DQ53)	DQ29	DQ5 (DQ101)
DQ6	DQ30 (DQ38)	DQ14	DQ22 (DQ46)	DQ22	DQ14 (DQ54)	DQ30	DQ6 (DQ102)
DQ7	DQ31 (DQ39)	DQ15	DQ23 (DQ47)	DQ23	DQ15 (DQ55)	DQ31	DQ7 (DQ103)
DBI0	DBI3 (DBI4)	DBI1	DBI2 (DBI5)	DBI2	DBI1 (DBI6)	DBI3	DBI0 (DBI7)
EDC0	EDC3 (EDC4)	EDC1	EDC2 (EDC5)	EDC2	EDC1 (EDC6)	EDC3	EDC0 (EDC7)
GDDR5 CLK Mapping							
WCK01	WCK23 (WCK45)	WCK23	WCK01 (WCK67)	WCK23	WCK01 (WCK67)	WCK23	WCK01 (WCK67)
WCK01#	WCK23# (WCK45#)	WCK23#	WCK01# (WCK67#)	WCK23#	WCK01# (WCK67#)	WCK23#	WCK01# (WCK67#)
CK	CK	CK	CK	CK	CK	CK	CK
CK#	CK#	CK#	CK#	CK#	CK#	CK#	CK#
Others							
MF	MF	SEN	SEN	SEN	SEN	SEN	SEN
ZQ	ZQ	RESET#	RESET#	RESET#	RESET#	RESET#	RESET#

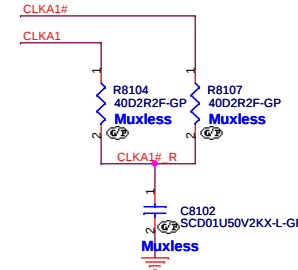
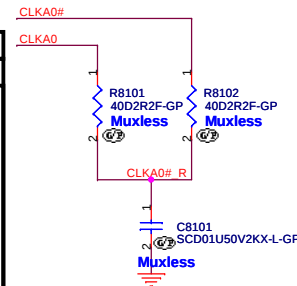
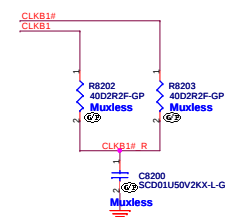
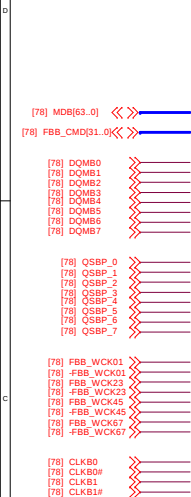


Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	AB1*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RAS*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CA5*

DIS

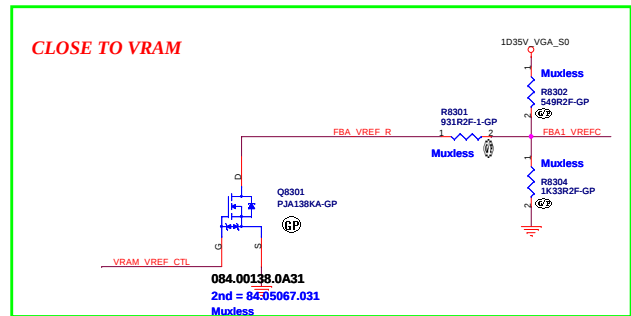


GDDR5 Data Mapping							
BYTE0 (BYTE4)		BYTE1 (BYTE5)		BYTE2 (BYTE6)		BYTE3 (BYTE7)	
MF=0	MF=1	MF=0	MF=1	MF=0	MF=1	MF=0	MF=1
DQ0	DQ24 (DQ40)	DQ8	DQ16 (DQ48)	DQ16	DQ8 (DQ40)	DQ24	DQ0 (DQ48)
DQ1	DQ25 (DQ49)	DQ9	DQ17 (DQ49)	DQ17	DQ9 (DQ48)	DQ25	DQ1 (DQ47)
DQ2	DQ26 (DQ50)	DQ10	DQ18 (DQ50)	DQ18	DQ10 (DQ49)	DQ26	DQ2 (DQ48)
DQ3	DQ27 (DQ51)	DQ11	DQ19 (DQ51)	DQ19	DQ11 (DQ50)	DQ27	DQ3 (DQ49)
DQ4	DQ28 (DQ52)	DQ12	DQ20 (DQ52)	DQ20	DQ12 (DQ51)	DQ28	DQ4 (DQ50)
DQ5	DQ29 (DQ53)	DQ13	DQ21 (DQ53)	DQ21	DQ13 (DQ52)	DQ29	DQ5 (DQ51)
DQ6	DQ30 (DQ54)	DQ14	DQ22 (DQ54)	DQ22	DQ14 (DQ53)	DQ30	DQ6 (DQ52)
DQ7	DQ31 (DQ55)	DQ15	DQ23 (DQ55)	DQ23	DQ15 (DQ54)	DQ31	DQ7 (DQ53)
DBI0	DBI3 (DB4)	DBI1	DBI2 (DB4)	DBI2	DBI1 (DB4)	DBI3	DBI0 (DB7)
EDC0	EDC3 (EDC4)	EDC1	EDC2 (EDC3)	EDC2	EDC1 (EDC3)	EDC3	EDC0 (EDC7)
GDDR5 CLK Mapping							
WCK01		WCK23 (WCK43)		WCK23		WCK01 (WCK47)	
WCK01#		WCK23# (WCK43#)		WCK23#		WCK01# (WCK47#)	
CK	CK						
CK#	CK#						
Others							
MF	MF	SEN	SEN				
ZQ	ZQ	RESET#	RESET#				

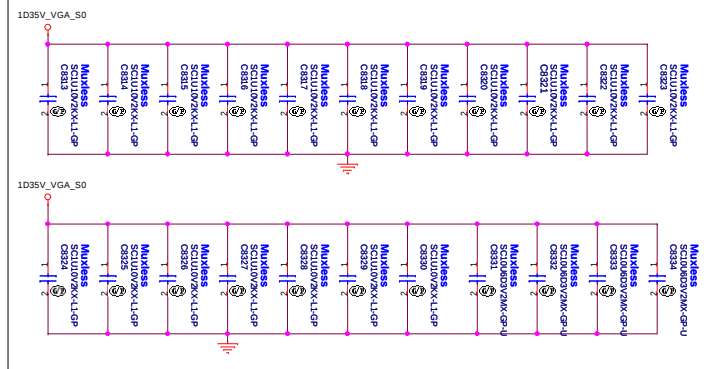
Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	ABI*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RAS*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CAS*

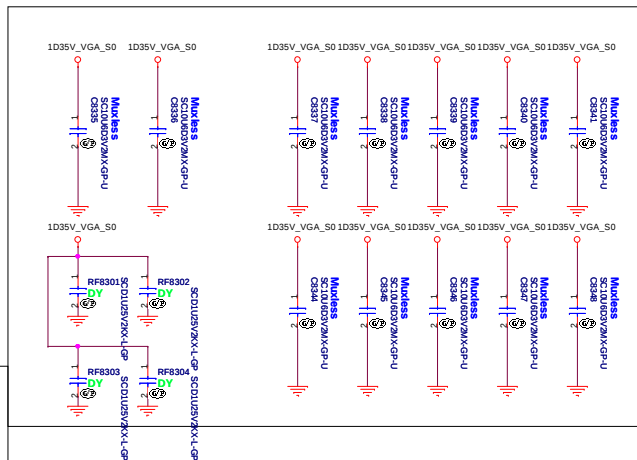
FOR VRAM1/ VRAM2



FOR VRAM1/VRAM2



UNDER THE MEMORY



CLOSE TO THE MEMORY

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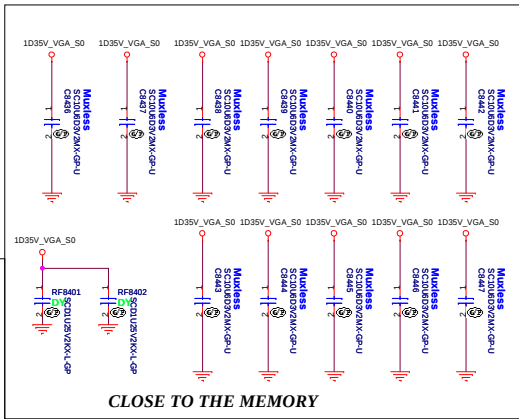
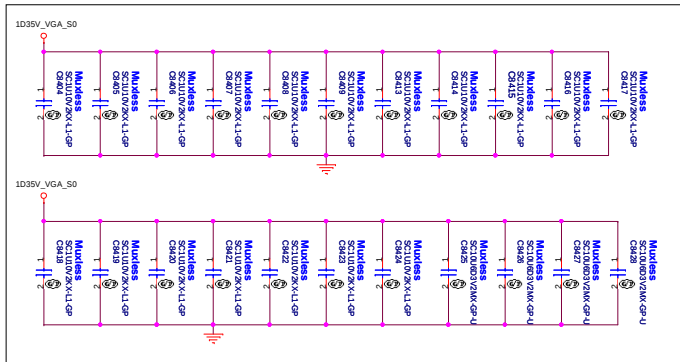
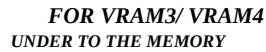
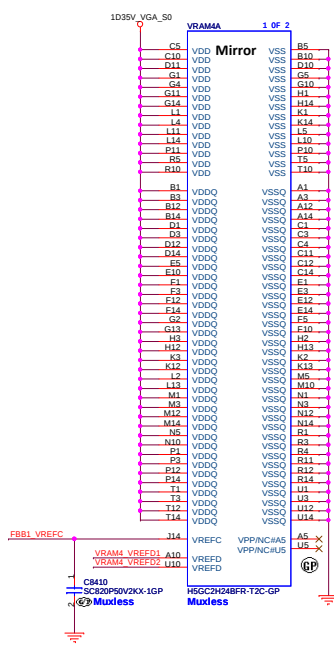
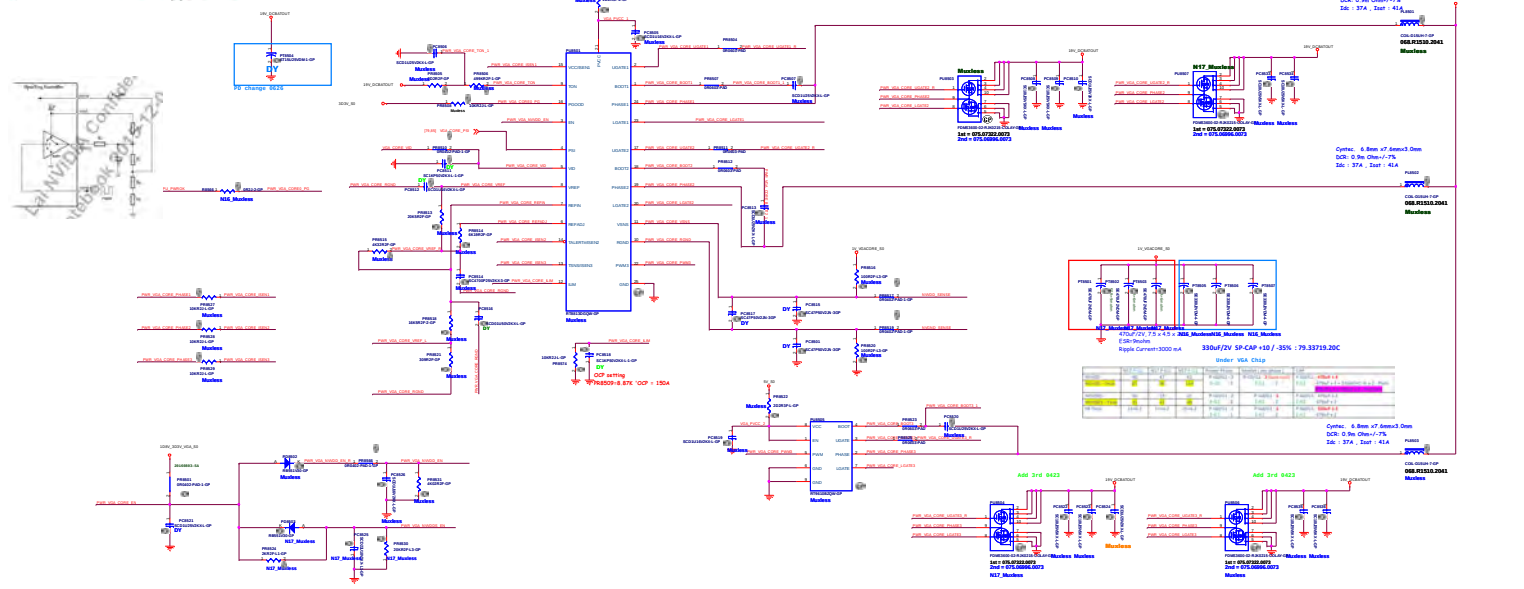
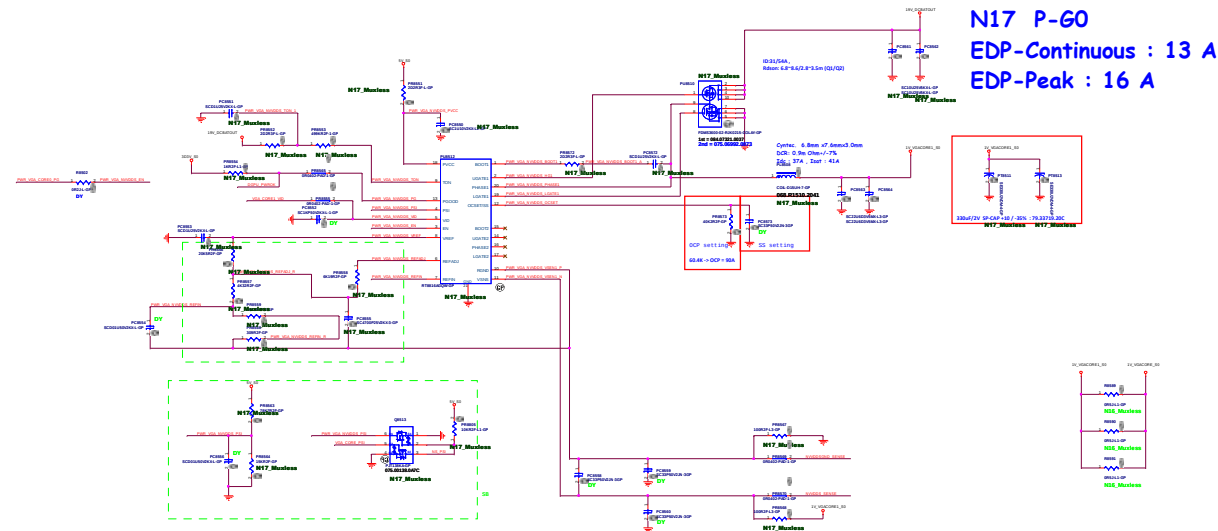


Table 7.8 PWM-VID Spec and Component Values

PWM-VID Specification			
	Unit	Config	
Number of Voltage Levels (N)	Level	160	
PWM Frequency (F _{sw})	kHz	8.75	
PWM Minimum Pulse Width (T _{min})	ns	9.26	
VID Transient Time (T)	ns	>150	
Component Value			
R1 (1k)	ΩD	8.19	
R2 (1k)	ΩD	20.3	
R3 (1k)	ΩD	4.32	
R4 (1k)	ΩD	16.5	
R5 (1k)	ΩD	9.26	
C	μF	1.5	



RT8816A For NVVDDS



RT8816A for PWR_VGA_GDDR

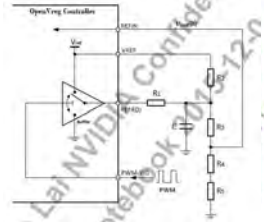
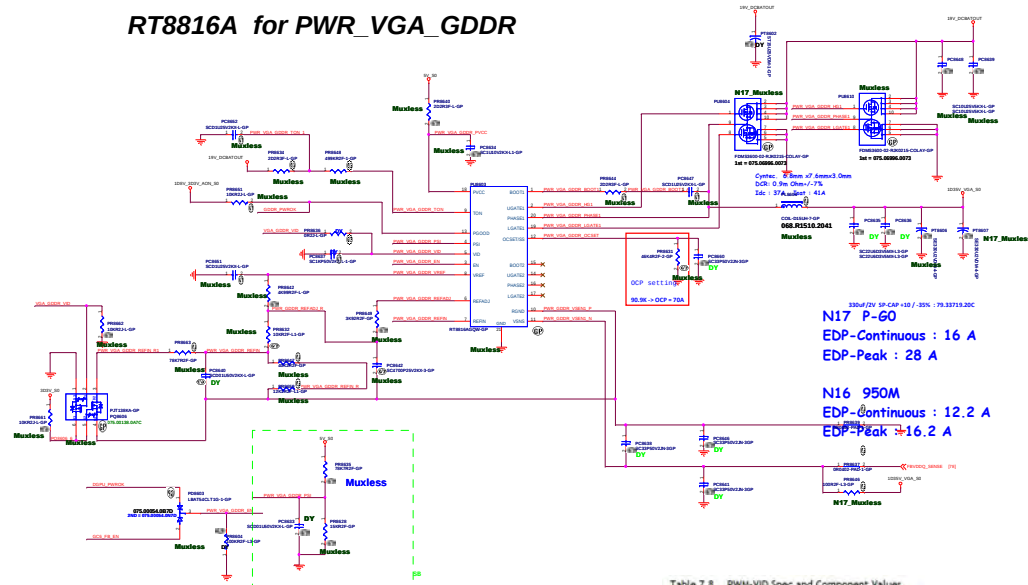
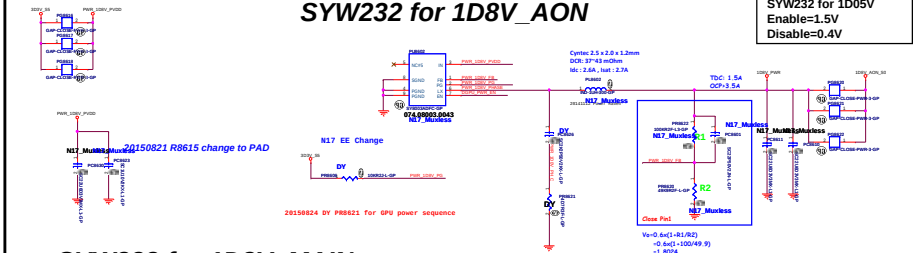


Table 7.8 PWM-VID Spec and Component Values

PWM-VID Specification		
	Unit	Config
Number of Voltage Levels II	Level	160
PWM Frequency F _{sw}	MHz	6.75
PWM Minimum Pulse Width T _{pw}	ns	9.26
VID Transient Time T _{tr}	ns	~100
Component Value		
R1 (1%)	R2	6.19
R2 (1%)	R3	20.5
R3 (1%)	R4	4.32
R4 (1%)	R5	14.5
R5 (1%)	R6	0.497
C	μF	

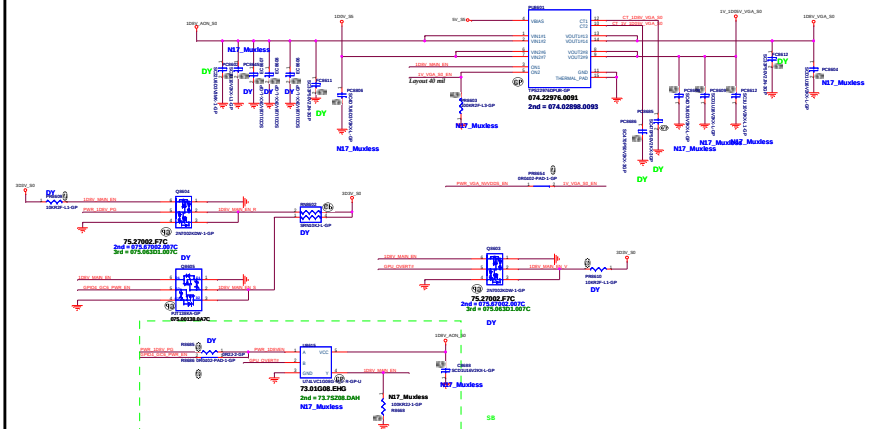
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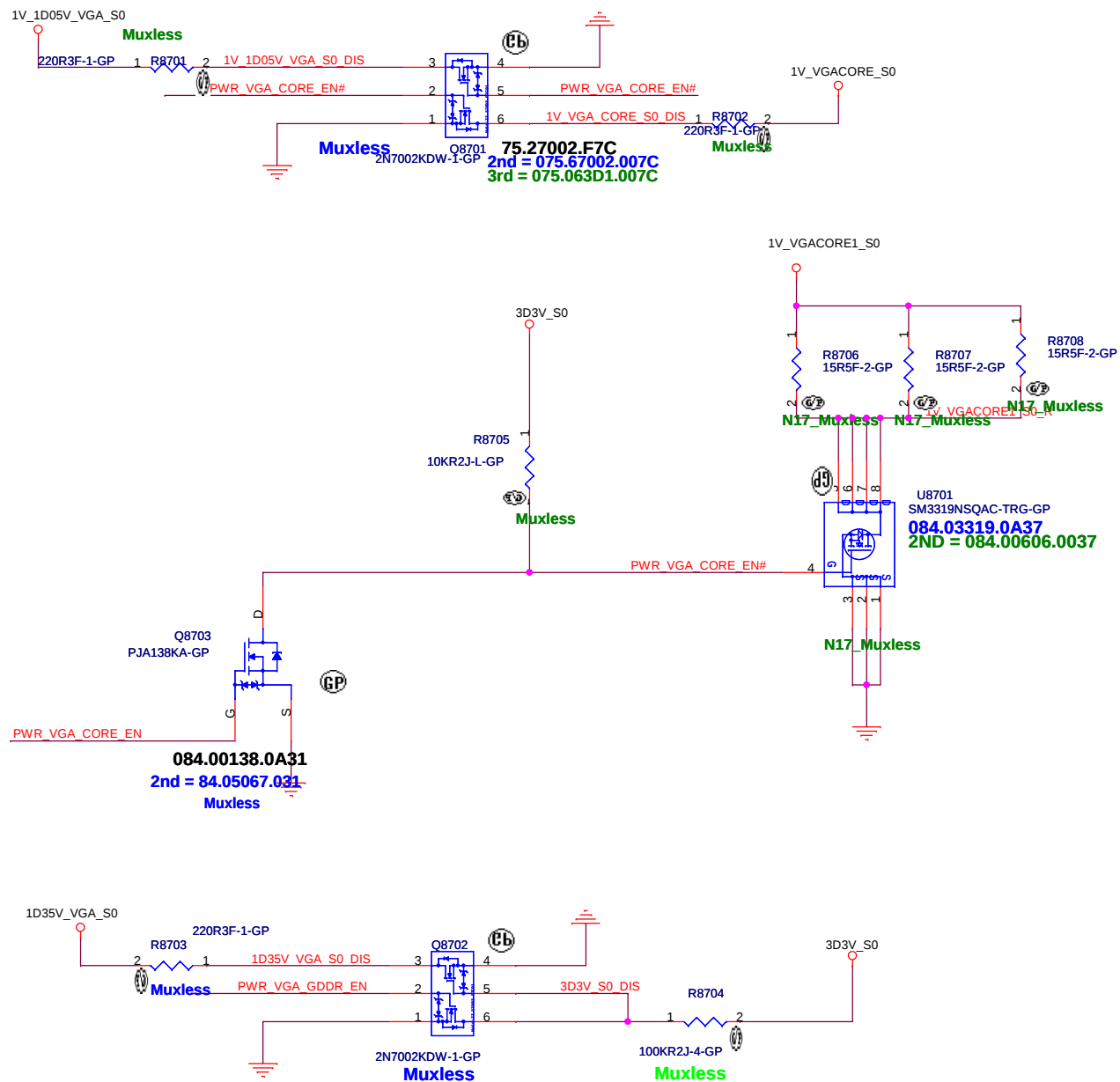


SYW232 for 1D8V_MAIN

N17 change to ANPEC APL3526/B

APL3526QB for 1V_VGA_S0





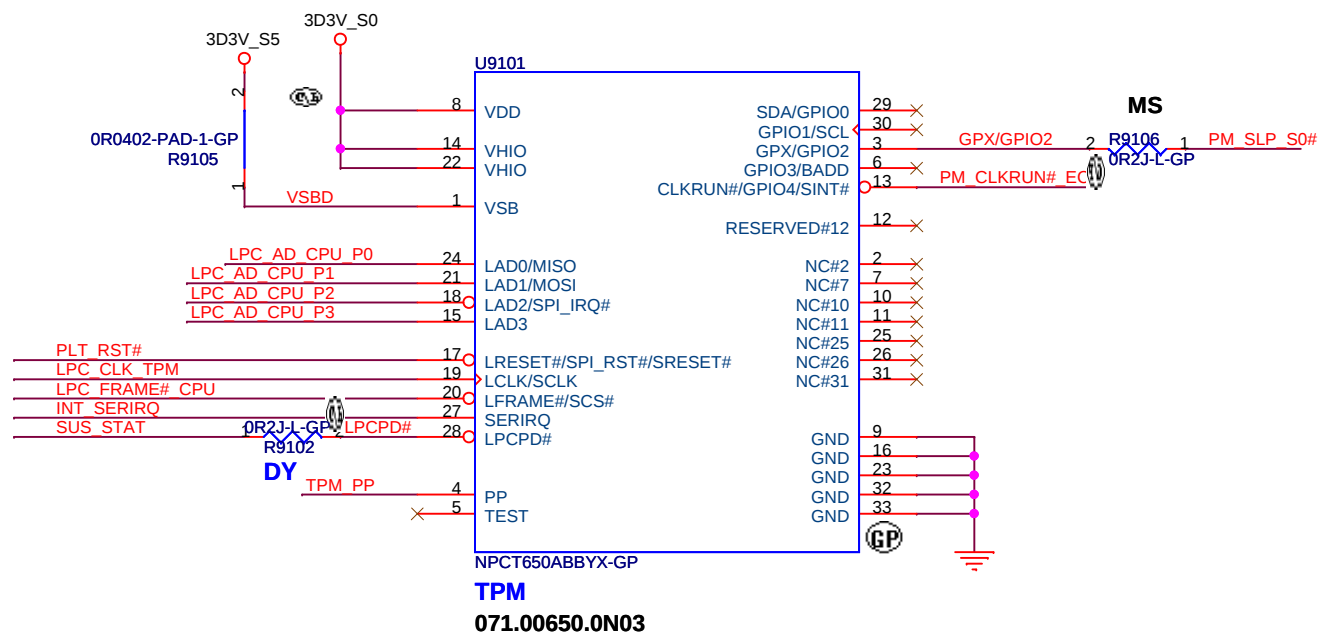
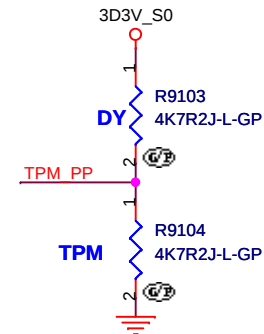
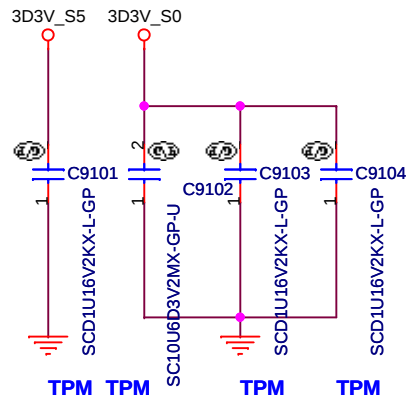
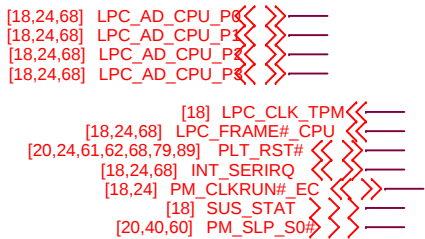
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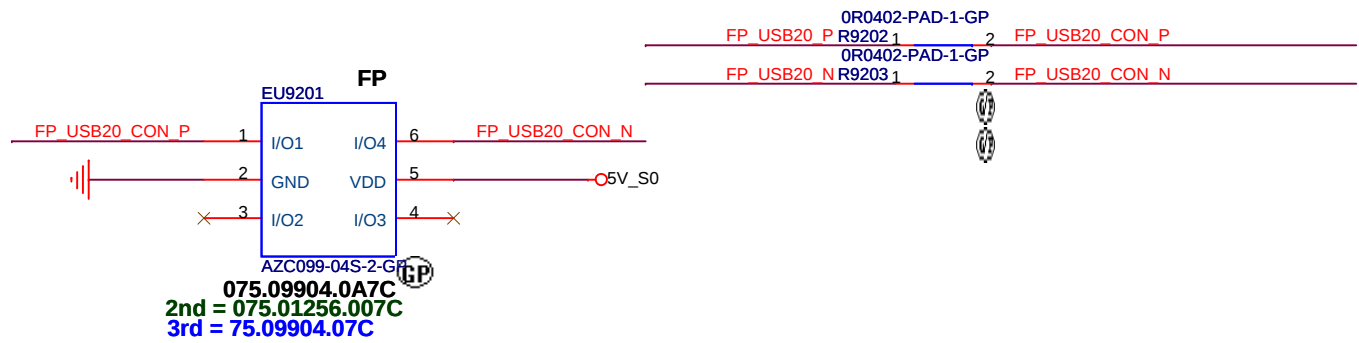
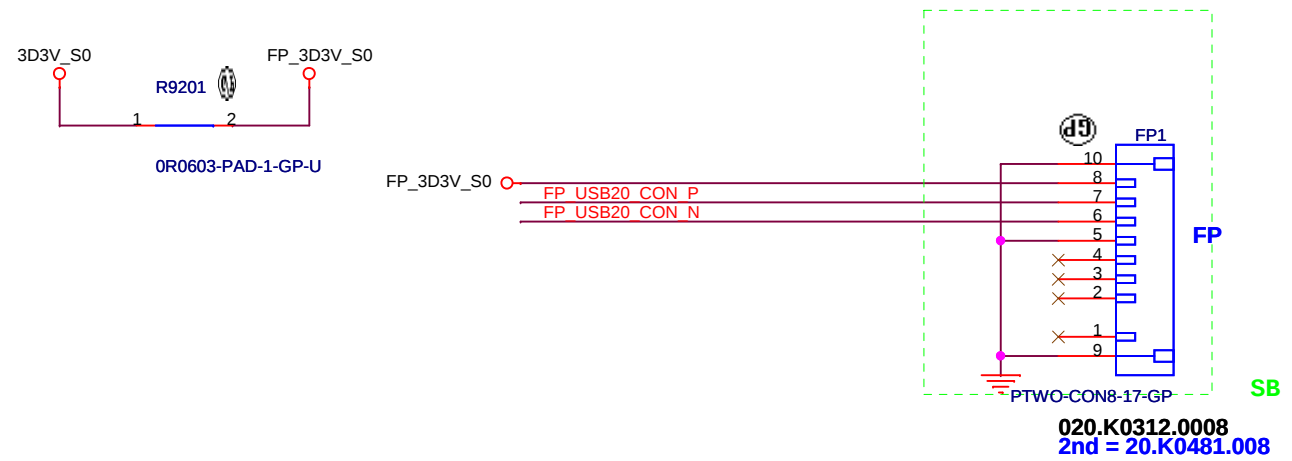
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[15] FP_USB20_P << >> _____

[89] FP_USB20_CON << >> _____
[89] FP_USB20_CON << >> _____



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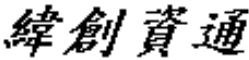
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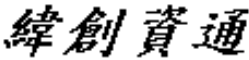
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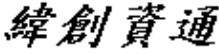
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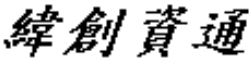
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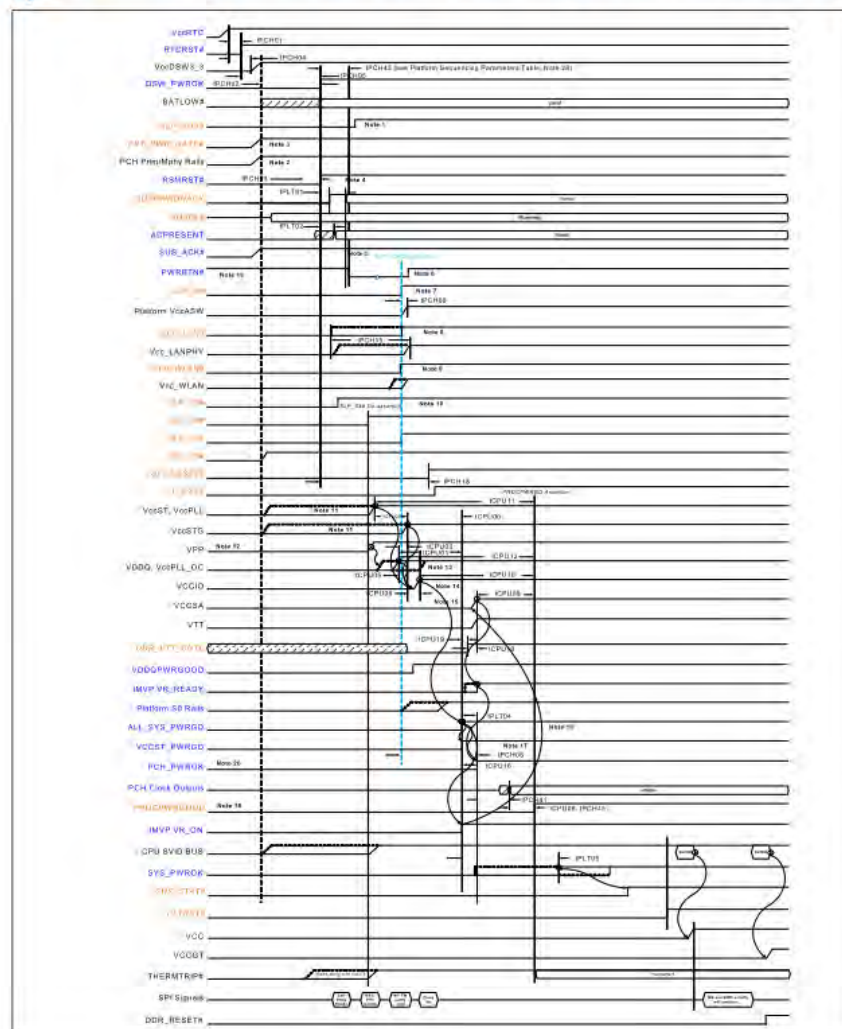
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Figure 41-5. KBL R U Timing Diagram for G3 to S0/M0 [Non-Deep Sx Platform] (Sheet 1 of 2)



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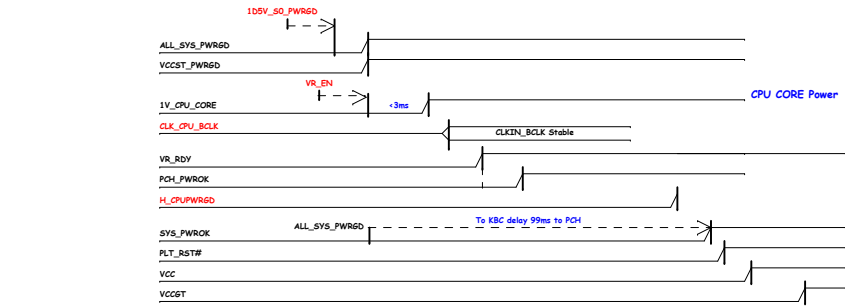
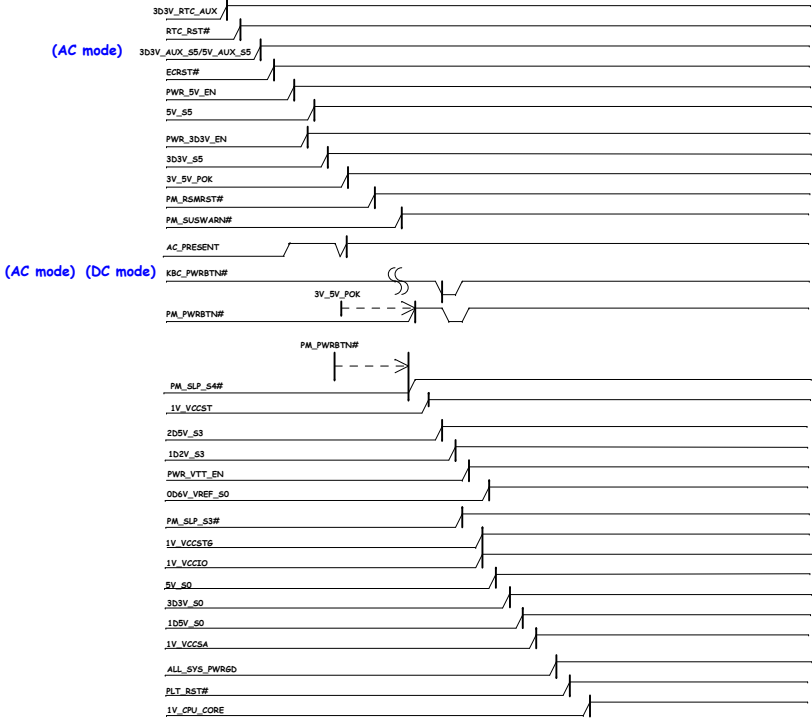
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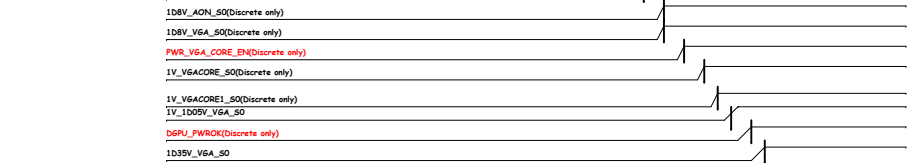
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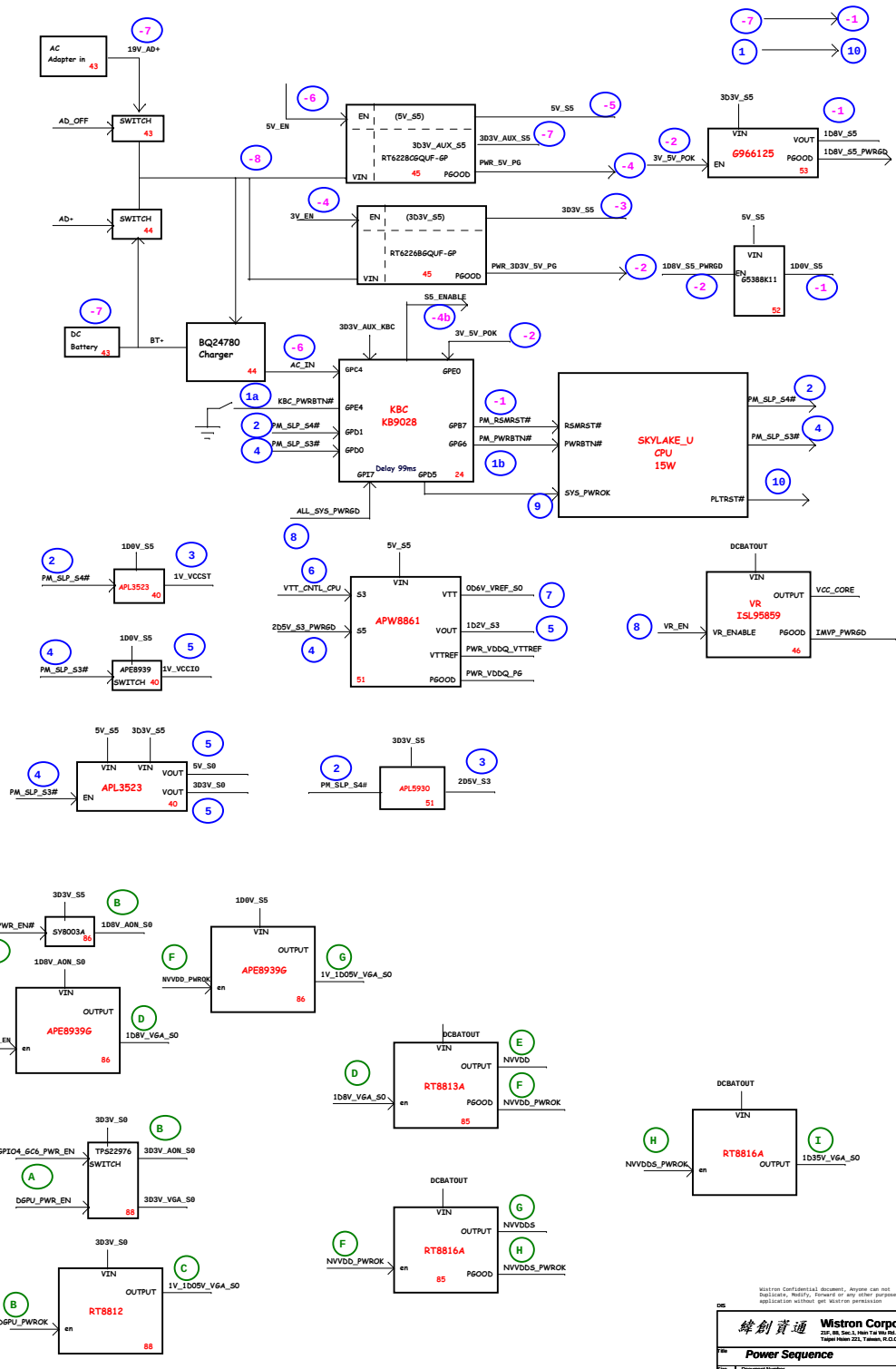
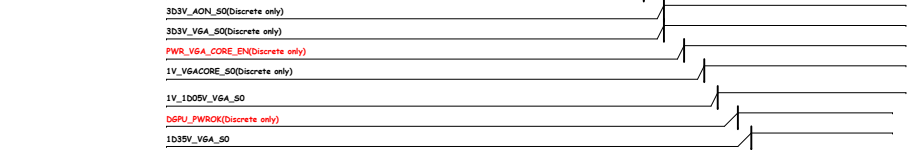
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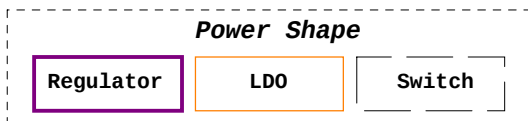
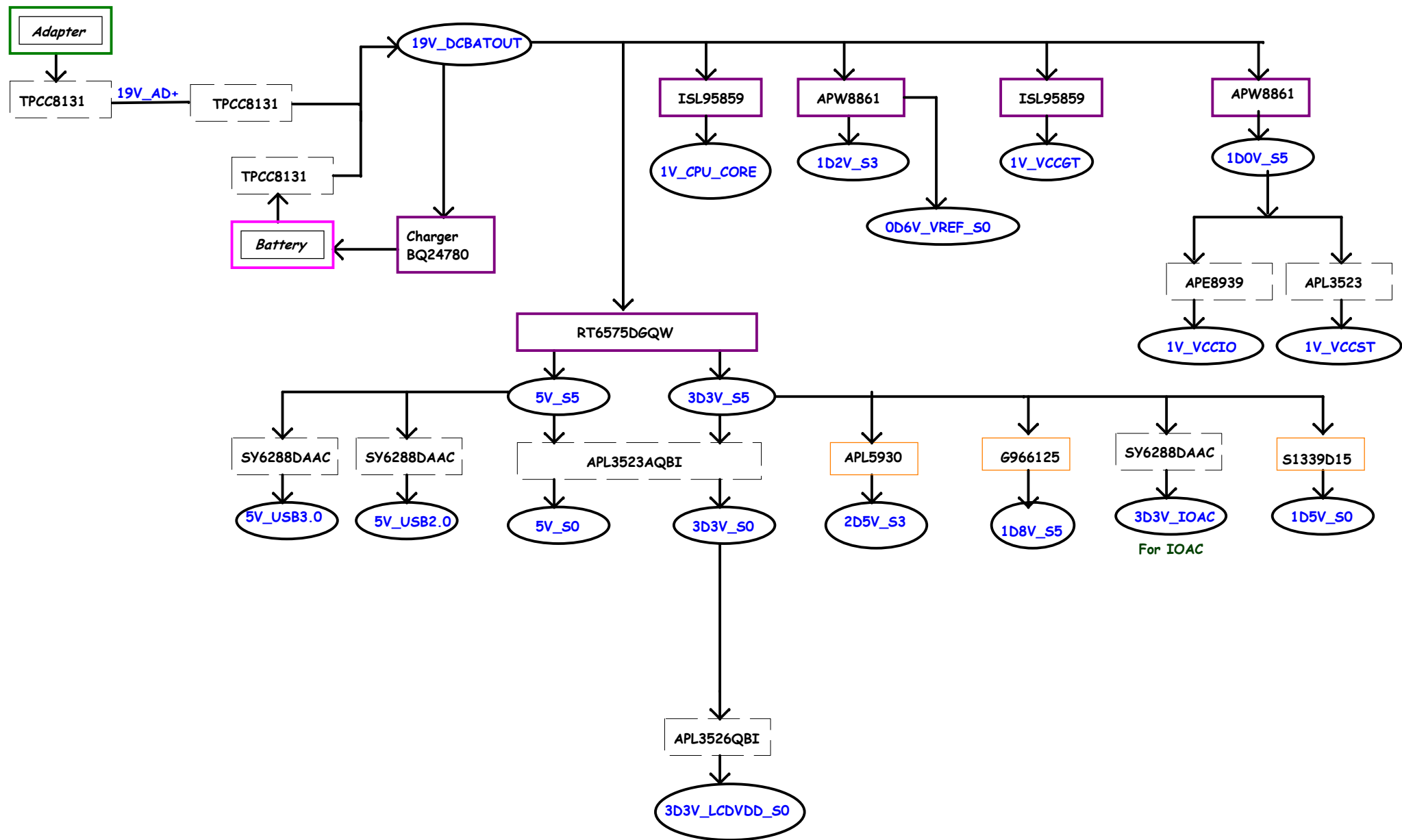


N17-Power Up Sequence



N16-Power Up Sequence



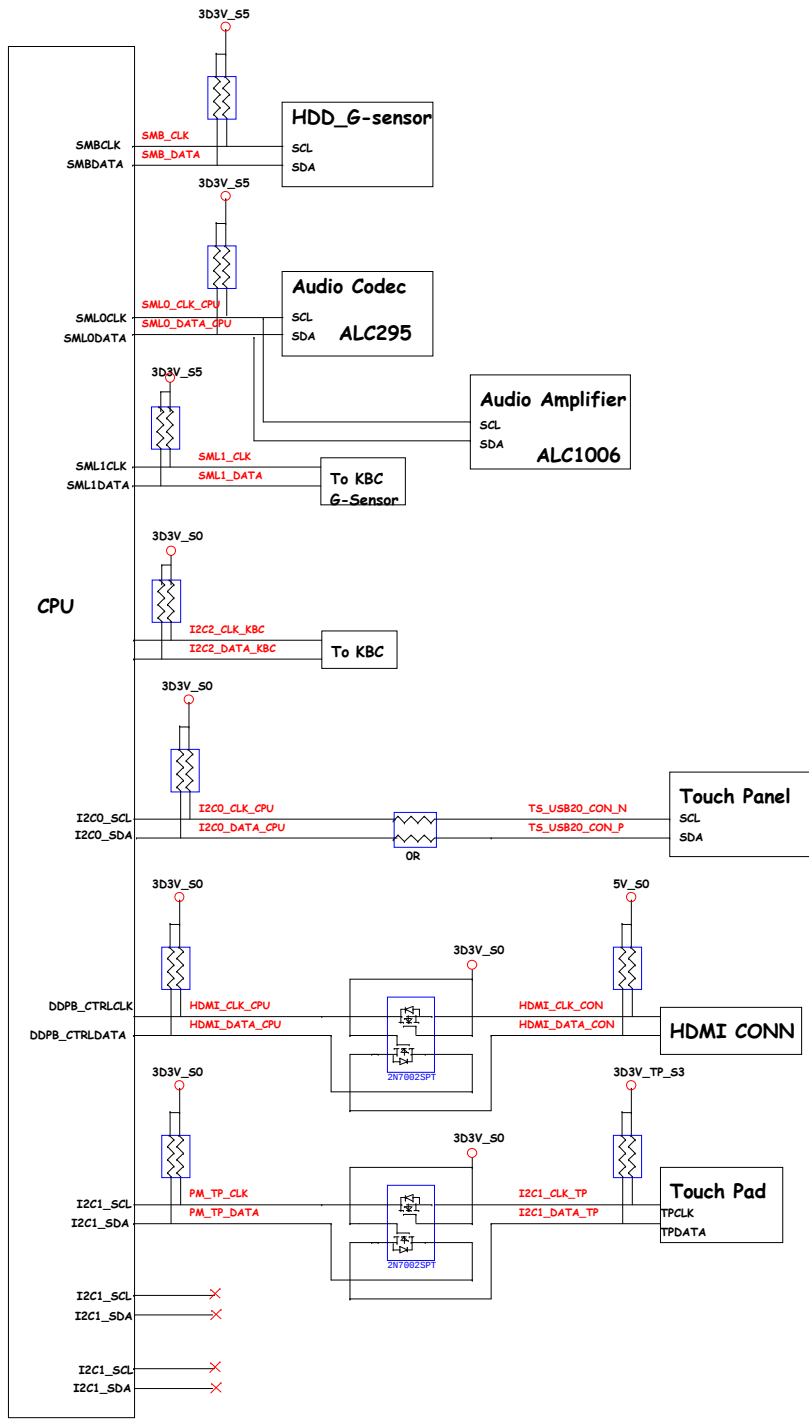


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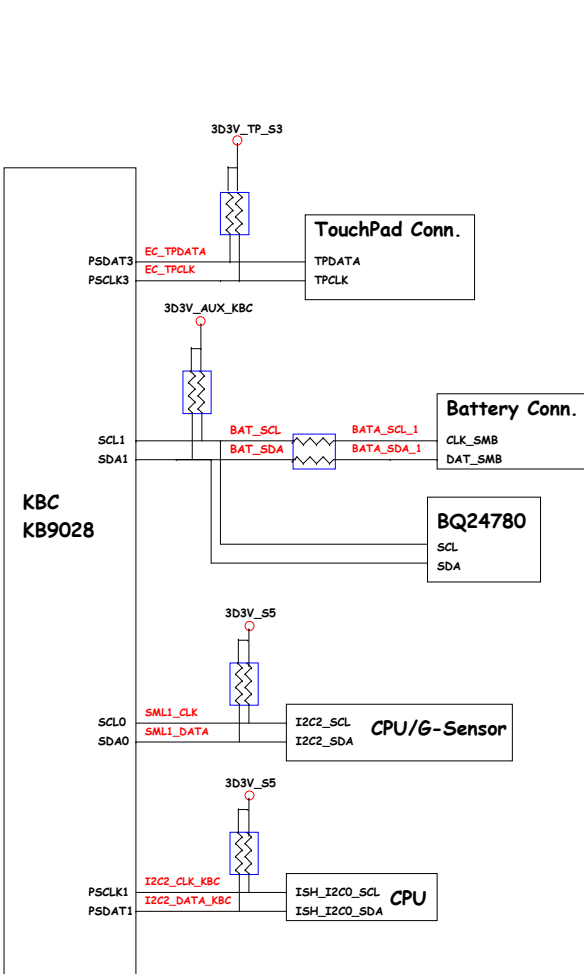
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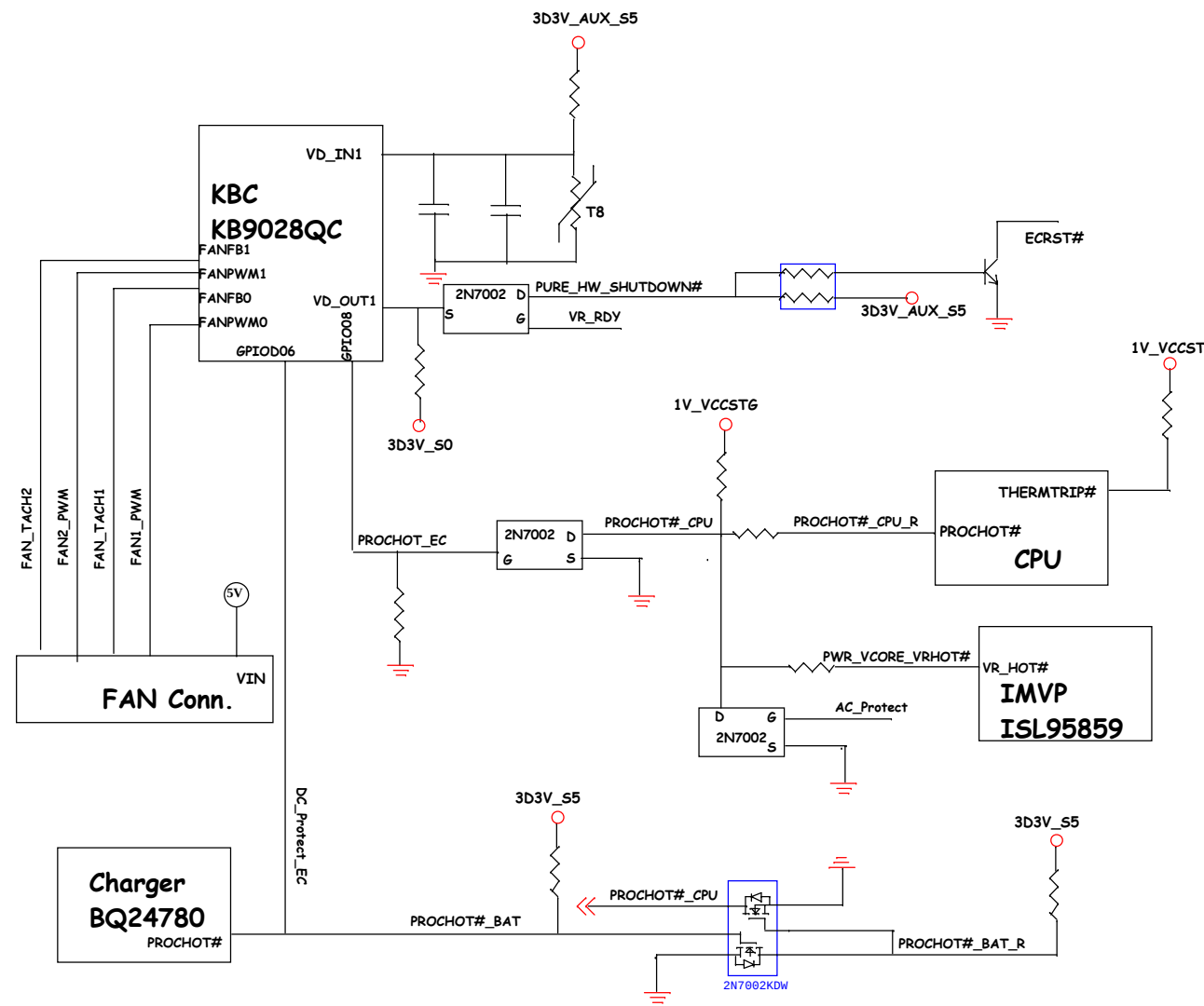
PCH SMBus/I2C Block Diagram



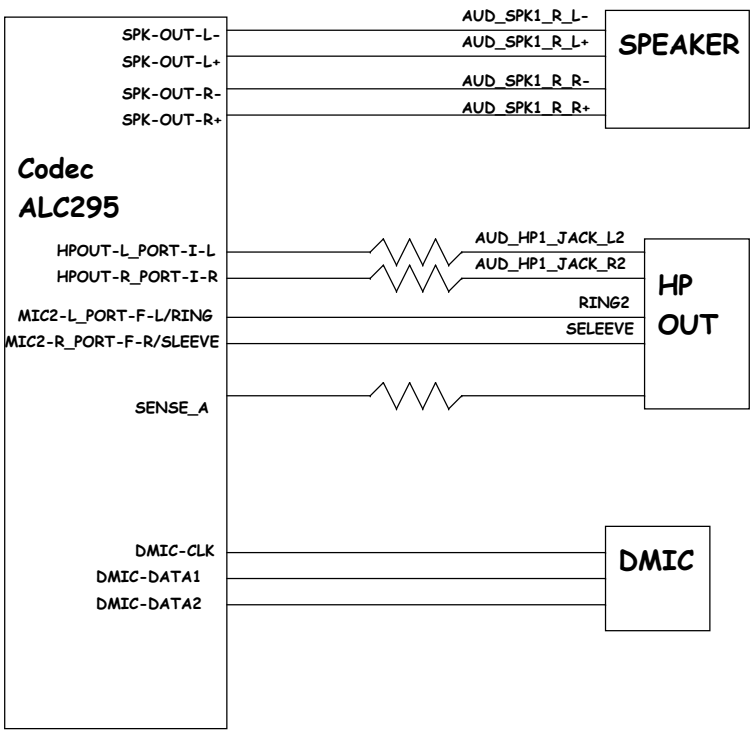
KBC SMBus/I2C Block Diagram



Thermal Block Diagram



Audio Block Diagram



CLOCK BLOCK DIAGRAM

